TMS320F28027, TMS320F28027-Q1, TMS320F28027F, TMS320F28027F-Q1, TMS320F28026
TMS320F28026-Q1, TMS320F28026F, TMS320F28026F-Q1, TMS320F28023
TMS320F28023-Q1, TMS320F28022, TMS320F28021, TMS320F28020, TMS320F280200
ZHCSA13P – NOVEMBER 2008 – REVISED FEBRUARY 2021

TMS320F2802x 微控制器

1 特性

- 高效 32 位 CPU (TMS320C28x)
  - 60MHz (16.67ns 周期时间)
  - 50MHz (20ns 周期时间)
  - 40MHz (25ns 周期时间)
  - 16 × 16 和 32 × 32 MAC 操作
  - 16 × 16 双 MAC
  - 哈佛 (Harvard) 总线架构
  - 连动运算
  - 快速中断响应和处理
  - 统一存储器编程模型
  - 高效代码 (使用 C/C++ 和汇编语言)
- 字节序：小端字节序
- 器件和系统均可实现低成本：
  - 3.3V 单电源
  - 无需电源时序
  - 集成型加电和欠压复位
  - 可采用低至 38 引脚小型封装
  - 低功耗
  - 无模拟支持引脚
- 时钟：
  - 两个内部零引脚振荡器
  - 片上晶振振荡器和外部时钟输入
  - 看门狗计时器模块
  - 丢失时钟检测电路
- 多达 22 个具有输入滤波功能且可单独编程的多路复用 GPIO 引脚
- 可支持所有外设中断的外设中断扩展 (PIE) 模块
- 三个 32 位 CPU 计时器
- 每个增强型脉宽调制器 (ePWM) 中均有一个独立的 16 位计时器
- 片上存储器
  - 闪存，SARAM，OTP，引导 ROM 可用
- 代码安全模块
- 128 位安全密钥和锁
  - 保护安全内存块
  - 防止固件逆向工程
- 串行端口外设
  - 一个串行通信接口 (SCI) 通用异步接收器/发送器 (UART) 模块
  - 一个串行外设接口 (SPI) 模块
  - 一个内部集成电路 (I2C) 模块
- 增强型控制外设
  - ePWM
  - 高分辨率 PWM (HRPWM)
  - 增强型捕捉 (eCAP) 模块
  - 模数转换器 (ADC)
  - 片上温度传感器
  - 比较器
- 高级仿真特性
  - 分析和断点功能
  - 通过硬件进行实时调试
- 封装选项
  - 38 引脚 DA Thin Shrink Small-Outline Package (TSSOP)
  - 48 引脚 PT Low-Profile Quad Flatpack (LQFP)
- 温度选项
  - T：–40°C 至 105°C
  - S：–40°C 至 125°C
  - Q：–40°C 至 125°C 的环境温度范围 (通过针对汽车应用的 AEC Q100 认证)

2 应用

- 空调室外机
- 逆变器和电机控制
- 纺织机
- 微型逆变器
- 交流驱动器功率级模块
- 交流输入 BLDC 电机驱动器
- 直流输入 BLDC 电机驱动器
- 工业交流/直流电源
- 三相 UPS
- 商用直流/直流电源
- 商用网络和服务器 PSU
- 商用通信电源整流器

3 说明

C2000™ 32 位微控制器针对处理、感应和驱动进行了优化，可提高实时控制应用（如工业电机驱动器、光伏逆变器和数字电源、电动汽车和运输、电机控制以及感应和信号处理）的闭环性能。C2000 系列包括高级性能 MCU 和入门级性能 MCU。

F2802x 微控制器系列提供 C28xx 内核的强大功能，同时结合低引脚数器件中高度集成的控制外设。该系列器件的代码与基于 C28x 的旧版代码兼容，同时具有较高的模拟集成度。

内部稳压器实现了单电源轨运行。HRPWM 模块经过强化，可实现双边沿控制（调频）。增设了具有 10 位内部基准的模拟比较器，可直接进行路由以控制 PWM 输出。ADC 可在 0V 至 3.3V 的固定满量程范围内实施转换，支持 V_{REFHI}/V_{REFLO} 基准的比例运算。ADC 接口已针对低开销和延迟进行了优化。

如需详细了解 C2000 MCU，请访问“C2000 概述”，地址为 www.ti.com/c2000。

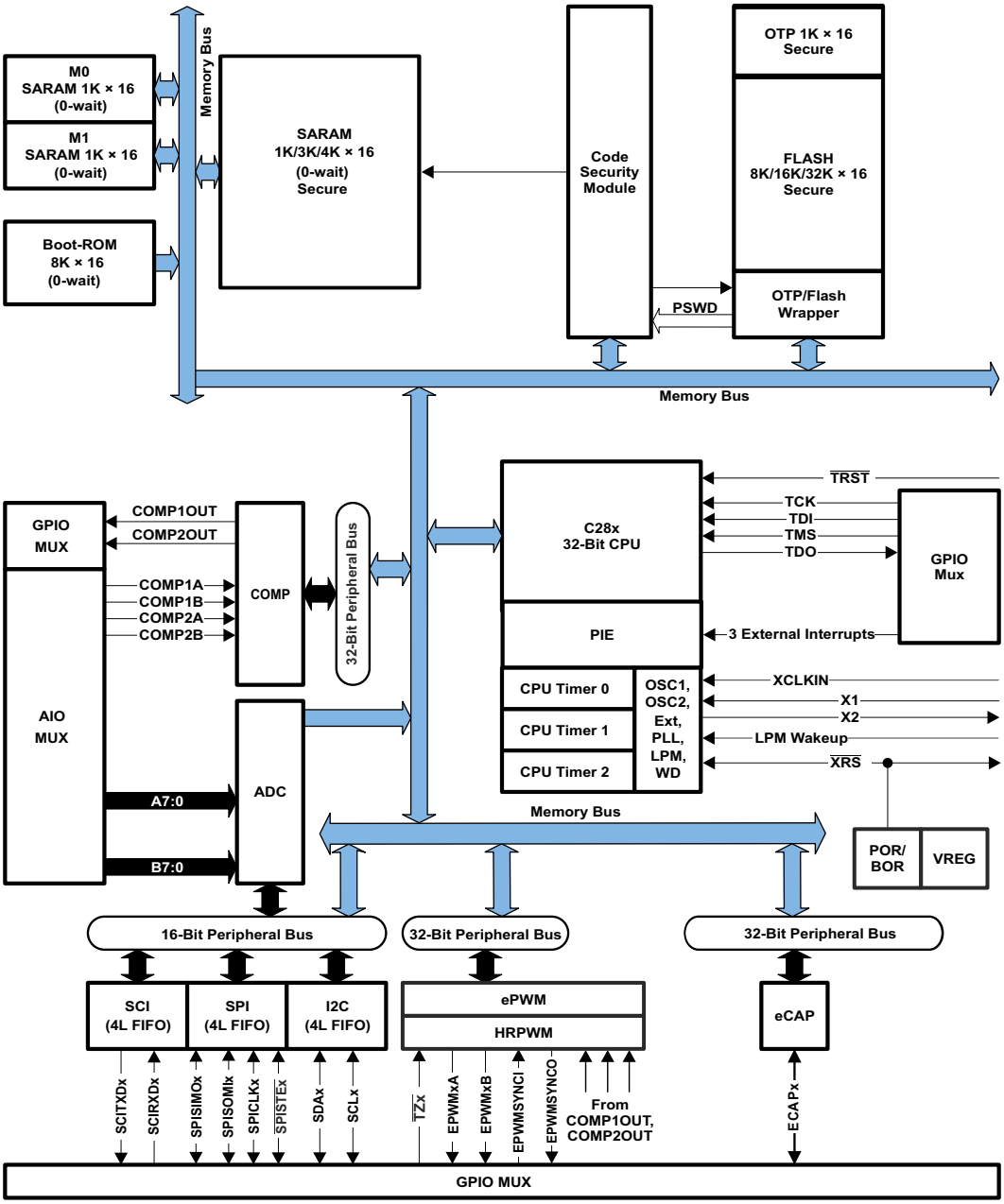
器件信息

器件型号(1)	封装	封装尺寸
TMS320F28027PT	LQFP (48)	7.0mm × 7.0mm
TMS320F28026PT	LQFP (48)	7.0mm × 7.0mm
TMS320F28023PT	LQFP (48)	7.0mm × 7.0mm
TMS320F28022PT	LQFP (48)	7.0mm × 7.0mm
TMS320F28021PT	LQFP (48)	7.0mm × 7.0mm
TMS320F28020PT	LQFP (48)	7.0mm × 7.0mm
TMS320F280200PT	LQFP (48)	7.0mm × 7.0mm
TMS320F28027DA	TSSOP (38)	12.5mm x 6.2mm
TMS320F28026DA	TSSOP (38)	12.5mm x 6.2mm
TMS320F28023DA	TSSOP (38)	12.5mm x 6.2mm
TMS320F28022DA	TSSOP (38)	12.5mm x 6.2mm
TMS320F28021DA	TSSOP (38)	12.5mm x 6.2mm
TMS320F28020DA	TSSOP (38)	12.5mm x 6.2mm
TMS320F280200DA	TSSOP (38)	12.5mm x 6.2mm

(1) 有关这些器件的详细信息，请参阅机械、封装和可订购信息。

4 功能方框图

功能方框图展示了器件的功能方框图。



A. 由于多路复用，所有外设引脚不能同时使用。

图 4-1. 功能方框图

内容

5 修订历史记录

Changes from OCTOBER 30, 2020 to JANUARY 18, 2021 (from Revision O (October 2020) to Revision P (January 2021)) **Page**

- *Device Comparison*: Updated part numebrs....6
- *ESD 等级 - 汽车*：更新了器件型号....15
- *ESD 等级 - 商用*：更新了器件型号....16
- *Device and Development Support Tool Nomenclature*: Updated Device Nomenclature image to show -Q1 part number....120

6 Device Comparison

表 6-1 lists the features of the TMS320F2802x devices.

表 6-1. Device Comparison

FEATURE		TYPE (1)	28027 28027-Q1 28027F 28027F-Q1 (60 MHz)(2)		28026 28026-Q1 28026F 28026F-Q1 (60 MHz)(2)		28023 28023-Q1 (50 MHz)		28022 28022-Q1 (50 MHz)		28021 (40 MHz)		28020 (40 MHz)		280200 (40 MHz)	
Package Type			38-Pin DA TSSOP	48-Pin PT LQFP	38-Pin DA TSSOP	48-Pin PT LQFP	38-Pin DA TSSOP	48-Pin PT LQFP	38-Pin DA TSSOP	48-Pin PT LQFP	38-Pin DA TSSOP	48-Pin PT LQFP	38-Pin DA TSSOP	48-Pin PT LQFP	38-Pin DA TSSOP	48-Pin PT LQFP
Instruction cycle		–	16.67 ns		16.67 ns		20 ns		20 ns		25 ns		25 ns		25 ns	
On-chip flash (16-bit word)		–	32K		16K		32K		16K		32K		16K		8K	
On-chip SARAM (16-bit word)		–	6K		6K		6K		6K		5K		3K		3K	
Code security for on-chip flash/SARAM/OTP blocks		–	Yes		Yes		Yes		Yes		Yes		Yes		Yes	
Boot ROM (8K x 16)		–	Yes		Yes		Yes		Yes		Yes		Yes		Yes	
One-time programmable (OTP) ROM (16-bit word)		–	1K		1K		1K		1K		1K		1K		1K	
ePWM channels		1	8 (ePWM1/2/3/4)		8 (ePWM1/2/3/4)		8 (ePWM1/2/3/4)		8 (ePWM1/2/3/4)		8 (ePWM1/2/3/4)		8 (ePWM1/2/3/4)		8 (ePWM1/2/3/4)	
eCAP inputs		0	1		1		1		1		1		1		–	
Watchdog timer		–	Yes		Yes		Yes		Yes		Yes		Yes		Yes	
12-Bit ADC	MSPS	3	4.6		4.6		3		3		2		2		2	
	Conversion Time		216.67 ns		216.67 ns		260 ns		260 ns		500 ns		500 ns		500 ns	
	Channels		7	13	7	13	7	13	7	13	7	13	7	13	7	13
	Temperature Sensor		Yes		Yes		Yes		Yes		Yes		Yes		Yes	
	Dual Sample-and-Hold		Yes		Yes		Yes		Yes		Yes		Yes		Yes	
32-Bit CPU timers		–	3		3		3		3		3		3		3	
High-resolution ePWM Channels		1	4 (ePWM1A/2A /3A/4A)		4 (ePWM1A/2A /3A/4A)		4 (ePWM1A/2A /3A/4A)		4 (ePWM1A/2A /3A/4A)		–		–		–	
Comparators w/ Integrated DACs		0	1	2	1	2	1	2	1	2	1	2	1	2	1	2
Inter-integrated circuit (I2C)		0	1		1		1		1		1		1		1	
Serial Peripheral Interface (SPI)		1	1		1		1		1		1		1		1	
Serial Communications Interface (SCI) (UART Compatible)		0	1		1		1		1		1		1		1	
I/O pins (shared)	Digital (GPIO)	–	20	22	20	22	20	22	20	22	20	22	20	22	20	22
	Analog (AIO)	–	6		6		6		6		6		6		6	
External interrupts		–	3		3		3		3		3		3		3	
Supply voltage (nominal)		–	3.3 V		3.3 V		3.3 V		3.3 V		3.3 V		3.3 V		3.3 V	
Temperature options	T: –40°C to 105°C	–	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	S: –40°C to 125°C	–	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	Q: –40°C to 125°C(3)	–	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	–	–	–	–	–	–

(1) A type change represents a major functional feature difference in a peripheral module. Within a peripheral type, there may be minor differences between devices that do not affect the basic functionality of the module. These device-specific differences are listed in the *C2000 Real-Time Control Peripherals Reference Guide* and in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

(2) TMS320F28027F and TMS320F28026F are InstaSPIN-FOC™-enabled MCUs. For more information, see 节 11.3 for a list of InstaSPIN Technical Reference Manuals.

(3) The letter Q refers to AEC Q100 qualification for automotive applications.

6.1 Related Products

For information about similar products, see the following links:

TMS320F2802x Microcontrollers
The F2802x series offers the lowest pin-count and Flash memory size options. InstaSPIN-FOC™ versions are available.

TMS320F2803x Microcontrollers
The F2803x series increases the pin-count and memory size options. The F2803x series also introduces the parallel control law accelerator (CLA) option.

TMS320F2805x Microcontrollers
The F2805x series is similar to the F2803x series but adds on-chip programmable gain amplifiers (PGAs). InstaSPIN-FOC and InstaSPIN-MOTION™ versions are available.

TMS320F2806x Microcontrollers
The F2806x series is the first to include a floating-point unit (FPU). The F2806x series also increases the pin-count, memory size options, and the quantity of peripherals. InstaSPIN-FOC™ and InstaSPIN-MOTION™ versions are available.

TMS320F2807x Microcontrollers
The F2807x series offers the most performance, largest pin counts, flash memory sizes, and peripheral options. The F2807x series includes the latest generation of accelerators, ePWM peripherals, and analog technology.

TMS320F28004x Microcontrollers
The F28004x series is a reduced version of the F2807x series with the latest generational enhancements. The F28004x series is the best roadmap option for those using the F2806x series. InstaSPIN-FOC and configurable logic block (CLB) versions are available.

7 Terminal Configuration and Functions

7.1 引脚图

图 7-1 显示了 48 引脚 PT 薄型四方扁平封装 (LQFP) 引脚分配。图 7-2 显示了 38 引脚 DA 薄型小外形尺寸封装 (TSSOP) 引脚分配。

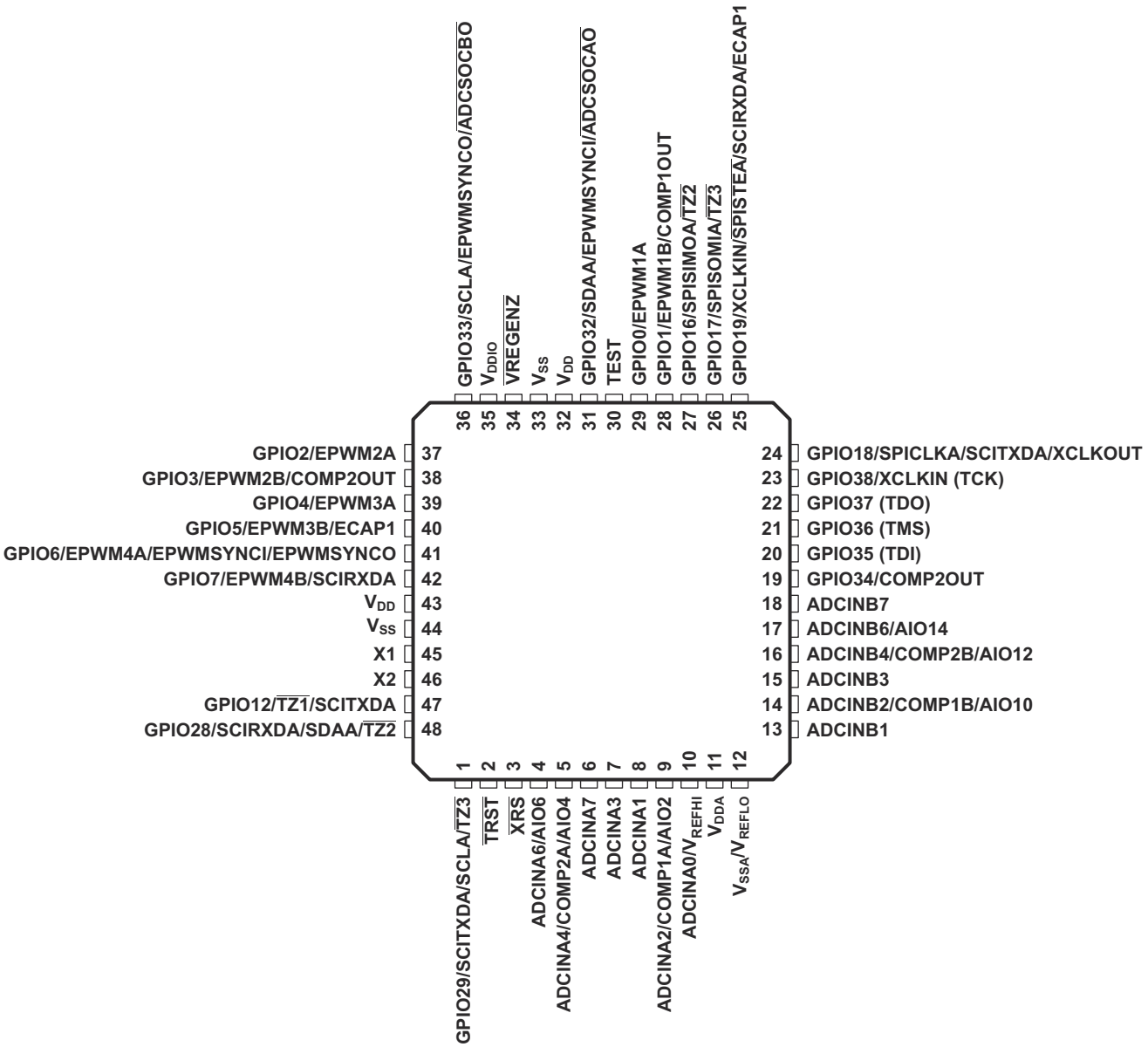


图 7-1. 2802x 48 引脚 PT LQFP（顶视图）

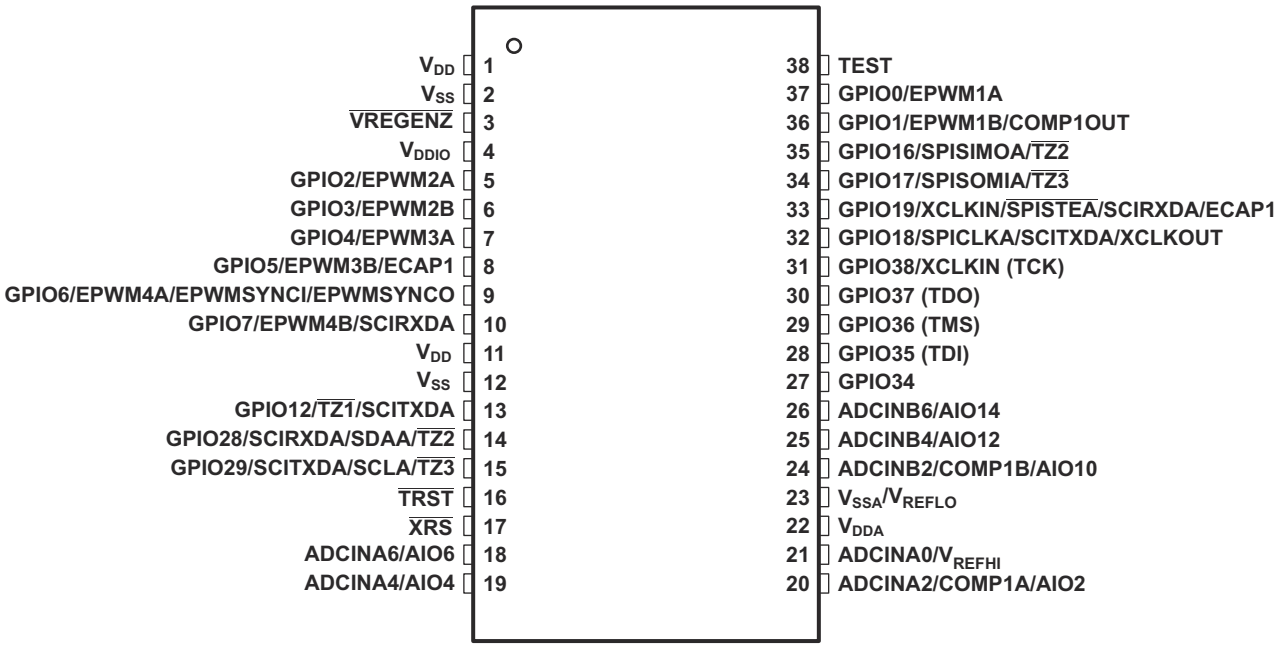


图 7-2. 2802x 38 引脚 DA TSSOP（顶视图）

7.2 信号说明

节 7.2.1 对这些信号进行了说明。除 JTAG 引脚以外，除非另有说明，否则 GPIO 功能是复位时的默认功能。它们下面列出的外设信号是供替换的功能。有些外设功能并不在所有器件上提供。有关详细信息，请参阅表 6-1。输入不可承受 5V 电压。所有 GPIO 引脚为 I/O/Z 且有一个内部上拉电阻，在每个引脚上可选择性启用/禁用此电阻。这一特性只适用于 GPIO 引脚。复位时不启用 PWM 引脚上的上拉电阻。复位后启用其他 GPIO 引脚上的上拉电阻。AIO 引脚没有内部上拉电阻。

备注

使用片上 VREG 时，GPIO19、GPIO34、GPIO35、GPIO36、GPIO37 和 GPIO38 引脚在上电期间可能有毛刺。这种潜在的毛刺将在读取引导模式引脚之前结束，不会影响引导行为。如果应用不能接受毛刺，可从外部提供 1.8V 电源。或者添加一个与这些引脚串联的限流电阻（例如 470Ω），可考虑使用外部驱动器限制降级到引脚和/或外部电路的可能性。当使用外部 1.8V 电源时，无需电源时序。然而，如果 I/O 引脚的电平转换输出缓冲器中的 3.3V 晶体管在 1.8V 晶体管之前上电，输出缓冲器有可能打开，这会导致上电期间引脚上出现毛刺。为了避免这种情况，V_{DD} 引脚应早于 V_{DDIO} 引脚或与之同时上电，确保 V_{DD} 引脚在 V_{DDIO} 引脚达到 0.7V 之前达到 0.7V。

7.2.1 信号说明

终端			I/O/Z	说明
名称(1)	PT 引脚编号	DA 引脚编号		
JTAG				
$\overline{TRST}$	2	16	I	具有内部下拉电阻的 JTAG 测试复位。驱动为高电平时，$\overline{TRST}$ 交由扫描系统控制器件的运行。如果此信号未连接或驱动为低电平，则器件将在功能模式下工作，测试复位信号将被忽略。 **注意：** $\overline{TRST}$ 是高电平有效的测试引脚，在器件正常工作期间必须始终保持低电平。此引脚上需要一个外部上拉电阻。此电阻的值应该基于设计适用的调试器 Pod 的驱动强度。一个 2.2kΩ 电阻器一般可提供足够的保护。由于这是特定于应用的，所以 TI 建议验证每个目标板是否能正常运行调试器和应用。(↓)
TCK	参阅 GPIO38		I	参阅 GPIO38。带有内部上拉电阻的 JTAG 测试时钟 (↑)
TMS	参阅 GPIO36		I	参阅 GPIO36。带有内部上拉电阻的 JTAG 测试模式选择 (TMS)。此串行控制输入在 TCK 上升沿输入到 TAP 控制器。(↑)
TDI	参阅 GPIO35		I	参阅 GPIO35。带有内部上拉电阻的 JTAG 测试数据输入 (TDI)。TDI 在 TCK 的上升沿输入到选择的寄存器（指令或数据）。(↑)
TDO	参阅 GPIO37		O/Z	参阅 GPIO37。JTAG 扫描输出，测试数据输出 (TDO)。所选寄存器（指令或数据）的内容在 TCK 下降沿从 TDO 移出。 （8mA 驱动）
闪存				
TEST	30	38	I/O	测试引脚。为 TI 预留。必须保持未连接状态。

终端			I/O/Z	说明
名称(1)	PT 引脚编号	DA 引脚编号		
时钟				
XCLKOUT	参阅 GPIO18		O/Z	参阅 GPIO18。源自 SYSCLKOUT 的输出时钟。XCLKOUT 频率要么与 SYSCLKOUT 的频率相同，要么是后者的一半或四分之一。这通过 XCLK 寄存器中的位 1:0 (XCLKOUTDIV) 控制。复位时，XCLKOUT = SYSCLKOUT/4。通过将 XCLKOUTDIV 设定为 3，可关闭 XCLKOUT 信号。GPIO18 的多路复用器控制也必须设定为 XCLKOUT，才能使此信号传播到引脚。
XCLKIN	参阅 GPIO19 和 GPIO38		I	参阅 GPIO19 和 GPIO38。外部振荡器输入。时钟的引脚源由 XCLK 寄存器内的 XCLKINSEL 位控制，默认选择 GPIO38。此引脚馈送来自外部 3.3V 振荡器的时钟。在这种情况下，X1 引脚（如果可用）必须连接至 GND，而且必须通过 CLKCTL 寄存器内的 14 位禁用片上晶体振荡器。如果使用晶振/谐振器，必须通过 CLKCTL 寄存器内的 13 位禁用 XCLKIN 路径。 **注意：**使用 GPIO38/TCK/XCLKIN 引脚提供外部时钟以使器件正常工作的设计可能需要集成一些挂钩，以便在使用 JTAG 连接器调试期间禁用此路径。这是为了防止 JTAG 调试会话期间活动的 TCK 信号相互竞争。此时可使用零引脚内部振荡器为器件计时。
X1	45	-	I	1.8V 片上晶体振荡器输入。要使用此振荡器，必须在 X1 和 X2 之间连接一个石英晶振或陶瓷谐振器。在这种情况下，必须通过 CLKCTL 寄存器内的 13 位禁用 XCLKIN 路径。如果此引脚未使用，必须连接至 GND。(I)
X2	46	–	O	片上晶体振荡器输出。必须在 X1 和 X2 之间连接一个石英晶振或陶瓷谐振器。如果 X2 未使用，必须保持未连接状态。(O)
复位				
$\overline{XRS}$	3	17	I/OD	器件复位（进）和看门狗复位（出）。这些器件具有内置上电复位 (POR) 电路和欠压复位 (BOR) 电路。在上电或欠压情况下，此引脚由器件驱动为低电平。外部电路也可能会驱动此引脚使器件复位生效。发生看门狗复位时，此引脚也由 MCU 驱动为低电平。在看门狗复位期间，$\overline{XRS}$ 引脚在 512 个 OSCCLK 周期的看门狗复位持续时间内被驱动为低电平。应在 $\overline{XRS}$ 和 V_{DDIO} 之间放置一个值为 2.2kΩ 至 10kΩ 的电阻器。如果在 $\overline{XRS}$ 和 V_{SS} 之间放置一个电容器进行噪声滤除，则该电容器的值应为 100nF 或更小。当看门狗复位生效时，这些值将能让看门狗在 512 个 OSCCLK 周期内正确地将 $\overline{XRS}$ 引脚驱动至 V_{OL}。任何源头的器件复位都会导致器件终止执行。程序计数器指向位置 0x3F FFC0 包含的地址。当复位失效时，从程序计数器指定的位置开始执行。此引脚的输出缓冲器是一个有内部上拉电阻的开漏器件。(↑) 如果此引脚由外部器件驱动，则应使用开漏器件进行驱动。
ADC、比较器、模拟 I/O				
ADCINA7	6	–	I	ADC 组 A，通道 7 输入
ADCINA6 AIO6	4	18	I I/O	ADC 组 A，通道 6 输入 数字 AIO 6
ADCINA4 COMP2A AIO4	5	19	I I I/O	ADC 组 A，通道 4 输入 比较器输入 2A（只在 48 引脚器件内可用） 数字 AIO 4
ADCINA3	7	–	I	ADC 组 A，通道 3 输入
ADCINA2 COMP1A AIO2	9	20	I I I/O	ADC 组 A，通道 2 输入 比较器输入 1A 数字 AIO 2
ADCINA1	8	-	I	ADC 组 A，通道 1 输入
ADCINA0 V_{REFHI}	10	21	I I	ADC 组 A，通道 0 输入 ADC 外部基准高 - 仅在 ADC 外部基准模式下使用。参阅节 9.9.1.1，ADC。
ADCINB7	18	-	I	ADC 组 B，通道 7 输入
ADCINB6 AIO14	17	26	I I/O	ADC 组 B，通道 6 输入 数字 AIO 14

终端			I/O/Z	说明
名称(1)	PT 引脚编号	DA 引脚编号		
ADCINB4 COMP2B AIO12	16	25	I I I/O	ADC 组 B，通道 4 输入 比较器输入 2B（只在 48 引脚器件内可用） 数字 AIO 12
ADCINB3	15	-	I	ADC 组 B，通道 3 输入
ADCINB2 COMP1B AIO10	14	24	I I I/O	ADC 组 B，通道 2 输入 比较器输入 1B 数字 AIO 10
ADCINB1	13	-	I	ADC 组 B，通道 1 输入
CPU 和 I/O 电源				
V_{DDA}	11	22		模拟电源引脚。在此引脚附近连接一个 2.2 μ F 电容器（典型值）。
V_{SSA} V_{REFLO}	12	23	I	模拟接地引脚 ADC 外部基准低（始终接地）
V_{DD}	32 43	1 11		CPU 和逻辑数字电源引脚。使用内部 VREG 时，在每个 V_{DD} 引脚和接地之间放置一个 1.2μF 电容器。可使用值较高的电容器。
V_{DDIO}	35	4		数字 I/O 缓冲器和闪存电源引脚。启用 VREG 时使用单电源。在此引脚上放置一个去耦电容器。确切值应由系统电压调节解决方案决定。
V_{SS}	33 44	2 12		数字接地引脚
稳压器控制信号				
$\overline{\text{VREGENZ}}$	34	3	I	具有内部下拉电阻的内部稳压器 (VREG) 使能。直接连接到 VSS（低）以启用内部 1.8V VREG。直接连接到 VDDIO（高）以禁用 VREG 并使用外部 1.8V 电源。
GPIO 和外设信号 (2)				
GPIO0 EPWM1A - -	29	37	I/O/Z O - -	通用输入/输出 0 增强型 PWM1 输出 A 和 HRPWM 通道 - -
GPIO1 EPWM1B - COMP1OUT	28	36	I/O/Z O - O	通用输入/输出 1 增强型 PWM1 输出 B 比较器 1 的直接输出
GPIO2 EPWM2A - -	37	5	I/O/Z O	通用输入/输出 2 增强型 PWM2 输出 A 和 HRPWM 通道 - -
GPIO3 EPWM2B - COMP2OUT	38	6	I/O/Z O O	通用输入/输出 3 增强型 PWM2 输出 B - 比较器 2 的直接输出（只在 48 引脚器件内可用）
GPIO4 EPWM3A - -	39	7	I/O/Z O	通用输入/输出 4 增强型 PWM3 输出 A 和 HRPWM 通道 - -

终端			I/O/Z	说明
名称(1)	PT 引脚编号	DA 引脚编号		
GPIO5	40	8	I/O/Z	通用输入/输出 5
EPWM3B			O	增强型 PWM3 输出 B
-				-
ECAP1			I/O	增强型捕捉输入/输出 1
GPIO6	41	9	I/O/Z	通用输入/输出 6
EPWM4A			O	增强型 PWM4 输出 A 和 HRPWM 通道
EPWMSYNCI			I	外部 ePWM 同步脉冲输入
EPWMSYNCO			O	外部 ePWM 同步脉冲输出
GPIO7	42	10	I/O/Z	通用输入/输出 7
EPWM4B			O	增强型 PWM4 输出 B
SCIRXDA			I	SCI-A 接收数据
-				-
GPIO12	47	13	I/O/Z	通用输入/输出 12
$\overline{TZ1}$			I	跳闸区输入 1
SCITXDA			O	SCI-A 发送数据
-				-
GPIO16	27	35	I/O/Z	通用输入/输出 16
SPISIMOA			I/O	SPI 从器件输入，主器件输出
-				-
$\overline{TZ2}$			I	跳闸区输入 2
GPIO17	26	34	I/O/Z	通用输入/输出 17
SPISOMIA			I/O	SPI-A 从器件输出，主器件输入
-				-
$\overline{TZ3}$			I	跳闸区输入 3
GPIO18	24	32	I/O/Z	通用输入/输出 18
SPICLKA			I/O	SPI-A 时钟输入/输出
SCITXDA			O	SCI-A 发送
XCLKOUT			O/Z	源自 SYSCLKOUT 的输出时钟。XCLKOUT 频率要么与 SYSCLKOUT 的频率相同，要么是后者的一半或四分之一。这通过 XCLK 寄存器中的位 1:0 (XCLKOUTDIV) 控制。复位时，XCLKOUT = SYSCLKOUT/4。通过将 XCLKOUTDIV 设定为 3，可关闭 XCLKOUT 信号。GPIO18 的多路复用器控制也必须设定为 XCLKOUT，才能使此信号传播到引脚。
GPIO19	25	33	I/O/Z	通用输入/输出 19
XCLKIN			I	外部振荡器输入。此引脚到时钟块的路径不受此引脚的多路复用器功能控制。如果此路径用于其他外设功能，必须注意不要启用此路径来计时。
$\overline{SPISTEA}$			I/O	SPI-A 从器件发送使能输入/输出
SCIRXDA			I	SCI-A 接收
ECAP1			I/O	增强型捕捉输入/输出 1
GPIO28	48	14	I/O/Z	通用输入/输出 28
SCIRXDA			I	SCI 接收数据
SDAA			I/OD	I2C 数据开漏双向端口
$\overline{TZ2}$			I	跳闸区输入 2

终端			I/O/Z	说明
名称(1)	PT 引脚编号	DA 引脚编号		
GPIO29	1	15	I/O/Z	通用输入/输出 29。
SCITXDA			O	SCI 发送数据
SCLA			I/OD	I2C 时钟开漏双向端口
$\overline{TZ3}$			I	跳闸区输入 3
GPIO32	31	-	I/O/Z	通用输入/输出 32
SDAA			I/OD	I2C 数据开漏双向端口
EPWMSYNCI			I	增强型 PWM 外部同步脉冲输入
$\overline{ADCSOCAO}$			O	ADC 转换启动 A
GPIO33	36	-	I/O/Z	通用输入/输出 33
SCLA			I/OD	I2C 时钟开漏双向端口
EPWMSYNCO			O	增强型 PWM 外部同步脉冲输入
$\overline{ADCSOCBO}$			O	ADC 转换启动 B
GPIO34	19	27	I/O/Z	通用输入/输出 34
COMP2OUT			O	比较器 2 的直接输出。在 DA 封装中，COMP2OUT 信号不可用。
-				-
-				-
GPIO35	20	28	I/O/Z	通用输入/输出 35
TDI			I	带有内部上拉电阻的 JTAG 测试数据输入 (TDI)。TDI 在 TCK 的上升沿输入到选择的寄存器（指令或数据）
GPIO36	21	29	I/O/Z	通用输入/输出 36
TMS			I	带有内部上拉电阻的 JTAG 测试模式选择 (TMS)。此串行控制输入在 TCK 上升沿输入到 TAP 控制器。
GPIO37	22	30	I/O/Z	通用输入/输出 37
TDO			O/Z	JTAG 扫描输出，测试数据输出 (TDO)。所选寄存器（指令或数据）的内容在 TCK 下降沿从 TDO 移出（8mA 驱动）
GPIO38	23	31	I/O/Z	通用输入/输出 38
TCK			I	带有内部上拉电阻的 JTAG 测试时钟
XCLKIN			I	外部振荡器输入。此引脚到时钟块的路径不受此引脚的多路复用器功能控制。如果此路径用于其他功能，必须注意不要启用此路径来计时。

(1) I = 输入，O = 输出，Z = 高阻抗，OD = 开漏，↑ = 上拉，↓ = 下拉
(2) GPIO 功能（以粗斜体显示）在复位时为默认值。它们下面列出的外设信号是供替换的功能。对于 GPIO 功能多路复用的 JTAG 引脚，输入到 GPIO 块的路径始终有效。根据 $\overline{TRST}$ 信号条件，启用/禁用从 GPIO 块输出的路径和从一个引脚到 JTAG 块的路径。有关详细信息，请参阅 *TMS320F2802x、TMS320F2802xx 技术参考手册*中的“系统控制”一章。

8 规格

8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1) (2)

		MIN	MAX	UNIT
Supply voltage	V_{DDIO} (I/O and Flash) with respect to V_{SS}	–0.3	4.6	V
	V_{DD} with respect to V_{SS}	–0.3	2.5	
Analog voltage	V_{DDA} with respect to V_{SSA}	–0.3	4.6	V
Input voltage	V_{IN} (3.3 V)	–0.3	4.6	V
	V_{IN} (X1)	–0.3	2.5	
Output voltage	V_O	–0.3	4.6	V
Input clamp current	Digital/analog input (per pin), I_{IK} ($V_{IN} < V_{SS}$ or $V_{IN} > V_{DDIO}$)(3)	–20	20	mA
	Analog input (per pin), $I_{IKANALOG}$ ($V_{IN} < V_{SSA}$ or $V_{IN} > V_{DDA}$)	–20	20	
	Total for all inputs, $I_{IKTOTAL}$ ($V_{IN} < V_{SS}/V_{SSA}$ or $V_{IN} > V_{DDIO}/V_{DDA}$)	–20	20	
Output clamp current	I_{OK} ($V_O < 0$ or $V_O > V_{DDIO}$)	–20	20	mA
Junction temperature(4)	T_J	–40	150	°C
Storage temperature(4)	T_{stg}	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under 节 8.4 is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to V_{SS}, unless otherwise noted.
(3) Continuous clamp current per pin is ±2 mA. Do not operate in this condition continuously as V_{DDIO}/V_{DDA} voltage may internally rise and impact other electrical specifications.
(4) Long-term high-temperature storage or extended use at maximum temperature conditions may result in a reduction of overall device life. For additional information, see *Semiconductor and IC Package Thermal Metrics*; *Calculating Useful Lifetimes of Embedded Processors*; and *Calculating FIT for a Mission Profile*.

8.2 ESD 等级 - 汽车

			值	单位
采用 48 引脚 PT 封装的 TMS320F28027-Q1、TMS320F28027F-Q1、TMS320F28026-Q1、TMS320F28026F-Q1、TMS320F28023-Q1、TMS320F28022-Q				
$V_{(ESD)}$ 静电放电	人体放电模型 (HBM)，符合 AEC Q100-002(1)	所有引脚	±2000	V
	充电器件模型 (CDM)，符合 AEC Q100-011	除边角引脚以外的所有引脚	±500	
		48 引脚 PT 上的转角引脚：1、12、13、24、25、36、37、48	±750	
采用 38 引脚 DA 封装的 TMS320F28027-Q1、TMS320F28027F-Q1、TMS320F28026-Q1、TMS320F28026F-Q1、TMS320F28023-Q1、TMS320F28022-Q1				
$V_{(ESD)}$ 静电放电	人体放电模型 (HBM)，符合 AEC Q100-002(1)	所有引脚	±2000	V
	充电器件模型 (CDM)，符合 AEC Q100-011	除边角引脚以外的所有引脚	±500	
		38 引脚 DA 上的转角引脚：1、19、20、38	±750	

(1) AEC Q100-002 指示应当按照 ANSI/ESDA/JEDEC JS-001 规范执行 HBM 应力测试。

8.3 ESD 等级 - 商用

		值	单位
采用 48 引脚 PT 封装的 TMS320F28027-Q1、TMS320F28027F-Q1、TMS320F28026-Q1、TMS320F28026F-Q1、TMS320F28023-Q1、TMS320F28022-Q1、TMS320F28021、TMS320F28020、TMS320F280200			
$V_{(ESD)}$ 静电放电	人体放电模型 (HBM)，符合 ANSI/ESDA/JEDEC JS-001 标准(1)	±2000	V
	充电器件模型 (CDM)，符合 JEDEC 规范 JESD22-C101 或 ANSI/ESDA/JEDEC JS-002(2)	±500	
采用 38 引脚 DA 封装的 TMS320F28027-Q1、TMS320F28027F-Q1、TMS320F28026-Q1、TMS320F28026F-Q1、TMS320F28023-Q1、TMS320F28022-Q1、TMS320F28021、TMS320F28020、TMS320F280200			
$V_{(ESD)}$ 静电放电	人体放电模型 (HBM)，符合 ANSI/ESDA/JEDEC JS-001 标准(1)	±2000	V
	充电器件模型 (CDM)，符合 JEDEC 规范 JESD22-C101 或 ANSI/ESDA/JEDEC JS-002(2)	±500	

(1) JEDEC 文件 JEP155 规定：500V HBM 可实现在标准 ESD 控制流程下安全生产。
(2) JEDEC 文档 JEP157 指出：250V CDM 可实现在标准 ESD 控制流程下安全生产。

8.4 建议工作条件

		最小值	标称值	最大值	单位
器件电源电压，I/O，V_{DDIO} (1)		2.97	3.3	3.63	V
器件电源电压 CPU，V_{DD}（当内部 VREG 禁用并且由 1.8V 电源外部供电时）		1.71	1.8	1.995	V
电源接地，V_{SS}			0		V
模拟电源电压，V_{DDA}		2.97	3.3	3.63	V
模拟接地，V_{SSA}			0		V
器件时钟频率（系统时钟）	28020、28021、280200	2		40	MHz
	28022、28023	2		50	
	28026、28027	2		60	
高电平输入电压，V_{IH}(3.3V)		2		V_{DDIO}+0.3	V
低电平输入电压，V_{IL}(3.3V)		V_{SS}-0.3		0.8	V
高电平输出源电流，V_{OH}=V_{OH}（最小值），I_{OH}	所有 GPIO/AIO 引脚			-4	mA
	组 2(2)			-8	mA
低电平输出灌电流，V_{OL}=V_{OL}（最大值），I_{OL}	所有 GPIO/AIO 引脚			4	mA
	组 2(2)			8	mA
结温，T_J (3)	T 版本	-40		105	°C
	S 版本	-40		125	
	Q 版本（AEC Q100 认证）	-40		125	

(1) 如果 BOR 未被使用，那么 V_{DDIO} 可使用一个 ±10% 的容差。有关详细信息，请参阅 *TMS320F2802x、TMS320F2802xx MCU 器件勘误表*。如果 BOR 被启用，V_{DDIO} 的容差为 ±5%。
(2) 组 2 引脚如下所示：GPIO16、GPIO17、GPIO18、GPIO19、GPIO28、GPIO29、GPIO36、GPIO37
(3) T_A（环境温度）取决于产品和应用，可达到器件的指定 T_J 最大值。热性能设计注意事项，请参阅节 8.8。

8.5 功耗摘要

8.5.1 TMS320F2802x/F280200 在 40MHz SYSCLKOUT 下的电流消耗

模式(1)	测试条件	VREG 启用				VREG 禁用					
		I_{DDIO} (2)		I_{DDA} (3)		I_{DD}		I_{DDIO} (2)		I_{DDA} (3)	
		典型值 (4)	最大值	典型值 (4)	最大值	典型值 (4)	最大值	典型值(4)	最大值	典型值 (4)	最大值
工作（闪存）	启用下列外设时钟： • ePWM1/2/3/4 • eCAP1 • SCI-A • SPI-A • ADC • I2C • COMP1/2 • CPU Timer0/1/2 所有 PWM 引脚在 40kHz 下切换。 所有 I/O 引脚保持未连接状态。(5) 代码即将耗尽有 1 个等待状态的闪存。 XCLKOUT 关闭。	70mA	80mA	13mA	18mA	62mA	70mA	15mA	18mA	13mA	18mA
空闲	闪存断电。 XCLKOUT 关闭。 所有外设时钟关闭。	13mA	16mA	53 µA	58 µA	15mA	17mA	120 µA	400 µA	53 µA	58 µA
待机	闪存断电。 外设时钟关闭。	3mA	6mA	10 µA	15 µA	3mA	6mA	120 µA	400 µA	10 µA	15 µA
停机	闪存断电。 外设时钟关闭。 输入时钟禁用。(6)	50 µA		10 µA	15 µA	15 µA		25 µA		10 µA	15 µA

(1) 对于 TMS320F280200 器件，从节 8.5.1 中显示的工作模式的 I_{DD}（VREG 禁用）/I_{DDIO}（VREG 启用）电流数字中减去 eCAP 的 I_{DD} 电流数字（参阅表 8-1）。
(2) I_{DDIO} 电流取决于 I/O 引脚上的电力负载。
(3) 要实现空闲、待机、停机模式下的 I_{DDA} 电流，必须通过写入 PCLKCR0 寄存器来显式关闭 ADC 模块的时钟。
(4) 典型值数字适用于室温和标称电压下。
(5) 在循环中完成以下操作：
- 数据持续从 SPI-A 和 SCI-A 端口中发出。
- 使用硬件乘法器。
- 复位看门狗。
- ADC 执行连续转换。
- COMP1/2 是连续开关电压。
- 切换 GPIO17。

(6) 如果使用石英晶振或者陶瓷谐振器作为时钟源，停机模式将关闭片上晶体振荡器。

8.5.2 TMS320F2802x 在 50MHz SYSCLKOUT 下的电流消耗

模式	测试条件	VREG 启用				VREG 禁用					
		I_{DDIO} (1)		I_{DDA} (2)		I_{DD}		I_{DDIO} (1)		I_{DDA} (2)	
		典型值 (3)	最大值	典型值 (3)	最大值	典型值 (3)	最大值	典型值 (3)	最大值	典型值 (3)	最大值
工作（闪存）	启用下列外设时钟： • ePWM1/2/3/4 • eCAP1 • SCI-A • SPI-A • ADC • I2C • COMP1/2 • CPU Timer0/1/2 所有 PWM 引脚在 40kHz 下切换。 所有 I/O 引脚保持未连接状态。(4) 代码即将耗尽有 1 个等待状态的闪存。 XCLKOUT 关闭。	80mA	90mA	13mA	18mA	71mA	80mA	15mA	18mA	13mA	18mA
空闲	闪存断电。 XCLKOUT 关闭。 所有外设时钟关闭。	16mA	19mA	64 µA	69 µA	17mA	20mA	120 µA	400 µA	64 µA	69 µA
待机	闪存断电。 外设时钟关闭。	4mA	7mA	10 µA	15 µA	4mA	7mA	120 µA	400 µA	10 µA	15 µA
停机	闪存断电。 外设时钟关闭。 输入时钟禁用。(5)	50 µA		10 µA	15 µA	15 µA		25 µA		10 µA	15 µA

(1) I_{DDIO} 电流取决于 I/O 引脚上的电力负载。
(2) 要实现空闲、待机、停机模式下的 I_{DDA} 电流，必须通过写入 PCLKCR0 寄存器来显式关闭 ADC 模块的时钟。
(3) 典型值数字适用于室温和标称电压下。
(4) 在循环中完成以下操作：
- 数据持续从 SPI-A 和 SCI-A 端口中发出。
- 使用硬件乘法器。
- 复位看门狗。
- ADC 执行连续转换。
- COMP1/2 是连续开关电压。
- 切换 GPIO17。

(5) 如果使用石英晶振或者陶瓷谐振器作为时钟源，停机模式将关闭片上晶体振荡器。

8.5.3 TMS320F2802x 在 60MHz SYSCLKOUT 下的电流消耗

模式	测试条件	VREG 启用				VREG 禁用					
		I_{DDIO} (1)		I_{DDA} (2)		I_{DD}		I_{DDIO} (1)		I_{DDA} (2)	
		典型值(3)	最大值	典型值(3)	最大值	典型值(3)	最大值	典型值(3)	最大值	典型值(3)	最大值
工作（闪存）	启用下列外设时钟： • ePWM1/2/3/4 • eCAP1 • SCI-A • SPI-A • ADC • I2C • COMP1/2 • CPU-TIMER0/1/2 所有 PWM 引脚在 60kHz 下切换。 所有 I/O 引脚保持未连接状态。(4) 代码即将耗尽有 2 个等待状态的闪存。 XCLKOUT 关闭。	90mA	100mA	13mA	18mA	80mA	90mA	15mA	18mA	13mA	18mA
空闲	闪存断电。 XCLKOUT 关闭。 所有外设时钟关闭。	18mA	23mA	75 µA	80 µA	19mA	24mA	120 µA	400 µA	75 µA	80 µA
待机	闪存断电。 外设时钟关闭。	4mA	7mA	10 µA	15 µA	4mA	7mA	120 µA	400 µA	10 µA	15 µA
停机	闪存断电。 外设时钟关闭。 输入时钟禁用。(5)	50 µA		10 µA	15 µA	15 µA		25 µA		10 µA	15 µA

(1) I_{DDIO} 电流取决于 I/O 引脚上的电力负载。
(2) 要实现空闲、待机、停机模式下的 I_{DDA} 电流，必须通过写入 PCLKCR0 寄存器来显式关闭 ADC 模块的时钟。
(3) 典型值数字适用于室温和标称电压下。
(4) 在循环中完成以下操作：
- 数据持续从 SPI-A 和 SCI-A 端口中发出。
- 使用硬件乘法器。
- 复位看门狗。
- ADC 执行连续转换。
- COMP1/2 是连续开关电压。
- 切换 GPIO17。

(5) 如果使用石英晶振或者陶瓷谐振器作为时钟源，停机模式将关闭片上晶体振荡器。

备注

器件中实现的外设 I/O 多路复用可防止同时使用所有可用外设。这是因为多个外设功能可能共享一个 I/O 引脚。然而，可同时打开所有外设的时钟，不过此配置并无用处。如果这么做，器件消耗的电流将大于电流消耗表中指定的数值。

8.5.4 Reducing Current Consumption

The 2802x/280200 devices incorporate a method to reduce the device current consumption. Because each peripheral unit has an individual clock-enable bit, significant reduction in current consumption can be achieved by turning off the clock to any peripheral module that is not used in a given application. Furthermore, any one of the three low-power modes could be taken advantage of to reduce the current consumption even further. 表 8-1 indicates the typical reduction in current consumption achieved by turning off the clocks.

表 8-1. Typical Current Consumption by Various Peripherals (at 60 MHz)

PERIPHERAL MODULE(1) (3)	I_{DD} CURRENT REDUCTION (mA)
ADC	2(2)
I2C	3
ePWM	2
eCAP	2
SCI	2
SPI	2
COMP/DAC	1
HRPWM	3
CPU-TIMER	1
Internal zero-pin oscillator	0.5

(1) All peripheral clocks (except CPU Timer clocks) are disabled upon reset. Writing to/reading from peripheral registers is possible only after the peripheral clocks are turned on.
(2) This number represents the current drawn by the digital portion of the ADC module. Turning off the clock to the ADC module results in the elimination of the current drawn by the analog portion of the ADC (I_{DDA}) as well.
(3) For peripherals with multiple instances, the current quoted is per module. For example, the 2 mA value quoted for ePWM is for one ePWM module.

备注

I_{DDIO} current consumption is reduced by 15 mA (typical) when XCLKOUT is turned off.

备注

The baseline I_{DD} current (current when the core is executing a dummy loop with no peripherals enabled) is 45 mA, typical. To arrive at the I_{DD} current for a given application, the current-drawn by the peripherals (enabled by that application) must be added to the baseline I_{DD} current.

Following are other methods to reduce power consumption further:

- The flash module may be powered down if code is run off SARAM. This results in a current reduction of 18 mA (typical) in the V_{DD} rail and 13 mA (typical) in the V_{DDIO} rail.
- Savings in I_{DDIO} may be realized by disabling the pullups on pins that assume an output function.
- To realize the lowest V_{DDA} current consumption in a low-power mode, see the respective analog chapter of the *TMS320F2802x,TMS320F2802xx Technical Reference Manual* to ensure each module is powered down as well.

8.5.5 流耗图（VREG 启用）

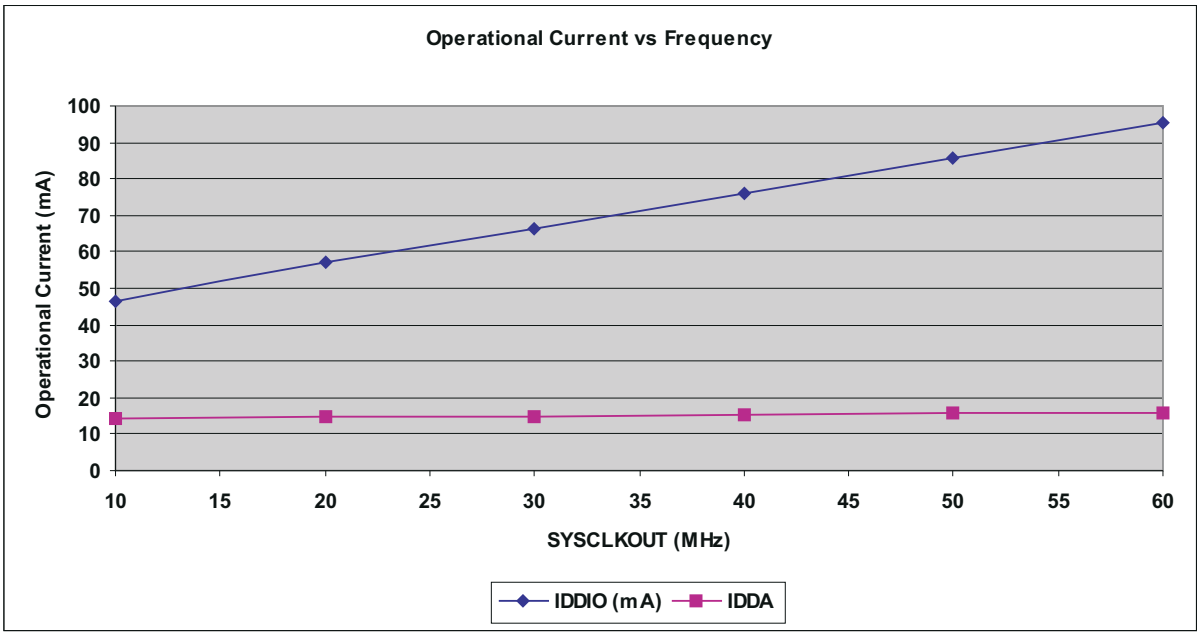


图 8-1. 典型运行电流与频率间的关系 (F2802x/F280200)

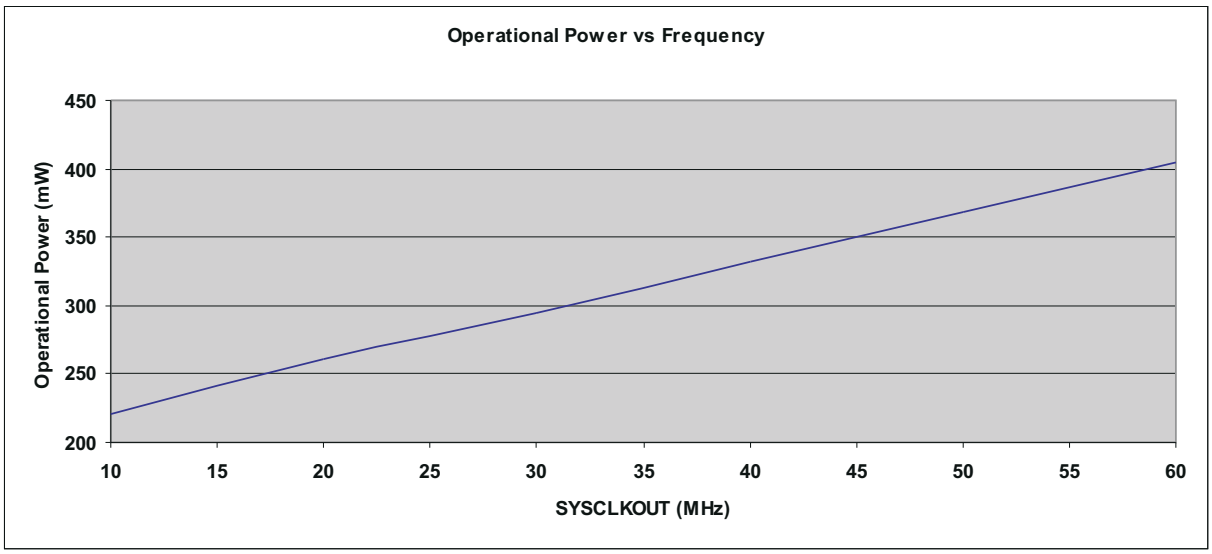


图 8-2. 典型运行功率与频率间的关系 (F2802x/F280200)

8.6 电气特性

在推荐的运行条件下（除非另有说明）(1)

参数			测试条件		最小值	典型值	最大值	单位
V_{OH}	高电平输出电压		I_{OH}=I_{OH} 最大值		2.4			V
			I_{OH}=50 μA		V_{DDIO}-0.2			
V_{OL}	低电平输出电压		I_{OL}=I_{OL} 最大值				0.4	V
I_{IL}	输入电流（低电平）	启用上拉的引脚	V_{DDIO}=3.3V，V_{IN}=0V	所有 GPIO	-80	-140	-205	μA
				$\overline{XRS}$ 引脚	-225	-290	-360	
		启用下拉的引脚	V_{DDIO}=3.3V，V_{IN}=0V				±2	

在推荐的运行条件下 (除非另有说明) (1)

参数			测试条件	最小值	典型值	最大值	单位
I_{IH}	输入电流 (高电平)	启用上拉的引脚	V_{DDIO}=3.3V，V_{IN}=V_{DDIO}			±2	μA
		启用下拉的引脚	V_{DDIO}=3.3V，V_{IN}=V_{DDIO}	28	50	80	
I_{OZ}	输出电流，上拉电阻器或者下拉电阻器被禁用		V_O = V_{DDIO} 或 0V			±2	μA
C_I	输入电容				2		pF
	V_{DDIO} BOR 触发点		下降的 V_{DDIO}	2.42	2.65	3.135	V
	V_{DDIO} BOR 滞后				35		mV
	监视器复位延迟时间		延迟时间过后，BOR/POR/OVR 事件被移除以释放 $\overline{XRS}$	400		800	μs
	VREG V_{DD} 输出		内部 VREG 打开		1.9		V

(1) 当片上 VREG 被使用时，它的输出由 POR/BOR 电路监控，如果内核电压 (V_{DD}) 超出范围，此电路将复位器件。

8.7 热阻特性

8.7.1 PT 封装

		°C/W(1)	气流 (lfm)(2)
$R_{\Theta JC}$	结至外壳热阻	13.6	不适用
$R_{\Theta JB}$	结至电路板热阻	30.6	不适用
$R_{\Theta JA}$（高 k PCB）	结至大气热阻	64	0
		50.4	150
		48.2	250
		45	500
Psi_{JT}	结至封装顶部	0.56	0
		0.94	150
		1.1	250
		1.38	500
Psi_{JB}	结至电路板	30.1	0
		28.7	150
		28.4	250
		28	500

(1) 以上值基于 JEDEC 定义的 2S2P 系统（基于 JEDEC 定义的 1S0P 系统的 Theta JC [$R_{\Theta JC}$] 值除外），将随环境和应用的变化而更改。如需更多信息，请参阅以下 EIA/JEDEC 标准：

- JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions - Natural Convection (Still Air)*
- JESD51-3, *Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*
- JESD51-7, *High Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*
- JESD51-9, *Test Boards for Area Array Surface Mount Package Thermal Measurements*

(2) lfm = 线性英尺/分钟

8.7.2 DA 封装

		°C/W(1)	气流 (lfm)(2)
$R_{\Theta JC}$	结至外壳热阻	12.8	不适用
$R_{\Theta JB}$	结至电路板热阻	33	不适用
$R_{\Theta JA}$（高 k PCB）	结至大气热阻	70.1	0
		56.4	150
		53.9	250
		50.2	500
Psi_{JT}	结至封装顶部	0.34	0
		0.61	150
		0.74	250
		0.98	500
Psi_{JB}	结至电路板	32.5	0
		32.1	150
		31.7	250
		31.1	500

(1) 以上值基于 JEDEC 定义的 2S2P 系统（基于 JEDEC 定义的 1S0P 系统的 Theta JC [$R_{\Theta JC}$] 值除外），将随环境和应用的变化而更改。如需更多信息，请参阅以下 EIA/JEDEC 标准：

- JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions - Natural Convection (Still Air)*
- JESD51-3, *Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*
- JESD51-7, *High Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*
- JESD51-9, *Test Boards for Area Array Surface Mount Package Thermal Measurements*

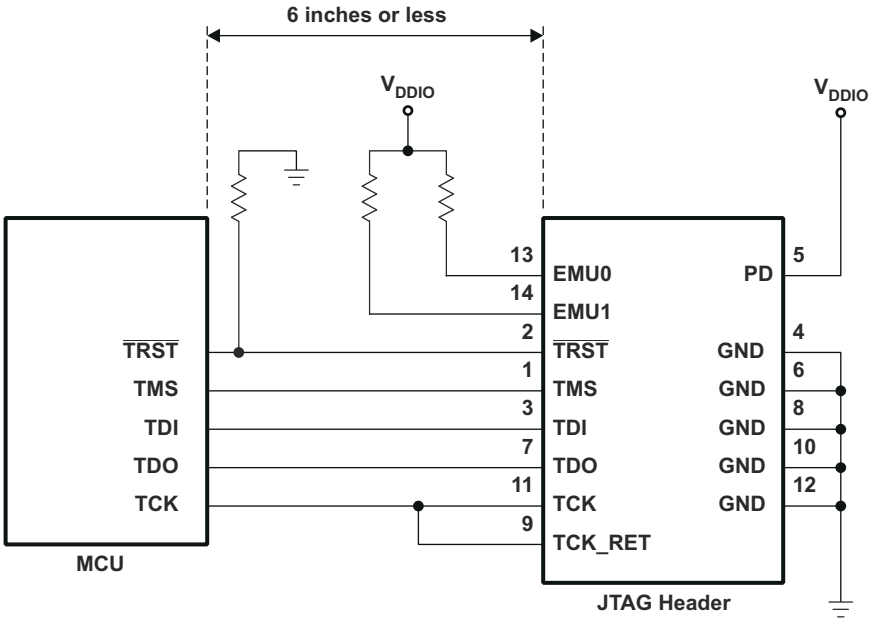
(2) lfm = 线性英尺/分钟

8.8 散热设计注意事项

根据最终应用设计和运行情况，I_{DD} 和 I_{DDIO} 电流可能有所不同。最终产品中超过建议最大功率损耗的系统可能需要额外的散热增强措施。环境温度 (T_A) 因最终应用和产品设计而异。影响可靠性和功能性的关键因素是结温 T_J，而非环境温度。因此，应该注意将 T_J 保持在指定限值内。应该测量 T_{case} 以评估运行结温 T_J。通常在封装顶部表面的中心测量 T_{case}。热应用报告*半导体和 IC 封装热指标*可帮助您了解各项热指标和相关定义。

8.9 无信号缓冲情况下 MCU 与 JTAG 调试探针的连接

图 8-3 显示了采用单处理器配置时 MCU 和 JTAG 接头之间的连接。如果 JTAG 接头和 MCU 之间的距离大于 6 英寸，那么仿真信号必须被缓冲。如果距离小于 6 英寸，通常无需缓冲。图 8-3 显示了较简单、无缓冲的情况。对于上拉/下拉电阻器的值，请参阅节 7.2，信号说明。



A. 有关 JTAG/GPIO 多路复用的信息，请参阅图 9-39。

图 8-3. 无信号缓冲情况下 MCU 与 JTAG 调试探针的连接

备注

2802x 器件无 EMU0/EMU1 引脚。对于具有板载 JTAG 接头的设计，接头上的 EMU0/EMU1 引脚必须通过一个 4.7kΩ（典型值）电阻连接至 V_{DDIO}。

8.10 参数信息

8.10.1 时序参数符号

所用的时序参数符号是按照 JEDEC 标准 100 创建的。为了缩短符号，有些引脚名称和其他相关术语已如下缩写：

小写下标及其意义：		字母和符号及其意义：	
a	访问时间	H	高
c	周期时间（周期）	L	低
d	延迟时间	V	有效
f	下降时间	X	未知、改变或者不关心级别
h	保持时间	Z	高阻抗
r	上升时间		
su	建立时间		
t	转换时间		
v	有效时间		
w	脉冲持续时间（宽度）		

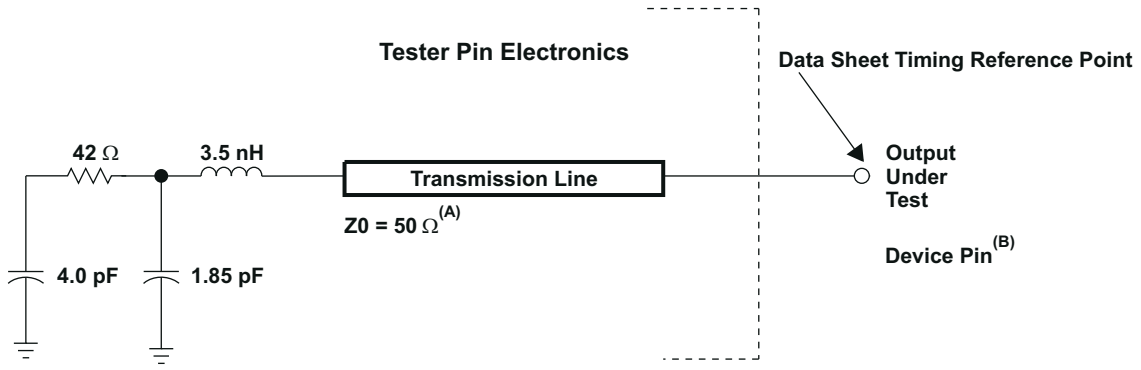
8.10.2 定时参数的通用注释

所有 28x 器件的输出信号（包括 XCLKOUT）取自一个内部时钟，这样，对于一个指定半周期的所有输出转换在一个互相之间相对最小转换率时发生。

这个显示在下面时序图中的信号组合也许不一定代表真实的周期。对于真实周期范例，请参见本文档的合适周期说明部分。

8.11 测试负载电路

此测试负载电路用于测量本文档中提供的所有开关特性。



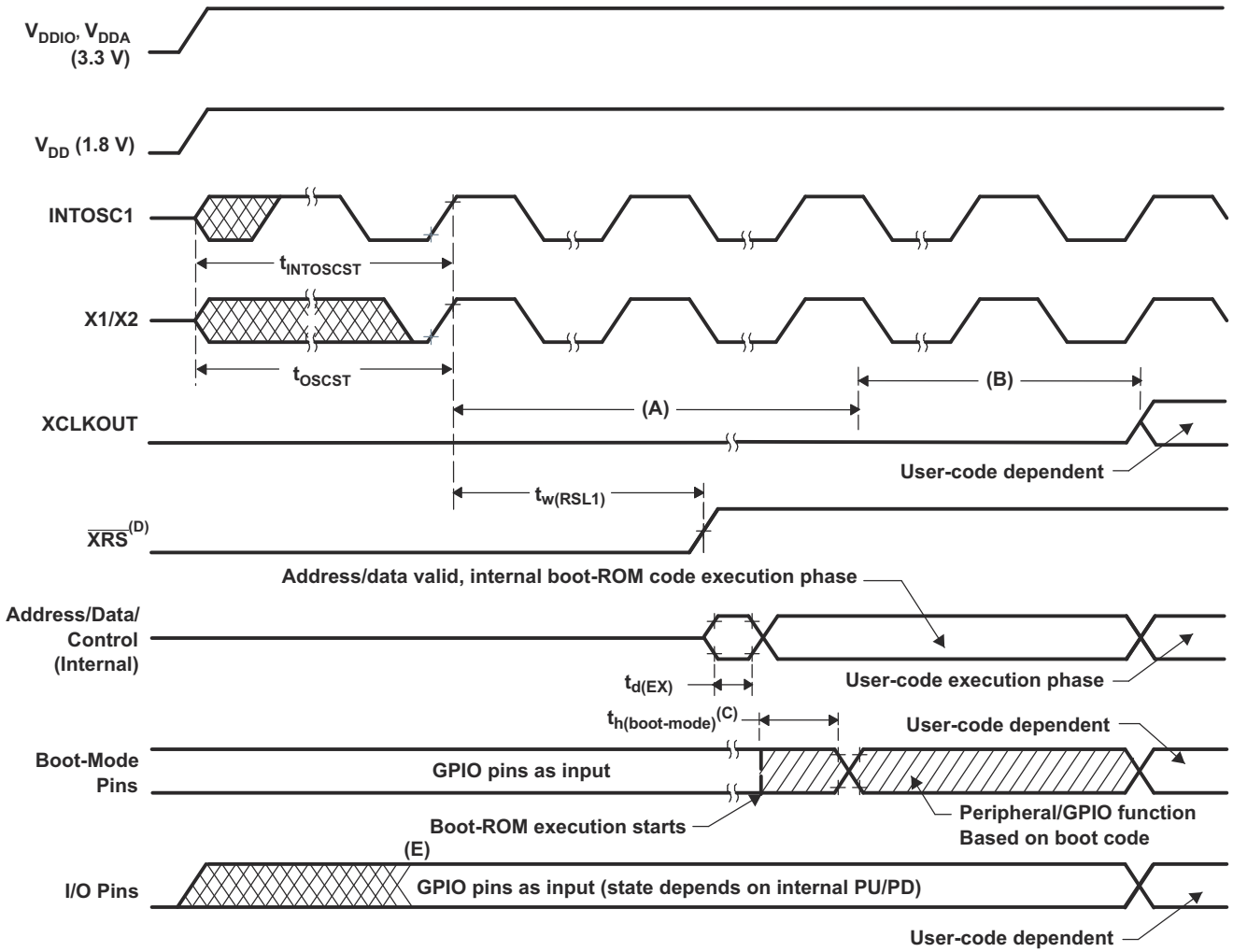
A. 此数据表中的输入要求是在器件引脚上以小于每纳秒 4 伏 (4V/ns) 的输入转换率测试得出的。

B. 此数据表提供器件引脚上的时序。在分析输出时序时，必须考虑测试仪引脚电子元件及其传输线路影响。可使用具有 2ns 或更长延迟时间的传输线路实现所需的传输线路效果。传输线路只用作负载。无需从数据表时序中增加或者减去传输线路延迟（2ns 或者更长）。

图 8-4. 3.3V 测试负载电路

8.12 电源时序

复位后无需电源时序来确保器件处于正常状态或者防止上电/下电期间的 I/O 上的毛刺脉冲（GPIO19、GPIO34 – 38 上没有无毛刺脉冲 I/O）。在器件上电之前，不应将 V_{DDIO} 之上大于二极管压降 (0.7V) 的电压应用于任何数字引脚（对于模拟引脚，此值是高于 V_{DDA} 0.7V 的电压值）。应用于未加电器件的引脚上的电压会以一种无意的方式偏置内部 p-n 接头并产生无法预料的结果。



A. 上电时，SYSCLKOUT 为 OSCCLK/4。由于 XCLK 寄存器内的 XCLKOUTDIV 位出现复位状态 0，SYSCLKOUT 在出现在 XCLKOUT 上之前会进一步除以 4。这个状态期间，XCLKOUT=OSCCLK/16。

B. 引导 ROM 将 DIVSEL 位配置为 /1 运行。在这个状态期间，XCLKOUT=OSCCLK/4。XCLKOUT 只有通过用户代码明确配置，才会显示在引脚上。

C. 复位后，引导 ROM 代码采样引导模式引脚。基于引导模式引脚的状态，引导代码向目的内存或者引导代码函数下达分支指令。如果引导 ROM 代码在加电条件后（在调试器环境中）执行代码，引导代码执行时间由当前的 SYSCLKOUT 的速度而定。SYSCLKOUT 将基于用户环境并可在 PLL 启用或者不启用时使用。

D. 由于片上加电复位 (POR) 电路，使用 $\overline{XRS}$ 引脚是可选的。

E. 当 BOR 被驱动为高电平，内部上拉/下拉将起作用。

图 8-5. 加电复位

8.12.1 复位 (XRS) 时序要求

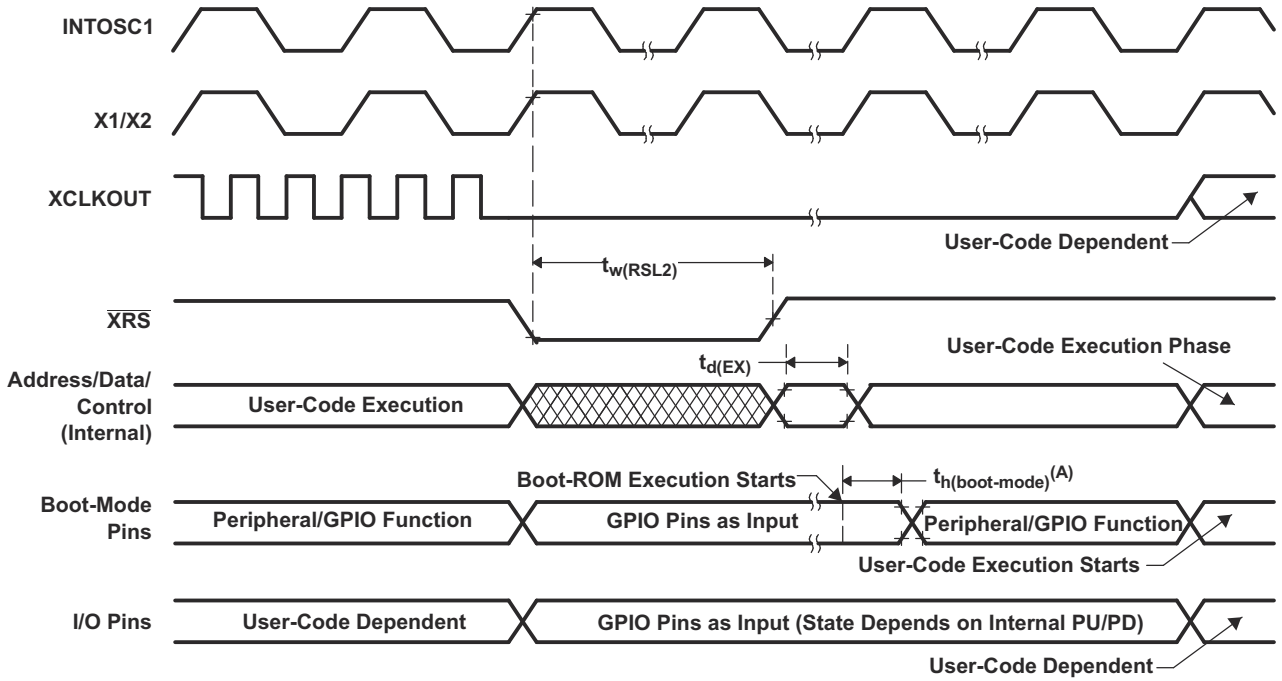
		最小值	最大值	单位
$t_{h(引导模式)}$	引导模式引脚的保持时间	$1000t_{c(SCO)}$		周期
$t_{w(RSL2)}$	脉冲持续时间，热复位时 XRS 处于低电平	$32t_{c(OSCCLK)}$		周期

8.12.2 复位 (XRS) 开关特性

在推荐的运行条件下（除非另有说明）

参数		测试条件	最小值	典型值	最大值	单位
$t_{w(RSL1)}$	脉冲持续时间，XRS 由器件驱动			600		μs
$t_{w(WDRS)}$	脉冲持续时间，由看门狗生成复位脉冲			$512t_{c(OSCCLK)}$		周期
$t_{d(EX)}$	延迟时间，XRS 高电平后，地址/数据有效			$32t_{c(OSCCLK)}$		周期
$t_{INTOSCST}$	启动时间，内部零引脚振荡器			3		μs
t_{OSCST} (1)	片上晶体振荡器启动时间		1	10		ms

(1) 取决于晶体/谐振器和电路板设计。



A. 复位后，引导 ROM 代码采样引导模式引脚。基于引导模式引脚的状态，引导代码向目的内存或者引导代码函数下达分支指令。如果引导 ROM 代码在加电条件后（在调试器环境中）执行代码，引导代码执行时间由当前的 SYSCLKOUT 的速度而定。SYSCLKOUT 将基于用户环境并可在 PLL 启用或者不启用时使用。

图 8-6. 热复位

图 8-7 显示了写入 PLLCR 寄存器所产生的效果的一个示例。在第一个阶段，PLLCR = 0x0004 且 SYSCLKOUT = OSCCLK x 2。然后写入 0x0008 到 PLLCR。就在 PLLCR 寄存器被写入后，PLL 锁存阶段开始。在此阶段，SYSCLKOUT = OSCCLK/2。在 PLL 锁存完成后，SYSCLKOUT 表示新的运行频率，OSCCLK x 4。

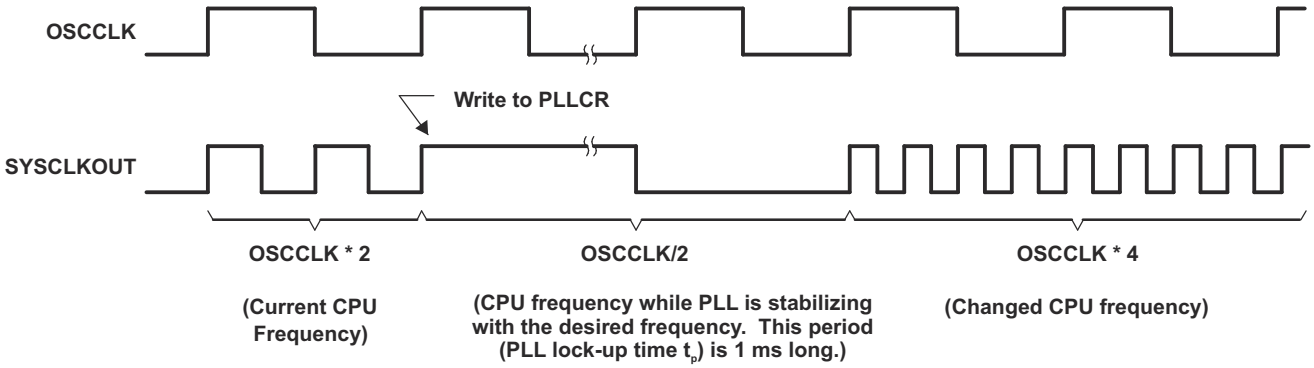


图 8-7. 写入 PLLCR 寄存器所产生的结果的示例

8.13 时钟规范

8.13.1 器件时钟表

此部分介绍 2802x MCU 上可用的不同时钟选项的定时要求和开关特性。节 8.13.1.1、节 8.13.1.2 和 节 8.13.1.3 列出了不同时钟的周期时间。

8.13.1.1 2802x 时钟表和命名规则（40MHz 器件）

		最小值	标称值	最大值	单位
SYSCLKOUT	$t_{c(SCO)}$，周期时间	25		500	ns
	频率	2		40	MHz
LSPCLK(1)	$t_{c(LCO)}$，周期时间	25	100(2)		ns
	频率		10(2)	40	MHz
ADC 时钟	$t_{c(ADCCLK)}$，周期时间	25			ns
	频率			40	MHz

(1) 更低的 LSPCLK 将减少器件功耗。
(2) 如果 SYSCLKOUT=40MHz，这个值为缺省复位值。

8.13.1.2 2802x 时钟表和命名规则（50MHz 器件）

		最小值	标称值	最大值	单位
SYSCLKOUT	$t_{c(SCO)}$，周期时间	20		500	ns
	频率	2		50	MHz
LSPCLK(1)	$t_{c(LCO)}$，周期时间	20	80(2)		ns
	频率		12.5(2)	50	MHz
ADC 时钟	$t_{c(ADCCLK)}$，周期时间	20			ns
	频率			50	MHz

(1) 更低的 LSPCLK 将减少器件功耗。
(2) 如果 SYSCLKOUT=50MHz，这个值为缺省复位值。

8.13.1.3 2802x 时钟表和命名规则（60MHz 器件）

		最小值	标称值	最大值	单位
SYSCLKOUT	$t_{c(SCO)}$，周期时间	16.67		500	ns
	频率	2		60	MHz
LSPCLK(1)	$t_{c(LCO)}$，周期时间	16.67	66.67(2)		ns
	频率		15(2)	60	MHz
ADC 时钟	$t_{c(ADCCLK)}$，周期时间	16.67			ns
	频率			60	MHz

(1) 更低的 LSPCLK 将减少器件功耗。
(2) 如果 SYSCLKOUT=60MHz，这个值为缺省复位值。

8.13.1.4 器件计时要求/特性

		最小值	标称值	最大值	单位
片上振荡器 (X1/X2 引脚) (晶振/谐振器)	$t_{c(OSC)}$，周期时间	50		200	ns
	频率	5		20	MHz
外部振荡器/时钟源 (XCLKIN 引脚) — PLL 启用	$t_{c(CI)}$，周期时间 (C8)	33.3		200	ns
	频率	5		30	MHz
外部振荡器/时钟源 (XCLKIN 引脚) — PLL 禁用	$t_{c(CI)}$，周期时间 (C8)	33.33		250	ns
	频率	4		30	MHz
跛行模式 SYSCLKOUT (/2 启用)	频率范围		1 至 5		MHz
XCLKOUT	$t_{c(XCO)}$，周期时间 (C1)	66.67		2000	ns
	频率	0.5		15	MHz
PLL 锁定时间(1)	t_p			1	ms

(1) PLLLOCKPRD 寄存器必须按照 OSCCLK 周期的数量进行更新。如果内部零引脚振荡器 (10MHz) 被用作时钟源，那么必须将值 10,000 (最小值) 写入 PLLLOCKPRD 寄存器。

8.13.1.5 内部零引脚振荡器 (INTOSC1/INTOSC2) 特性

参数		最小值	典型值	最大值	单位
内部零引脚振荡器 1 (INTOSC1)(1) (2)	频率		10		MHz
内部零引脚振荡器 2 (INTOSC2)(1) (2)	频率		10		MHz
步长尺寸 (粗调)			55		kHz
步长尺寸 (微调)			14		kHz
温度漂移(3)			3.03	4.85	kHz/°C
电压 (V_{DD}) 漂移(3)			175		Hz/mV

(1) 振荡器频率将随温度变化，请参阅图 8-8。要补偿振荡器温度漂移，请参阅*振荡器补偿指南* 和 C2000Ware。
(2) 只有当 VREG 被启用时，才能确保频率范围，$\overline{\text{VREGENZ}}$=$V_{SS}$。
(3) 内部振荡器的输出频率由温度梯度和电压 (V_{DD}) 梯度确定。例如：
- 温度的上升将引起输出频率按照温度系数增加。
- 电压的下降 (V_{DD}) 将引起输出频率按照电压系数下降。

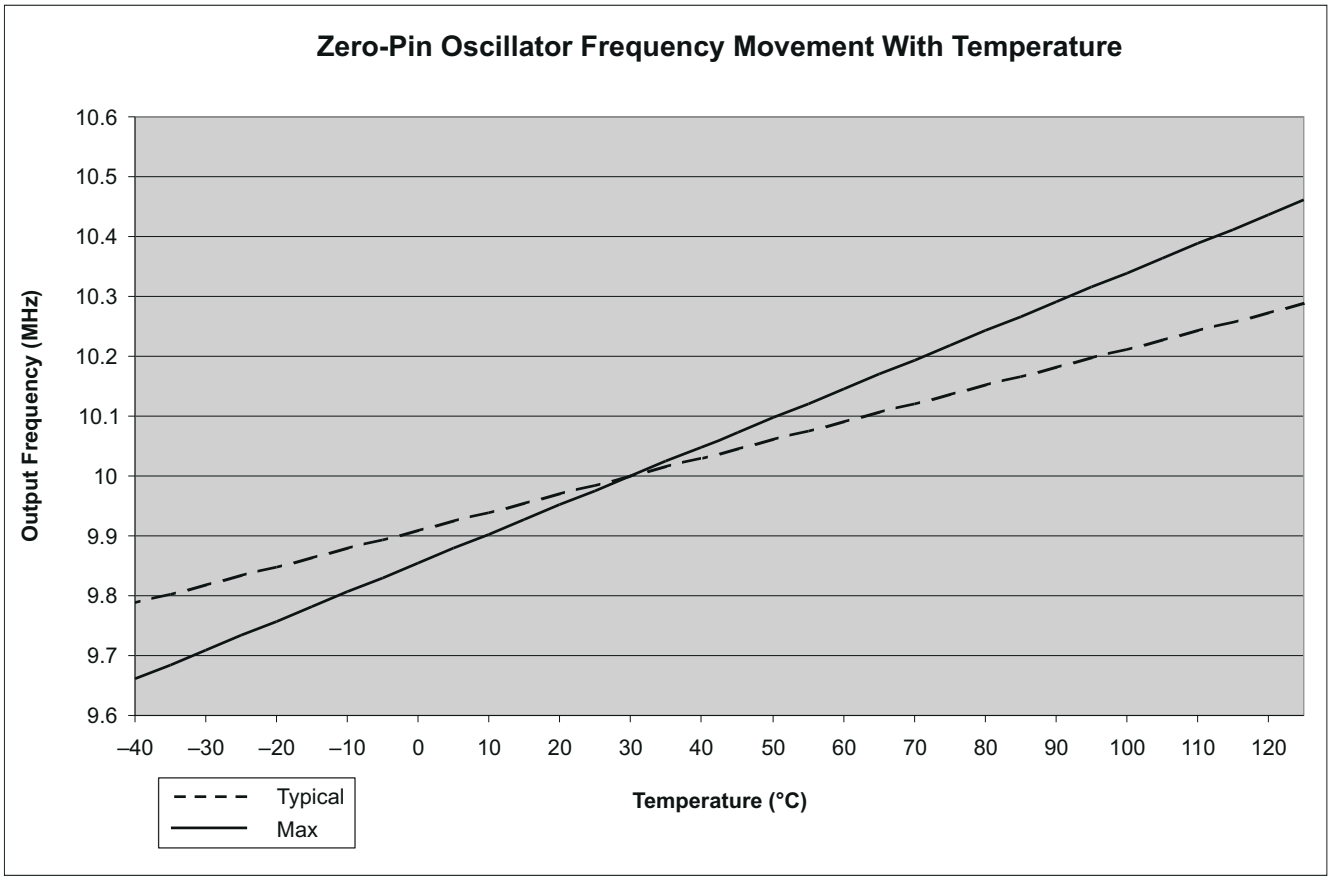


图 8-8. 随温度变化而变化的零引脚振荡器频率

8.13.2 时钟要求和特性

8.13.2.1 XCLKIN 定时要求 - PLL 已启用

编号			最小值	最大值	单位
C9	$t_{f(CI)}$	下降时间，XCLKIN		6	ns
C10	$t_{r(CI)}$	上升时间，XCLKIN		6	ns
C11	$t_{w(CIL)}$	脉冲持续时间，XCLKIN 低电平为 $t_{c(OSCCLK)}$ 的一个百分比	45%	55%	
C12	$t_{w(CIH)}$	脉冲持续时间，XCLKIN 高电平为 $t_{c(OSCCLK)}$ 的一个百分比	45%	55%	

8.13.2.2 XCLKIN 时序要求 - PLL 已禁用

编号				最小值	最大值	单位
C9	$t_{f(CI)}$	下降时间，XCLKIN	高达 20MHz		6	ns
			20MHz 至 30MHz		2	
C10	$t_{r(CI)}$	上升时间，XCLKIN	高达 20MHz		6	ns
			20MHz 至 30MHz		2	
C11	$t_{w(CIL)}$	脉冲持续时间，XCLKIN 低电平为 $t_{c(OSCCLK)}$ 的一个百分比		45%	55%	
C12	$t_{w(CIH)}$	脉冲持续时间，XCLKIN 高电平为 $t_{c(OSCCLK)}$ 的一个百分比		45%	55%	

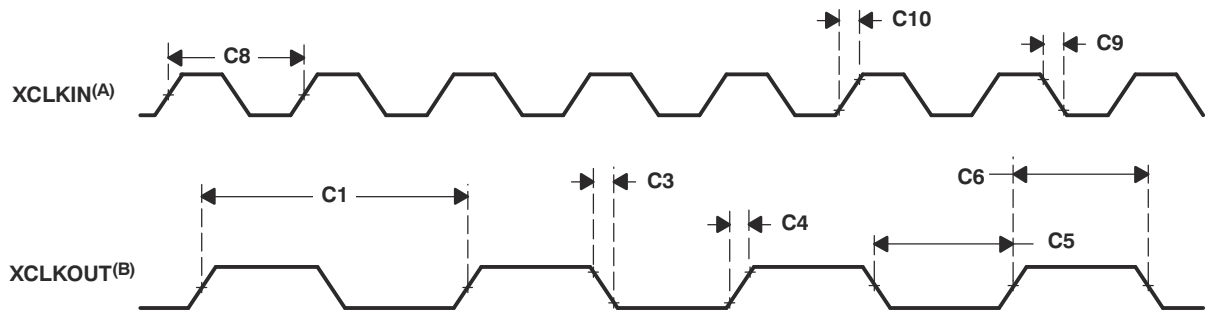
表 9-16 中显示了可能的配置模式。

8.13.2.3 XCLKOUT 开关特性（旁路或启用 PLL）

在推荐的运行条件下（除非另有说明）(1) (2)

编号	参数		最小值	最大值	单位
C3	$t_{f(XCO)}$	下降时间，XCLKOUT		11	ns
C4	$t_{r(XCO)}$	上升时间，XCLKOUT		11	ns
C5	$t_{w(XCOL)}$	脉冲持续时间，XCLKOUT 低电平	H – 2	H + 2	ns
C6	$t_{w(XCOH)}$	脉冲持续时间，XCLKOUT 高电平	H – 2	H + 2	ns

(1) 这些参数假定有 40pF 负载。
(2) $H = 0.5t_{c(XCO)}$



A. XCLKIN 与 XCLKOUT 的关系取决于所选择的分频系数。所示波形关系仅用于说明时序参数，可能因实际配置而异。
B. 已配置 XCLKOUT 以反映 SYSCLKOUT。

图 8-9. 时钟时序

8.14 闪存定时

8.14.1 T 温度材料的闪存/OTP 耐久性

		温度 擦除/编程(1)	最小值	典型值	最大值	单位
N_f	闪存对于阵列的耐受度（写入/擦除周期）	0°C 至 105°C（环境温度）	20000	50000		周期
N_{OTP}	OTP 对于阵列的耐受度（写入周期）	0°C 至 30°C（环境温度）			1	写入

(1) 所示温度范围之外的写入/擦除操作并未说明，有可能影响耐受数。

8.14.2 S 温度材料的闪存/OTP 耐久性

		温度 擦除/编程(1)	最小值	典型值	最大值	单位
N_f	闪存对于阵列的耐受度（写入/擦除周期）	0°C 至 125°C（环境温度）	20000	50000		周期
N_{OTP}	OTP 对于阵列的耐受度（写入周期）	0°C 至 30°C（环境温度）			1	写入

(1) 所示温度范围之外的写入/擦除操作并未说明，有可能影响耐受数。

8.14.3 Q 温度材料的闪存/OTP 耐久性

		温度 擦除/编程(1)	最小值	典型值	最大值	单位
N_f	闪存对于阵列的耐受度（写入/擦除周期）	-40°C 至 125°C（环境温度）	20000	50000		周期
N_{OTP}	OTP 对于阵列的耐受度（写入周期）	-40°C 至 30°C（环境温度）			1	写入

(1) 所示温度范围之外的写入/擦除操作并未说明，有可能影响耐受数。

8.14.4 60MHz SYSCLKOUT 下的闪存参数

参数		测试条件	最小值	典型值	最大值	单位
I_{DDP} (1)	擦除/编程周期内的 V_{DD} 流耗	VREG 禁用		80		mA
I_{DDIOP} (1)	擦除/编程周期内的 V_{DDIO} 流耗			60		mA
I_{DDIOP} (1)	擦除/编程周期内的 V_{DDIO} 流耗	VREG 启用		120		mA

(1) 室温下包括函数调用开销在内的典型参数，是在所有外设关闭时的参数。在整个闪存编程过程中保持稳定的电源很重要。可想而知，闪存编程期间的器件电流消耗可能高于正常工作条件下。如数据表“建议工作条件”中所述，使用的电源应始终确保 V_{MIN} 位于电源轨上。擦除/编程过程中发生任何欠压保护或电源中断，都可能会损坏密码位置并永久锁定器件。不建议通过 USB 端口为目标板供电（在闪存编程期间），因为该端口可能无法响应编程过程中设置的电源需求。

8.14.5 50MHz SYSCLKOUT 上的闪存参数：

参数		测试条件	最小值	典型值	最大值	单位
I_{DDP} (1)	擦除/编程周期内的 V_{DD} 流耗	VREG 禁用		70		mA
I_{DDIOP} (1)	擦除/编程周期内的 V_{DDIO} 流耗			60		
I_{DDIOP} (1)	擦除/编程周期内的 V_{DDIO} 流耗	VREG 启用		110		mA

(1) 室温下包括函数调用开销在内的典型参数，是在所有外设关闭时的参数。在整个闪存编程过程中保持稳定的电源很重要。可想而知，闪存编程期间的器件电流消耗可能高于正常工作条件下。如数据表“建议工作条件”中所述，使用的电源应始终确保 V_{MIN} 位于电源轨上。擦除/编程过程中发生任何欠压保护或电源中断，都可能会损坏密码位置并永久锁定器件。不建议通过 USB 端口为目标板供电（在闪存编程期间），因为该端口可能无法响应编程过程中设置的电源需求。

8.14.6 40MHz SYSCLKOUT 上的闪存参数：

参数		测试条件	最小值	典型值	最大值	单位
I_{DDP} (1)	擦除/编程周期内的 V_{DD} 流耗	VREG 禁用		60		mA
I_{DDIOP} (1)	擦除/编程周期内的 V_{DDIO} 流耗			60		

参数		测试条件	最小值	典型值	最大值	单位
I_{DDIOP} (1)	擦除/编程周期内的 V_{DDIO} 流耗	VREG 启用		100		mA

(1) 室温下包括函数调用开销在内的典型参数，是在所有外设关闭时的参数。在整个闪存编程过程中保持稳定的电源很重要。可想而知，闪存编程期间的器件电流消耗可能高于正常工作条件下。如数据表“建议工作条件”中所述，使用的电源应始终确保 V_{MIN} 位于电源轨上。擦除/编程过程中发生任何欠压保护或电源中断，都可能会损坏密码位置并永久锁定器件。不建议通过 USB 端口为目标板供电（在闪存编程期间），因为该端口可能无法响应编程过程中设置的电源需求。

8.14.7 闪存编程/擦除时间

参数		测试条件	最小值	典型值	最大值 (2)	单位
编程时间(1)	8K 扇区			250	2000	ms
	4K 扇区			125	2000	ms
	16 位字			50		μs
擦除时间(3)	8K 扇区			2	12	s
	4K 扇区			2	12	s

(1) 编程时间是最大器件频率下的值。此表中指示的编程时间仅适用于器件 RAM 中的所有必需代码/数据都可用并准备好进行编程的情况。编程时间包括闪存状态机的开销，但不包括将以下项传输到 RAM 的时间：

- 使用闪存 API 对闪存进行编程的代码
- 闪存 API 本身
- 要进行编程的闪存数据

(2) 所提到的最大闪存参数对应于前 100 个编程和擦除周期。

(3) 当器件从 TI 出货时，片上闪存存储器处于一个被擦除状态。这样，当首次编辑器件时，在编程前无需擦除闪存存储器。然而，对于所有随后的编程操作，需要执行擦除操作。

8.14.8 闪存 / OTP 访问时序

参数		最小值	最大值	单位
$t_{a(fp)}$	页式闪存访问时间	40		ns
$t_{a(fr)}$	随机闪存访问时间	40		ns
$t_{a(OTP)}$	OTP 访问时间	60		ns

8.14.9 Flash Data Retention Duration

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$t_{retention}$	Data retention duration	T_J = 55°C	15		years

表 8-2. Minimum Required Flash/OTP Wait States at Different Frequencies

SYSCLKOUT (MHz)	SYSCLKOUT (ns)	PAGE WAIT STATE(1)	RANDOM WAIT STATE(1)	OTP WAIT STATE
60	16.67	2	2	3
55	18.18	2	2	3
50	20	1	1	2
45	22.22	1	1	2
40	25	1	1	2
35	28.57	1	1	2
30	33.33	1	1	1
25	40	0	1	1

(1) Random wait state must be ⩾ 1.

The equations to compute the Flash page wait state and random wait state in 表 8-2 are as follows:

$$\text{Flash Page Wait State} = \left[\left(\frac{t_{a(f\bullet p)}}{t_{c(SCO)}}\right) - 1\right] \text{ round up to the next highest integer}$$

$$\text{Flash Random Wait State} = \left[\left(\frac{t_{a(f\cdot r)}}{t_{c(SCO)}}\right) - 1\right] \text{ round up to the next highest integer, or 1, whichever is larger}$$

The equation to compute the OTP wait state in 表 8-2 is as follows:

$$\text{OTP Wait State} = \left[\left(\frac{t_{a(OTP)}}{t_{c(SCO)}}\right) - 1\right] \text{ round up to the next highest integer, or 1, whichever is larger}$$

9 详细说明

9.1 Overview

9.1.1 CPU

2802x (C28x) 系列是 TMS320C2000™ 微控制器 (MCU) 平台的成员。基于 C28x 的控制器具有与现有 C28x MCU 一样的 32 位定点架构。它是一款高效的 C/C++ 引擎，不仅支持用户使用高级语言开发控制软件，还支持使用 C/C++ 开发数学算法。此器件在处理 MCU 算术任务时与处理系统控制任务时同样有效，而系统控制任务通常由微控制器器件处理。鉴于此器件具有高效率，无需像很多系统一样使用第二个处理器。利用 32 x 32 位 MAC 64 位处理能力，控制器能够高效地处理更高的数值分辨率问题。添加了带有关键寄存器自动环境保存的快速中断响应，使得一个器件能够用最小的延迟处理很多异步事件。此器件有一个具有流水线式存储器访问的 8 级深受保护流水线。这个流水线式操作使得此器件能够在高速执行而无需求助于昂贵的高速存储器。特别分支超前硬件大大减少了条件不连续而带来的延迟。特别存储条件操作进一步提升了性能。

9.1.2 Memory Bus (Harvard Bus Architecture)

As with many MCU-type devices, multiple buses are used to move data between the memories and peripherals and the CPU. The memory bus architecture contains a program read bus, data read bus, and data write bus. The program read bus consists of 22 address lines and 32 data lines. The data read and write buses consist of 32 address lines and 32 data lines each. The 32-bit-wide data buses enable single cycle 32-bit operations. The multiple bus architecture, commonly termed Harvard Bus, enables the C28x to fetch an instruction, read a data value and write a data value in a single cycle. All peripherals and memories attached to the memory bus prioritize memory accesses. Generally, the priority of memory bus accesses can be summarized as follows:

___	Highest:	Data Writes	(Simultaneous data and program writes cannot occur on the memory bus.)
___		Program Writes	(Simultaneous data and program writes cannot occur on the memory bus.)
___		Data Reads	
___		Program Reads	(Simultaneous program reads and fetches cannot occur on the memory bus.)
___	Lowest:	Fetches	(Simultaneous program reads and fetches cannot occur on the memory bus.)

9.1.3 外设总线

为了在多种德州仪器 (TI) MCU 器件系列间实现外设迁移，此器件采用一个针对外设互连的外设总线标准。外设总线桥对各个总线进行多路复用，使处理器内存总线成为包含 16 条地址线和 16 条或 32 条数据线及关联控制信号的单个总线。支持外设总线的三个版本。一个版本只支持 16 位访问（被称为外设帧 2）。另外版本支持 16 位和 32 位访问（被称为外设帧 1）。

9.1.4 Real-Time JTAG and Analysis

The devices implement the standard IEEE 1149.1 JTAG [1]interface for in-circuit based debug. Additionally, the devices support real-time mode of operation allowing modification of the contents of memory, peripheral, and register locations while the processor is running and executing code and servicing interrupts. The user can also single step through non-time-critical code while enabling time-critical interrupts to be serviced without interference. The device implements the real-time mode in hardware within the CPU. This is a feature unique to the 28x family of devices, requiring no software monitor. Additionally, special analysis hardware is provided that allows setting of hardware breakpoint or data/address watch-points and generating various user-selectable break events when a match occurs. These devices do not support boundary scan; however, IDCODE and BYPASS features are available if the following considerations are taken into account. The IDCODE does not come by default. The user must go through a sequence of SHIFT IR and SHIFT DR state of JTAG to get the IDCODE. For BYPASS instruction, the first shifted DR value would be 1.

9.1.5 Flash

The F280200 device contains 8K × 16 of embedded flash memory, segregated into two 4K × 16 sectors. The F28021/23/27 devices contain 32K × 16 of embedded flash memory, segregated into four 8K × 16 sectors. The F28020/22/26 devices contain 16K × 16 of embedded flash memory, segregated into four 4K × 16 sectors. All devices also contain a single 1K × 16 of OTP memory at address range 0x3D 7800 to 0x3D 7BFF. The user can individually erase, program, and validate a flash sector while leaving other sectors untouched. However, it is not possible to use one sector of the flash or the OTP to execute flash algorithms that erase/program other sectors. Special memory pipelining is provided to enable the flash module to achieve higher performance. The flash/OTP is mapped to both program and data space; therefore, it can be used to execute code or store data information. Addresses 0x3F 7FF0 to 0x3F 7FF5 are reserved for data variables and should not contain program code.

备注

The Flash and OTP wait states can be configured by the application. This allows applications running at slower frequencies to configure the flash to use fewer wait states.

Flash effective performance can be improved by enabling the flash pipeline mode in the Flash options register. With this mode enabled, effective performance of linear code execution will be much faster than the raw performance indicated by the wait-state configuration alone. The exact performance gain when using the Flash pipeline mode is application-dependent.

For more information on the Flash options, Flash wait state, and OTP wait-state registers, see the System Control chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

9.1.6 M0，M1 SARAM

所有器件包含这两块单周期访问内存，每一个的大小为 1K x 16。复位时，堆栈指针指向块 M1 的开始位置。M0 和 M1 块，与所有其它 C28x 器件上的内存块一样，被映射到程序和数据空间。因此，用户能够使用 M0 和 M1 来执行代码或者用于数据变量。分区在连接器内执行。C28x 器件提供了一个到编程器的统一内存映射。这使得用高级语言编程变得更加容易。

9.1.7 L0 SARAM

此器件包含高达 4K x 16 的单周期访问 RAM。请参考节 9.2 中的器件专用内存映射图表来确定一个指定器件的准确大小。这个块被映射到程序和数据空间。

[1] IEEE Standard 1149.1-1990 Standard Test Access Port and Boundary Scan Architecture

9.1.8 Boot ROM

The Boot ROM is factory-programmed with bootloader software. The Boot ROM uses the boot-mode-select GPIO pins to determine what boot mode to use upon power up. The user can select to boot normally to application code, to download new software from an external connection, or to select boot software that is programmed in the internal Flash/ROM. The Boot ROM also contains standard tables, such as SIN/COS waveforms, for use in math-related algorithms. The boot-ROM content, and hence the checksum value, may vary for different silicon revisions. For details, see the Boot ROM chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

表 9-1. Boot Mode Selection

MODE	GPIO37/TDO	GPIO34/COMP2OUT	TRST	MODE
3	1	1	0	GetMode
2	1	0	0	Wait (see 节 9.1.9 for description)
1	0	1	0	SCI
0	0	0	0	Parallel IO
EMU	x	x	1	Emulation Boot

9.1.8.1 仿真引导

连接 JTAG 调试探针时，无法使用 GPIO37/TDO 引脚进行引导模式选择。在这种情况下，引导 ROM 会检测已连接 JTAG 调试探针，并使用 PIE 向量表中的两个保留 SARAM 位置内容来确定引导模式。如果两个位置内的内容均无效，那么使用*等待*引导选项。可在仿真引导中访问所有引导模式选项。

9.1.8.2 GetMode

GetMode 的缺省运行状态选项为引导至闪存。通过在 OTP 中设定两个位置，这个运行状态能够被改变为其它的引导选项。如果两个 OTP 位置的内容均为无效，那么引导至闪存。可以指定以下加载程序之一：SCI、SPI、I2C 或 OTP。

9.1.8.3 引导加载器使用的外设引脚

表 9-2 显示了每一个外设引导加载器所使用的 GPIO 引脚。请参阅 GPIO 多路复用器表以检查这些引脚是否与您希望在应用中使用的任一外设冲突。

表 9-2. 外设引导加载引脚

引导加载器	外设加载器引脚
SCI	SCIRXDA (GPIO28) SCITXDA (GPIO29)
并行引导	数据 (GPIO[7:0]) 28x 控制 (GPIO16) 主机控制 (GPIO12)
SPI	SPISIMOA (GPIO16) SPISOMIA (GPIO17) SPICLKA (GPIO18) SPISTEA (GPIO19)
I2C	SDAA (GPIO32)(1) SCLA (GPIO33)(1)

(1) 在您的器件封装上，GPIO 引脚 32 和 33 也许不可用。在这些器件上，这个引导加载选项不可用。

9.1.9 Security

The devices support high levels of security to protect the user firmware from being reverse engineered. The security features a 128-bit password (hardcoded for 16 wait states), which the user programs into the flash. One code security module (CSM) is used to protect the flash/OTP and the L0/L1 SARAM blocks. The security feature prevents unauthorized users from examining the memory contents through the JTAG port or trying to boot-load some undesirable software that would export the secure memory contents. To enable access to the secure blocks, the user must write the correct 128-bit KEY value that matches the value stored in the password locations within the Flash.

In addition to the CSM, the emulation code security logic (ECSL) has been implemented to prevent unauthorized users from stepping through secure code. Any code or data access to flash, user OTP, or L0 memory while the JTAG debug probe is connected will trip the ECSL and break the debug probe connection. To allow debug of secure code, while maintaining the CSM protection against secure memory reads, the user must write the correct value into the lower 64 bits of the KEY register (KEY0 - KEY3), which matches the value stored in the lower 64 bits of the password locations (PWL0 - PWL3) within the flash. Dummy reads of all 128 bits of the password in the flash must still be performed. If the lower 64 bits of the password locations are all ones (unprogrammed), then the KEY value does not need to match. During debug of secure code, operations like single-stepping is possible. However, the actual contents of the secure memory cannot be seen in the CCS window.

When power is applied to a secure device that is connected to a JTAG debug probe, the CPU will start executing and may execute an instruction that performs an access to a protected area. If this happens, the ECSL will trip and cause the JTAG circuitry to be deactivated. Under this condition, a host (such as a computer running CCS or flash programing software) would not be able to establish connection with the device.

The solution is to use the *Wait* boot option. In this mode, the device loops around a software breakpoint to allow a JTAG debug probe to be connected without tripping security. The user can then exit this mode once the JTAG debug probe is connected by using one of the emulation boot options as described in the Boot ROM chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*. These devices do not support a hardware wait-in-reset mode.

备注

- When the code-security passwords are programmed, all addresses from 0x3F7F80 to 0x3F7FF5 cannot be used as program code or data. These locations must be programmed to 0x0000.
- If reprogramming of a secure device via JTAG may be needed in future, it is important to design the board in such a way that the device could be put in Wait boot mode upon power-up (when reprogramming is warranted). Otherwise, ECSL may deactivate the JTAG circuitry and prevent connection to the device, as mentioned earlier. If reconfiguring the device for Wait boot mode in the field is not practical, some mechanism must be implemented in the firmware to detect when a firmware update is warranted. Code could then branch to the desired bootloader in the bootROM. It could also branch to the Wait bootmode, at which point the JTAG debug probe could be connected, device unsecured and programming accomplished through JTAG itself.
- If the code security feature is not used, addresses 0x3F7F80 to 0x3F7FEF may be used for code or data. Addresses 0x3F7FF0 to 0x3F7FF5 are reserved for data and should not contain program code.

The 128-bit password (at 0x3F 7FF8 to 0x3F 7FFF) must not be programmed to zeros. Doing so would permanently lock the device.

备注

Code Security Module Disclaimer

THE CODE SECURITY MODULE (CSM) INCLUDED ON THIS DEVICE WAS DESIGNED TO PASSWORD PROTECT THE DATA STORED IN THE ASSOCIATED MEMORY (EITHER ROM OR FLASH) AND IS WARRANTED BY TEXAS INSTRUMENTS (TI), IN ACCORDANCE WITH ITS STANDARD TERMS AND CONDITIONS, TO CONFORM TO TI'S PUBLISHED SPECIFICATIONS FOR THE WARRANTY PERIOD APPLICABLE FOR THIS DEVICE.

TI DOES NOT, HOWEVER, WARRANT OR REPRESENT THAT THE CSM CANNOT BE COMPROMISED OR BREACHED OR THAT THE DATA STORED IN THE ASSOCIATED MEMORY CANNOT BE ACCESSED THROUGH OTHER MEANS. MOREOVER, EXCEPT AS SET FORTH ABOVE, TI MAKES NO WARRANTIES OR REPRESENTATIONS CONCERNING THE CSM OR OPERATION OF THIS DEVICE, INCLUDING ANY IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE.

IN NO EVENT SHALL TI BE LIABLE FOR ANY CONSEQUENTIAL, SPECIAL, INDIRECT, INCIDENTAL, OR PUNITIVE DAMAGES, HOWEVER CAUSED, ARISING IN ANY WAY OUT OF YOUR USE OF THE CSM OR THIS DEVICE, WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO LOSS OF DATA, LOSS OF GOODWILL, LOSS OF USE OR INTERRUPTION OF BUSINESS OR OTHER ECONOMIC LOSS.

9.1.10 外设中断扩展 (PIE) 块

PIE 块将许多中断源复用至中断输入的较小的集合中。PIE 块能够支持多达 96 个外设中断。在 F2802x 上，外设使用 96 个可能中断中的 33 个。96 个中断被分成 8 组，每组被提供 12 个 CPU 中断线（INT1 或者 INT12）中的 1 个。96 个中断中的每一个中断由其存储在一个可被用户写覆盖的专用 RAM 块中的矢量支持。在处理这个中断时，这个矢量由 CPU 自动抽取。抽取这个矢量以及保存关键 CPU 寄存器将花费 8 个 CPU 时钟周期。因此 CPU 能够对中断事件作出快速响应。可以通过硬件和软件控制中断的优先级。每个中断都可以在 PIE 块内启用/禁用。

9.1.11 外部中断 (XINT1-XINT3)

此器件支持 3 个被屏蔽的外部中断 (XINT1-XINT3)。每一个中断可被选择成负边沿、正边沿、或者二者触发并能够被启用/禁用。这些中断还包含一个 16 位自由运行的上数计数器，当检测到一个有效的中断边沿时，该计数器复位为 0。这个计数器可被用于为中断精确计时。没有用于外部引脚的专用引脚。XINT1，XINT2，和 XINT3 中断可接受来自 GPIO0-GPIO3 引脚的输入。

9.1.12 内部零引脚振荡器、振荡器和 PLL

此器件可由两个内部零引脚振荡器、一个外部振荡器或者一个连接至片上振荡器电路（只适用于 48 引脚器件）的晶体中的任一个计时。一个提供的 PLL 支持高达 12 个输入时钟缩放比。PLL 比率可用软件中在器件运行时更改，这使得用户在需要低功耗运行时能够按比例降低运行频率。请参阅节 8，电气规格，了解时序详细信息。PLL 块可被设定为旁路模式。

9.1.13 看门狗

每个器件包含两个看门狗：一个是监视内核的 CPU 看门狗，一个是 NMI 看门狗，后者是时钟丢失检测电路。用户软件必须在特定的时间范围内定期复位 CPU 看门狗计数器；否则，CPU 看门狗将生成对处理器的复位。必要时可禁用 CPU 看门狗。NMI 看门狗仅在发生时钟故障时才起作用，可生成一个中断或者器件复位。

9.1.14 Peripheral Clocking

The clocks to each individual peripheral can be enabled/disabled to reduce power consumption when a peripheral is not in use. Additionally, the system clock to the serial ports (except I2C) can be scaled relative to the CPU clock.

9.1.15 Low-power Modes

The devices are full static CMOS devices. Three low-power modes are provided:

IDLE:	Place CPU in low-power mode. Peripheral clocks may be turned off selectively and only those peripherals that must function during IDLE are left operating. An enabled interrupt from an active peripheral or the watchdog timer will wake the processor from IDLE mode.
STANDBY:	Turns off clock to CPU and peripherals. This mode leaves the oscillator and PLL functional. An external interrupt event will wake the processor and the peripherals. Execution begins on the next valid cycle after detection of the interrupt event
HALT:	This mode basically shuts down the device and places it in the lowest possible power consumption mode. If the internal zero-pin oscillators are used as the clock source, the HALT mode turns them off, by default. To keep these oscillators from shutting down, the INTOSCnHALTI bits in CLKCTL register may be used. The zero-pin oscillators may thus be used to clock the CPU watchdog in this mode. If the on-chip crystal oscillator is used as the clock source, it is shut down in this mode. A reset or an external signal (through a GPIO pin) or the CPU watchdog can wake the device from this mode.

The CPU clock (OSCCLK) and watchdog clock source should be from the same clock source before attempting to put the device into HALT or STANDBY.

9.1.16 外设帧 0，1，2 (PFn)

此器件将外设分成 3 个部分。 外设映射如下：

PF0：	PIE：	PIE 中断启用和控制寄存器加上 PIE 矢量表
	闪存：	闪存写入状态寄存器
	定时器：	CPU - 定时器 0，1，2 寄存器
	CSM：	代码安全模块 KEY 寄存器
	ADC：	ADC 结果寄存器
PF1：	GPIO：	GPIO MUX 配置和控制寄存器
	ePWM：	增强型脉冲宽度调制器模块和寄存器
	eCAP：	增强型捕捉模块和寄存器
	比较器：	比较器模块：
PF2：	SYS：	系统控制寄存器
	SCI：	串行通信接口 (SCI) 控制和 RX/TX 寄存器
	SPI：	串行端口接口 (SPI) 和 RX/TX 寄存器
	ADC：	ADC 状态、控制、和配置寄存器
	IC2：	集成电路间模块和寄存器
	XINT：	外部中断寄存器

9.1.17 通用输入/输出 (GPIO) 复用器

大多数的外设信号与通用输入/输出 (GPIO) 信号复用。这使得用户能够在外设信号或者功能不使用时将一个引脚用作 GPIO。复位时，GPIO 引脚被配置为输入。针对 GPIO 模式或者外设信号模式，用户能够独立设定每一个引脚。对于特定的输入，用户也可以选择输入限定周期的数量。这是为了过滤掉有害的噪音毛刺脉冲。GPIO 信号也可被用于使器件脱离特定低功耗模式。

9.1.18 32 位 CPU 定时器 (0，1，2)

CPU 定时器 0，1，和 2 是完全一样的 32 位定时器，这些定时器带有可预先设定的周期和 16 位时钟预分频。此定时器有一个 32 位倒计数寄存器，此寄存器在计数器达到 0 时生成一个中断。这个计数器的减量为被预分频值设置所分频的 CPU 时钟速度的值。当此计数器达到 0 时，它自动重新载入一个 32 位的周期值。

CPU 定时器 0 为通用定时器并被连接至 PIE 块。CPU 定时器 1 为通用定时器并被连接至 CPU 的 INT13。CPU 定时器 2 为 DSP/BIOS 保留。它被连接至 CPU 的 INT14。如果 DSP/BIOS 未被使用，CPU 定时器 2 也可称为通用定时器。

CPU 定时器 2 可由下列任一器件计时：

- SYSCLKOUT (默认)
- 内部零引脚振荡器 1 (INTOSC1)
- 内部零引脚振荡器 2 (INTOSC2)
- 外部时钟源

9.1.19 Control Peripherals

The devices support the following peripherals that are used for embedded control and communication:

ePWM:	The enhanced PWM peripheral supports independent/complementary PWM generation, adjustable dead-band generation for leading/trailing edges, latched/cycle-by-cycle trip mechanism. Some of the PWM pins support the HRPWM high resolution duty and period features. The type 1 module found on 2802x devices also supports increased dead-band resolution, enhanced SOC and interrupt generation, and advanced triggering including trip functions based on comparator outputs.
eCAP:	The enhanced capture peripheral uses a 32-bit time base and registers up to four programmable events in continuous/one-shot capture modes. This peripheral can also be configured to generate an auxiliary PWM signal.
ADC:	The ADC block is a 12-bit converter. It has up to 13 single-ended channels pinned out, depending on the device. It contains two sample-and-hold units for simultaneous sampling.
Comparator:	Each comparator block consists of one analog comparator along with an internal 10-bit reference for supplying one input of the comparator.

9.1.20 串行端口外设

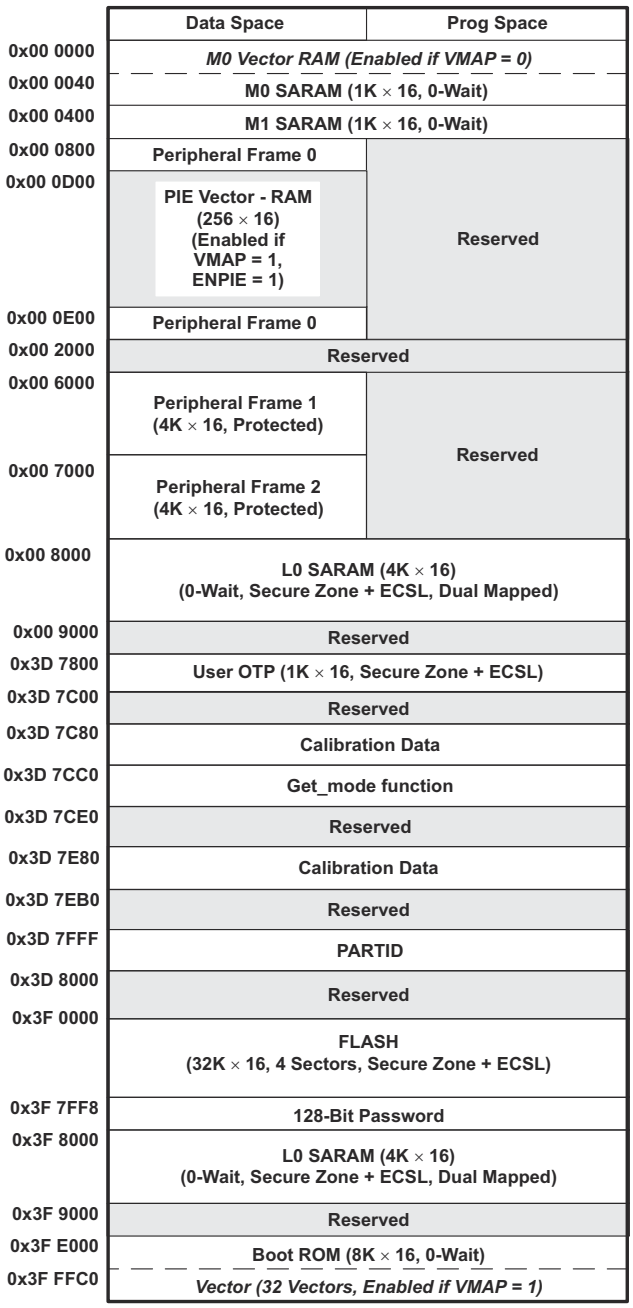
此器件支持下列的串行通信外设：

SPI：	SPI 是一个高速同步串行 I/O 端口，此端口允许编程长度（1 至 16 位）的串行位流以可编程的位传输速率移入和移出器件。通常，SPI 用于 MCU 和外部外设或者其他处理器之间的通信。典型应用包括外部 I/O 或者通过诸如移位寄存器、显示驱动器和 ADC 等器件进行外设扩展。多器件通信由 SPI 的主/从操作支持。SPI 包含用于减少中断服务开销的 4 级接收和发送 FIFO。
SCI：	串行通信接口是一种双线制异步串行端口，通常称为 UART。SCI 包含用于减少中断服务开销的 4 级接收和发送 FIFO。
I2C：	内部集成电路 (I2C) 模块在 MCU 与符合 Philips Semiconductors 内部集成电路总线（I2C 总线®）规范版本 2.1 并通过 I^2C 总线连接的其他器件之间提供一个接口。该双线串行总线上连接的外部元件可以通过 I2C 模块向 MCU 发送/从 MCU 接收多达 8 位数据。I2C 包含用于减少中断服务开销的 4 级接收和发送 FIFO。

9.2 Memory Maps

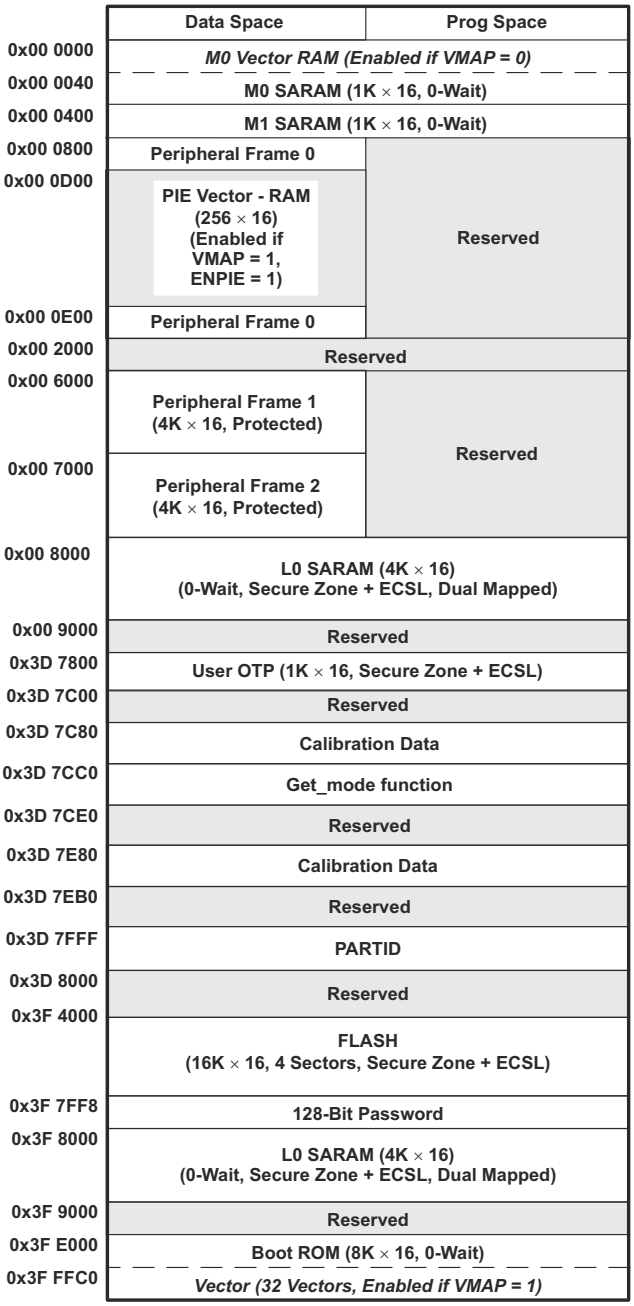
In 图 9-1, 图 9-2, 图 9-3, 图 9-4, and 图 9-5, the following apply:

- Memory blocks are not to scale.
- Peripheral Frame 0, Peripheral Frame 1 and Peripheral Frame 2 memory maps are restricted to data memory only. A user program cannot access these memory maps in program space.
- *Protected* means the order of Write-followed-by-Read operations is preserved rather than the pipeline order.
- Certain memory ranges are EALLOW protected against spurious writes after configuration.
- Locations 0x3D7C80 to 0x3D7CC0 contain the internal oscillator and ADC calibration routines. These locations are not programmable by the user.



A. Memory locations 0x3D 7E80 – 0x3D 7EAF are reserved in TMX/TMP silicon.

图 9-1. 28023-Q1/28027-Q1 Memory Map



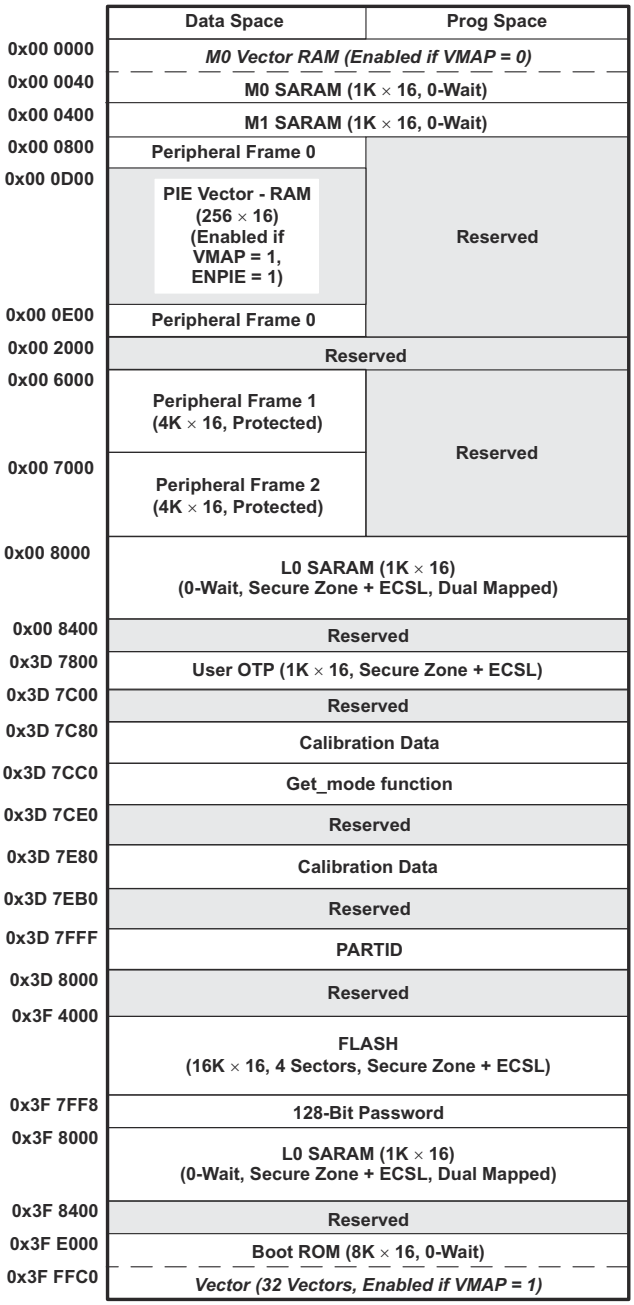
A. Memory locations 0x3D 7E80 – 0x3D 7EAF are reserved in TMX/TMP silicon.

图 9-2. 28022-Q1/28026-Q1 Memory Map

	Data Space	Prog Space
0x00 0000	*M0 Vector RAM (Enabled if VMAP = 0)*	
0x00 0040	M0 SARAM (1K × 16, 0-Wait)	
0x00 0400	M1 SARAM (1K × 16, 0-Wait)	
0x00 0800	Peripheral Frame 0	Reserved
0x00 0D00	PIE Vector - RAM (256 × 16) (Enabled if VMAP = 1, ENPIE = 1)	
0x00 0E00	Peripheral Frame 0	
0x00 2000	Reserved	
0x00 6000	Peripheral Frame 1 (4K × 16, Protected)	Reserved
0x00 7000	Peripheral Frame 2 (4K × 16, Protected)	
0x00 8000	L0 SARAM (3K × 16) (0-Wait, Secure Zone + ECSL, Dual Mapped)	
0x00 8C00	Reserved	
0x3D 7800	User OTP (1K × 16, Secure Zone + ECSL)	
0x3D 7C00	Reserved	
0x3D 7C80	Calibration Data	
0x3D 7CC0	Get_mode function	
0x3D 7CE0	Reserved	
0x3D 7E80	Calibration Data	
0x3D 7EB0	Reserved	
0x3D 7FFF	PARTID	
0x3D 8000	Reserved	
0x3F 0000	FLASH (32K × 16, 4 Sectors, Secure Zone + ECSL)	
0x3F 7FF8	128-Bit Password	
0x3F 8000	L0 SARAM (3K × 16) (0-Wait, Secure Zone + ECSL, Dual Mapped)	
0x3F 8C00	Reserved	
0x3F E000	Boot ROM (8K × 16, 0-Wait)	
0x3F FFC0	*Vector (32 Vectors, Enabled if VMAP = 1)*	

A. Memory locations 0x3D 7E80 – 0x3D 7EAF are reserved in TMX/TMP silicon.

图 9-3. 28021 Memory Map



A. Memory locations 0x3D 7E80 – 0x3D 7EAF are reserved in TMX/TMP silicon.

图 9-4. 28020 Memory Map

	Data Space	Prog Space
0x00 0000	*M0 Vector RAM (Enabled if VMAP = 0)*	
0x00 0040	M0 SARAM (1K × 16, 0-Wait)	
0x00 0400	M1 SARAM (1K × 16, 0-Wait)	
0x00 0800	Peripheral Frame 0	Reserved
0x00 0D00	PIE Vector - RAM (256 × 16) (Enabled if VMAP = 1, ENPIE = 1)	
0x00 0E00	Peripheral Frame 0	
0x00 2000	Reserved	
0x00 6000	Peripheral Frame 1 (4K × 16, Protected)	Reserved
0x00 7000	Peripheral Frame 2 (4K × 16, Protected)	
0x00 8000	L0 SARAM (1K × 16) (0-Wait, Secure Zone + ECSL, Dual Mapped)	
0x00 8400	Reserved	
0x3D 7800	User OTP (1K × 16, Secure Zone + ECSL)	
0x3D 7C00	Reserved	
0x3D 7C80	Calibration Data	
0x3D 7CC0	Get_mode function	
0x3D 7CE0	Reserved	
0x3D 7E80	Calibration Data	
0x3D 7EB0	Reserved	
0x3D 7FFF	PARTID	
0x3D 8000	Reserved	
0x3F 6000	FLASH (8K × 16, 2 Sectors, Secure Zone + ECSL)	
0x3F 7FF8	128-Bit Password	
0x3F 8000	L0 SARAM (1K × 16) (0-Wait, Secure Zone + ECSL, Dual Mapped)	
0x3F 8400	Reserved	
0x3F E000	Boot ROM (8K × 16, 0-Wait)	
0x3F FFC0	*Vector (32 Vectors, Enabled if VMAP = 1)*	

A. Memory locations 0x3D 7E80 – 0x3D 7EAF are reserved in TMX/TMP silicon.

图 9-5. 280200 Memory Map

表 9-3. Addresses of Flash Sectors in F28021/28023-Q1/28027-Q1

ADDRESS RANGE	PROGRAM AND DATA SPACE
0x3F 0000 to 0x3F 1FFF	Sector D (8K × 16)
0x3F 2000 to 0x3F 3FFF	Sector C (8K × 16)
0x3F 4000 to 0x3F 5FFF	Sector B (8K × 16)
0x3F 6000 to 0x3F 7F7F	Sector A (8K × 16)
0x3F 7F80 to 0x3F 7FF5	Program to 0x0000 when using the Code Security Module
0x3F 7FF6 to 0x3F 7FF7	Boot-to-Flash Entry Point (program branch instruction here)
0x3F 7FF8 to 0x3F 7FFF	Security Password (128-Bit) (Do not program to all zeros)

表 9-4. Addresses of Flash Sectors in F28020/28022-Q1/28026-Q1

ADDRESS RANGE	PROGRAM AND DATA SPACE
0x3F 4000 to 0x3F 4FFF	Sector D (4K × 16)
0x3F 5000 to 0x3F 5FFF	Sector C (4K × 16)
0x3F 6000 to 0x3F 6FFF	Sector B (4K × 16)
0x3F 7000 to 0x3F 7F7F	Sector A (4K × 16)
0x3F 7F80 to 0x3F 7FF5	Program to 0x0000 when using the Code Security Module
0x3F 7FF6 to 0x3F 7FF7	Boot-to-Flash Entry Point (program branch instruction here)
0x3F 7FF8 to 0x3F 7FFF	Security Password (128-Bit) (Do not program to all zeros)

表 9-5. Addresses of Flash Sectors in F280200

ADDRESS RANGE	PROGRAM AND DATA SPACE
0x3F 6000 to 0x3F 6FFF	Sector B (4K × 16)
0x3F 7000 to 0x3F 7F7F	Sector A (4K × 16)
0x3F 7F80 to 0x3F 7FF5	Program to 0x0000 when using the Code Security Module
0x3F 7FF6 to 0x3F 7FF7	Boot-to-Flash Entry Point (program branch instruction here)
0x3F 7FF8 to 0x3F 7FFF	Security Password (128-Bit) (Do not program to all zeros)

备注

- When the code-security passwords are programmed, all addresses from 0x3F 7F80 to 0x3F 7FF5 cannot be used as program code or data. These locations must be programmed to 0x0000.
- If the code security feature is not used, addresses 0x3F 7F80 to 0x3F 7FEF may be used for code or data. Addresses 0x3F 7FF0 to 0x3F 7FF5 are reserved for data and should not contain program code.

表 9-6 shows how to handle these memory locations.

表 9-6. Impact of Using the Code Security Module

ADDRESS	FLASH	
	CODE SECURITY ENABLED	CODE SECURITY DISABLED
0x3F 7F80 to 0x3F 7FEF	Fill with 0x0000	Application code and data
0x3F 7FF0 to 0x3F 7FF5		Reserved for data only

Peripheral Frame 1 and Peripheral Frame 2 are grouped together to enable these blocks to be write/read peripheral block protected. The protected mode makes sure that all accesses to these blocks happen as written. Because of the pipeline, a write immediately followed by a read to different memory locations, will appear in reverse order on the memory bus of the CPU. This can cause problems in certain peripheral applications where the user expected the write to occur first (as written). The CPU supports a block protection mode where a region of memory can be protected so that operations occur as written (the penalty is extra cycles are added to align the operations). This mode is programmable and by default, it protects the selected zones.

The wait states for the various spaces in the memory map area are listed in 表 9-7.

表 9-7. Wait States

AREA	WAIT STATES (CPU)	COMMENTS
M0 and M1 SARAMs	0-wait	Fixed
Peripheral Frame 0	0-wait	
Peripheral Frame 1	0-wait (writes) 2-wait (reads)	Cycles can be extended by peripheral generated ready. Back-to-back write operations to Peripheral Frame 1 registers will incur a 1-cycle stall (1-cycle delay).
Peripheral Frame 2	0-wait (writes) 2-wait (reads)	Fixed. Cycles cannot be extended by the peripheral.
L0 SARAM	0-wait data and program	Assumes no CPU conflicts
OTP	Programmable 1-wait minimum	Programmed through the Flash registers. 1-wait is minimum number of wait states allowed.
FLASH	Programmable 0-wait Paged min 1-wait Random min Random ≥ Paged	Programmed through the Flash registers.
FLASH Password	16-wait fixed	Wait states of password locations are fixed.
Boot-ROM	0-wait	

9.3 Register Maps

The devices contain three peripheral register spaces. The spaces are categorized as follows:

Peripheral Frame 0: These are peripherals that are mapped directly to the CPU memory bus. See 表 9-8.

Peripheral Frame 1: These are peripherals that are mapped to the 32-bit peripheral bus. See 表 9-9.

Peripheral Frame 2: These are peripherals that are mapped to the 16-bit peripheral bus. See 表 9-10.

表 9-8. Peripheral Frame 0 Registers

NAME(1)	ADDRESS RANGE	SIZE (×16)	EALLOW PROTECTED(2)
Device Emulation Registers	0x00 0880 to 0x00 0984	261	Yes
System Power Control Registers	0x00 0985 to 0x00 0987	3	Yes
FLASH Registers(3)	0x00 0A80 to 0x00 0ADF	96	Yes
Code Security Module Registers	0x00 0AE0 to 0x00 0AEF	16	Yes
ADC registers (0 wait read only)	0x00 0B00 to 0x00 0B0F	16	No
CPU – TIMER0/1/2 Registers	0x00 0C00 to 0x00 0C3F	64	No
PIE Registers	0x00 0CE0 to 0x00 0CFF	32	No
PIE Vector Table	0x00 0D00 to 0x00 0DFF	256	No

(1) Registers in Frame 0 support 16-bit and 32-bit accesses.
(2) If registers are EALLOW protected, then writes cannot be performed until the EALLOW instruction is executed. The EDIS instruction disables writes to prevent stray code or pointers from corrupting register contents.
(3) The Flash Registers are also protected by the Code Security Module (CSM).

表 9-9. Peripheral Frame 1 Registers

NAME	ADDRESS RANGE	SIZE (×16)	EALLOW PROTECTED
Comparator 1 registers	0x00 6400 to 0x00 641F	32	(1)
Comparator 2 registers	0x00 6420 to 0x00 643F	32	(1)
ePWM1 + HRPWM1 registers	0x00 6800 to 0x00 683F	64	(1)
ePWM2 + HRPWM2 registers	0x00 6840 to 0x00 687F	64	(1)
ePWM3 + HRPWM3 registers	0x00 6880 to 0x00 68BF	64	(1)
ePWM4 + HRPWM4 registers	0x00 68C0 to 0x00 68FF	64	(1)
eCAP1 registers	0x00 6A00 to 0x00 6A1F	32	No
GPIO registers	0x00 6F80 to 0x00 6FFF	128	(1)

(1) Some registers are EALLOW protected. For more information, see the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

表 9-10. Peripheral Frame 2 Registers

NAME	ADDRESS RANGE	SIZE (×16)	EALLOW PROTECTED
System Control Registers	0x00 7010 to 0x00 702F	32	Yes
SPI-A Registers	0x00 7040 to 0x00 704F	16	No
SCI-A Registers	0x00 7050 to 0x00 705F	16	No
NMI Watchdog Interrupt Registers	0x00 7060 to 0x00 706F	16	Yes
External Interrupt Registers	0x00 7070 to 0x00 707F	16	Yes
ADC Registers	0x00 7100 to 0x00 717F	128	(1)
I2C-A Registers	0x00 7900 to 0x00 793F	64	(1)

(1) Some registers are EALLOW protected. For more information, see the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

9.4 Device Emulation Registers

These registers are used to control the protection mode of the C28x CPU and to monitor some critical device signals. The registers are defined in 表 9-11 .

表 9-11. Device Emulation Registers

NAME	ADDRESS RANGE	SIZE (x16)	DESCRIPTION			EALLOW PROTECTED
DEVICECNF	0x0880 0x0881	2	Device Configuration Register			Yes
PARTID	0x3D 7FFF	1	Part ID Register	TMS320F280200PT	0x00C1	No
				TMS320F280200DA	0x00C0	
				TMS320F28027PT	0x00CF	
				TMS320F28027DA	0x00CE	
				TMS320F28027**F**PT	0x00CF	
				TMS320F28027**F**DA	0x00CE	
				TMS320F28026PT	0x00C7	
				TMS320F28026DA	0x00C6	
				TMS320F28026**F**PT	0x00C7	
				TMS320F28026**F**DA	0x00C6	
				TMS320F28023PT	0x00CD	
				TMS320F28023DA	0x00CC	
				TMS320F28022PT	0x00C5	
				TMS320F28022DA	0x00C4	
				TMS320F28021PT	0x00CB	
				TMS320F28021DA	0x00CA	
				TMS320F28020PT	0x00C3	
				TMS320F28020DA	0x00C2	
CLASSID	0x0882	1	Class ID Register	TMS320F280200PT/DA	0x00C7	No
				TMS320F28027PT/DA	0x00CF	
				TMS320F28027**F**PT/DA	0x00CF	
				TMS320F28026PT/DA	0x00C7	
				TMS320F28026**F**PT/DA	0x00C7	
				TMS320F28023PT/DA	0x00CF	
				TMS320F28022PT/DA	0x00C7	
				TMS320F28021PT/DA	0x00CF	
				TMS320F28020PT/DA	0x00C7	
REVID	0x0883	1	Revision ID Register	0x0000 - Silicon Rev. 0 - TMS		No
				0x0001 - Silicon Rev. A - TMS		
				0x0002 - Silicon Rev. B - TMS		

9.5 VREG/BOR/POR

虽然内核和 I/O 电路运行在两个不同的电压上，这些器件有一个片载电压稳压器 (VREG) 来生成 V_{DD} 电压，此电压由 V_{DDIO} 电源提供。这在应用板上免除了第二个外部稳压器的成本和空间的需要。此外，在加电和运行模式期间，内部加电复位 (POR) 和欠压复位 (BOR) 电力路监控 V_{DD} 和 V_{DDIO} 电源轨。

9.5.1 片载电压稳压器 (VREG)

一个线性稳压器生成内核电压 (V_{DD})，此电压由 V_{DDIO} 电源提供。因此，虽然在每一个 V_{DD} 引脚上都需要电容器来稳定生成的电压，但是运行此器件并不需要为这些引脚供电。相反地，如果功率或者冗余是应用关心的首要问题，那么可将 VREG 禁用。

9.5.1.1 使用片上 VREG

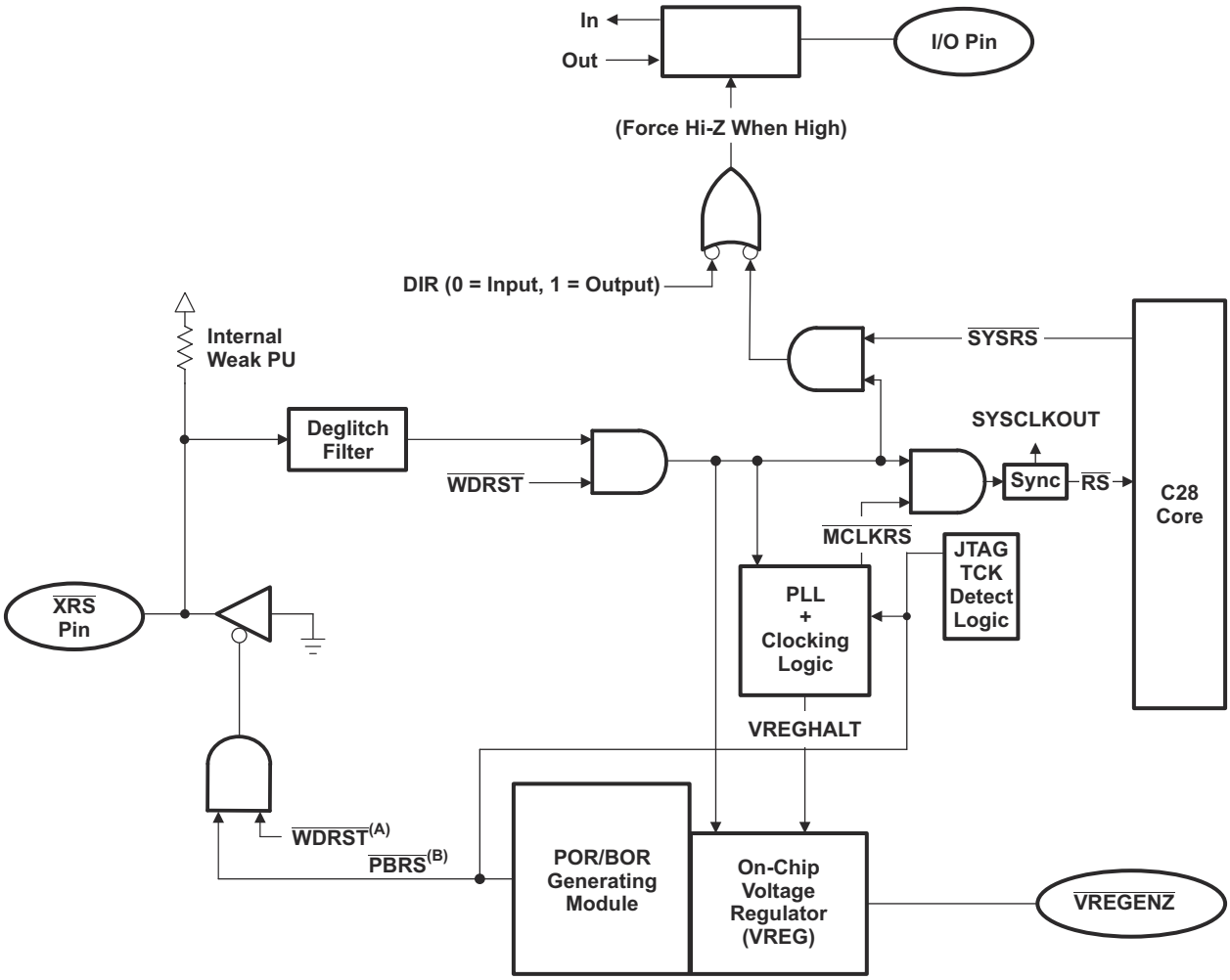
要使用片上 VREG，$\overline{\text{VREGENZ}}$ 引脚应连接至低电平并且将建议的适当工作电压应用于 V_{DDIO} 和 V_{DDA} 引脚。在这种情况下，内核逻辑所需的 V_{DD} 电压将由 VREG 生成。每个 V_{DD} 引脚需要 1.2 µF（最小值）级别的电容，以正确调节 VREG。这些电容器应尽可能靠近 V_{DD} 引脚。不支持使用内部 VREG 驱动外部负载。

9.5.1.2 禁用片载 VREG

为了节约能源，也可禁用片载 VREG 并使用一个效率更高的外部稳压器将内核逻辑电压提供给 V_{DD} 引脚。为了启用这个选项，$\overline{\text{VREGNZ}}$ 引脚必须被接至高电平。

9.5.2 On-chip Power-On Reset (POR) and Brown-Out Reset (BOR) Circuit

Two on-chip supervisory circuits, the power-on reset (POR) and the brown-out reset (BOR) remove the burden of monitoring the V_{DD} and V_{DDIO} supply rails from the application board. The purpose of the POR is to create a clean reset throughout the device during the entire power-up procedure. The trip point is a looser, lower trip point than the BOR, which watches for dips in the V_{DD} or V_{DDIO} rail during device operation. The POR function is present on both V_{DD} and V_{DDIO} rails at all times. After initial device power-up, the BOR function is present on V_{DDIO} at all times, and on V_{DD} when the internal VREG is enabled ($\overline{\text{VREGENZ}}$ pin is tied low). Both functions tie the $\overline{\text{XRS}}$ pin low when one of the voltages is below their respective trip point. V_{DD} BOR and overvoltage trip points are outside of the recommended operating voltages. Proper device operation cannot be ensured. If overvoltage or undervoltage conditions affecting the system is a concern for an application, an external voltage supervisor should be added. 图 9-6 shows the VREG, POR, and BOR. To disable both the V_{DD} and V_{DDIO} BOR functions, a bit is provided in the BORCFG register. For details, see the System Control chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.



A. $\overline{\text{WDRST}}$ is the reset signal from the CPU watchdog.
B. $\overline{\text{PBRS}}$ is the reset signal from the POR/BOR module.

图 9-6. VREG + POR + BOR + Reset Signal Connectivity

9.6 系统控制

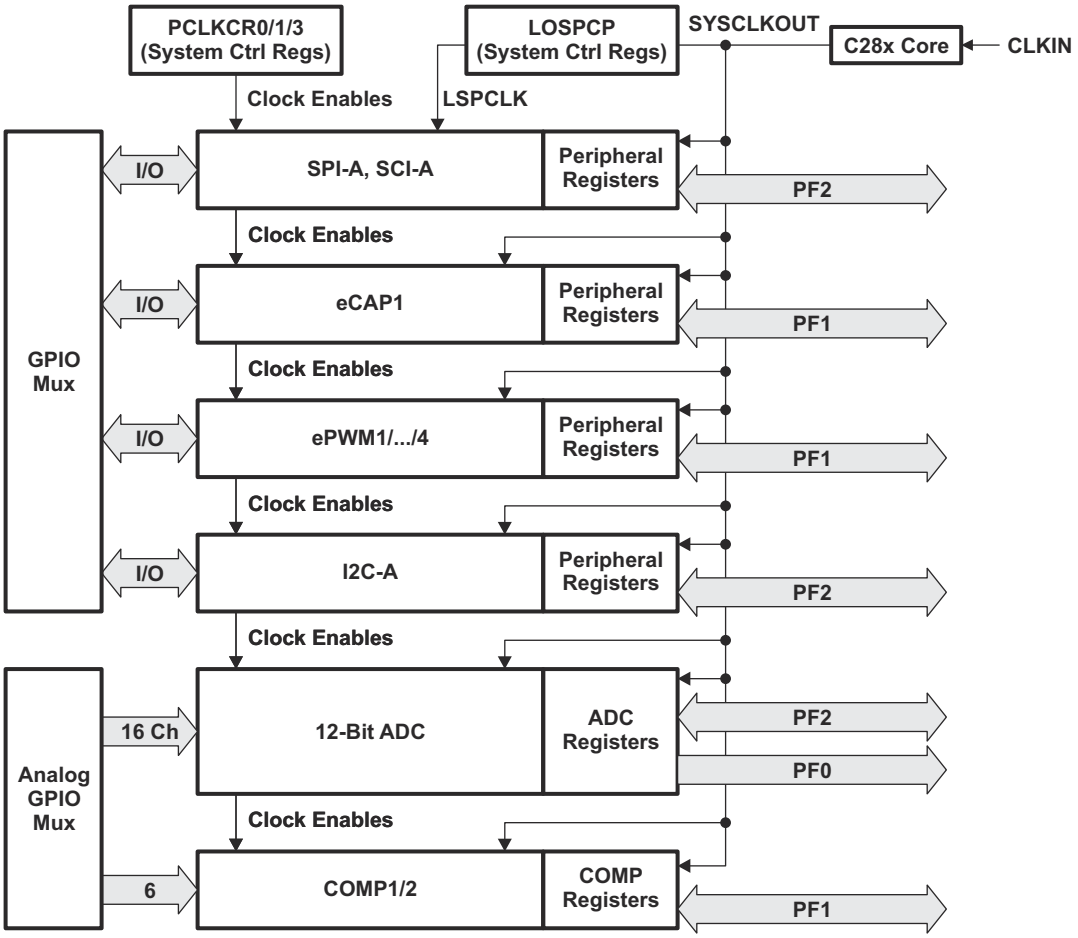
本部分介绍振荡器和时钟机制、看门狗功能以及低功率模式。

表 9-12. PLL、时钟、看门狗和低功率模式寄存器

名称	地址	大小 (x 16)	说明(1)
BORCFG	0x00 0985	1	BOR 配置寄存器
XCLK	0x00 7010	1	XCLKOUT 控制
PLLSTS	0x00 7011	1	PLL 状态寄存器
CLKCTL	0x00 7012	1	时钟控制寄存器
PLLLOCKPRD	0x00 7013	1	PLL 锁周期
INTOSC1TRIM	0x00 7014	1	内部振荡器 1 调整寄存器
INTOSC2TRIM	0x00 7016	1	内部振荡器 2 调整寄存器
LOSPCP	0x00 701B	1	低速外设时钟预分频器寄存器
PCLKCR0	0x00 701C	1	外设时钟控制寄存器 0
PCLKCR1	0x00 701D	1	外设时钟控制寄存器 1
LPMCR0	0x00 701E	1	低功耗模式控制寄存器 0
PCLKCR3	0x00 7020	1	外设时钟控制寄存器 3
PLLCR	0x00 7021	1	PLL 控制寄存器
SCSR	0x00 7022	1	系统控制与状态寄存器
WDCNTR	0x00 7023	1	看门狗计数器寄存器
WDKEY	0x00 7025	1	看门狗复位密钥寄存器
WDCR	0x00 7029	1	看门狗控制寄存器

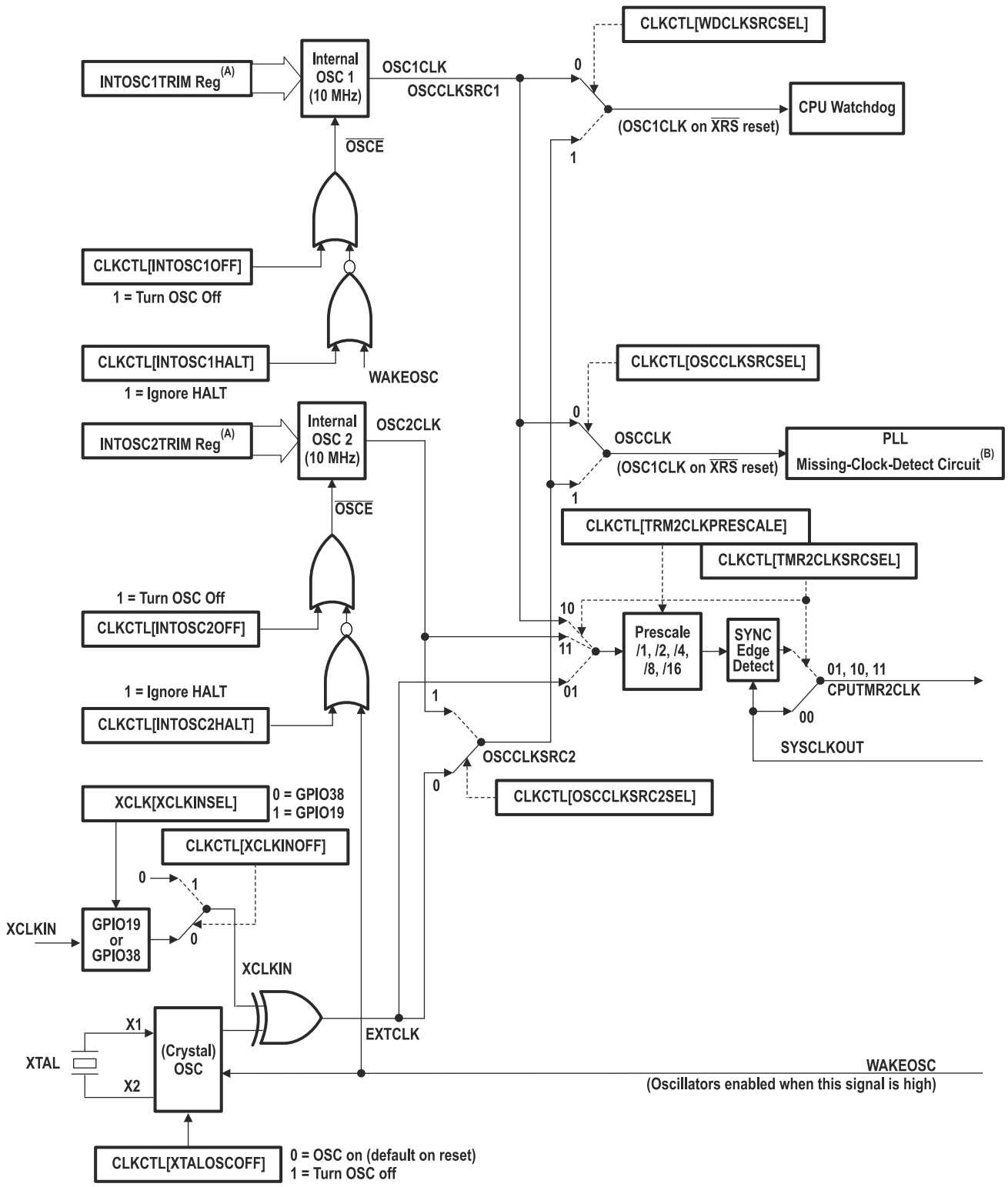
(1) 此表中的所有寄存器都受 EALLOW 保护。

图 9-7 显示了讨论的各种时钟域。图 9-8 显示了能够为器件运行提供时钟的各种时钟源（内部和外部）。



A. CLKIN 为 CPU 提供时钟。它作为 SYSCLKOUT 从 CPU 传出（也就是说，CLKIN 与 SYSCLKOUT 频率相同）。

图 9-7. 时钟和复位域



A. 从 TI 基于 OTP 的校准功能载入的寄存器。

B. 请参阅节 9.6.4 了解有关时钟缺失检测的详情。

图 9-8. 时钟树

9.6.1 内部零引脚振荡器

F2802x 器件包含两个独立的内部零引脚振荡器。缺省情况下，两个振荡器在加电时全都打开，此时，内部振荡器 1 是默认时钟源。为了节能，用户可将不使用的振荡器断电。这些振荡器的中心频率由它们各自的振荡器调整寄存器决定，此寄存器在校准例程中被写入作为引导 ROM 执行的一部分。有关这些振荡器的更多信息，请见节 8，电气规范。

9.6.2 Crystal Oscillator Option

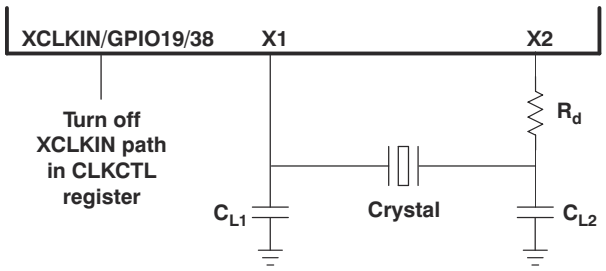
The on-chip crystal oscillator X1 and X2 pins are 1.8-V level signals and must never have 3.3-V level signals applied to them. If a system 3.3-V external oscillator is to be used as a clock source, it should be connected to the XCLKIN pin only. The X1 pin is not intended to be used as a single-ended clock input, it should be used with X2 and a crystal.

The typical specifications for the external quartz crystal (fundamental mode, parallel resonant) are listed in 表 9-13. Furthermore, ESR range = 30 to 150 Ω.

表 9-13. Typical Specifications for External Quartz Crystal(1)

FREQUENCY (MHz)	R_d (Ω)	C_{L1} (pF)	C_{L2} (pF)
5	2200	18	18
10	470	15	15
15	0	15	15
20	0	12	12

(1) C_{shunt} should be less than or equal to 5 pF.



A. X1/X2 pins are available in 48-pin package only.

图 9-9. Using the On-chip Crystal Oscillator

备注

1. C_{L1} and C_{L2} are the total capacitance of the circuit board and components excluding the IC and crystal. The value is usually approximately twice the value of the crystal's load capacitance.
2. The load capacitance of the crystal is described in the crystal specifications of the manufacturers.
3. TI recommends that customers have the resonator/crystal vendor characterize the operation of their device with the MCU chip. The resonator/crystal vendor has the equipment and expertise to tune the tank circuit. The vendor can also advise the customer regarding the proper tank component values that will produce proper start-up and stability over the entire operating range.

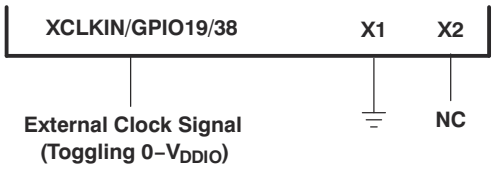


图 9-10. Using a 3.3-V External Oscillator

9.6.3 PLL-Based Clock Module

The devices have an on-chip, PLL-based clock module. This module provides all the necessary clocking signals for the device, as well as control for low-power mode entry. The PLL has a 4-bit ratio control PLLCR[DIV] to select different CPU clock rates. The watchdog module should be disabled before writing to the PLLCR register. It can be re-enabled (if need be) after the PLL module has stabilized, which takes
1 ms. The input clock and PLLCR[DIV] bits should be chosen in such a way that the output frequency of the PLL (VCOCLK) is at least 50 MHz.

表 9-14. PLL Settings

PLLCR[DIV] VALUE(2) (3)	SYSCLKOUT (CLKIN)		
	PLLSTS[DIVSEL] = 0 or 1(1)	PLLSTS[DIVSEL] = 2	PLLSTS[DIVSEL] = 3
0000 (PLL bypass)	OSCCLK/4 (Default)(2)	OSCCLK/2	OSCCLK
0001	(OSCCLK * 1)/4	(OSCCLK * 1)/2	(OSCCLK * 1)/1
0010	(OSCCLK * 2)/4	(OSCCLK * 2)/2	(OSCCLK * 2)/1
0011	(OSCCLK * 3)/4	(OSCCLK * 3)/2	(OSCCLK * 3)/1
0100	(OSCCLK * 4)/4	(OSCCLK * 4)/2	(OSCCLK * 4)/1
0101	(OSCCLK * 5)/4	(OSCCLK * 5)/2	(OSCCLK * 5)/1
0110	(OSCCLK * 6)/4	(OSCCLK * 6)/2	(OSCCLK * 6)/1
0111	(OSCCLK * 7)/4	(OSCCLK * 7)/2	(OSCCLK * 7)/1
1000	(OSCCLK * 8)/4	(OSCCLK * 8)/2	(OSCCLK * 8)/1
1001	(OSCCLK * 9)/4	(OSCCLK * 9)/2	(OSCCLK * 9)/1
1010	(OSCCLK * 10)/4	(OSCCLK * 10)/2	(OSCCLK * 10)/1
1011	(OSCCLK * 11)/4	(OSCCLK * 11)/2	(OSCCLK * 11)/1
1100	(OSCCLK * 12)/4	(OSCCLK * 12)/2	(OSCCLK * 12)/1

(1) By default, PLLSTS[DIVSEL] is configured for /4. (The boot ROM changes this to /1.) PLLSTS[DIVSEL] must be 0 before writing to the PLLCR and should be changed only after PLLSTS[PLLLOCKS] = 1.
(2) The PLL control register (PLLCR) and PLL Status Register (PLLSTS) are reset to their default state by the $\overline{\text{XRS}}$ signal or a watchdog reset only. A reset issued by the debugger or the missing clock detect logic has no effect.
(3) This register is EALLOW protected. See the System Control chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual* for more information.

表 9-15. CLKIN Divide Options

PLLSTS [DIVSEL]	CLKIN DIVIDE
0	/4
1	/4
2	/2
3	/1

The PLL-based clock module provides four modes of operation:

- **INTOSC1 (Internal Zero-pin Oscillator 1):** This is the on-chip internal oscillator 1. This can provide the clock for the Watchdog block, core and CPU-Timer 2
- **INTOSC2 (Internal Zero-pin Oscillator 2):** This is the on-chip internal oscillator 2. This can provide the clock for the Watchdog block, core and CPU-Timer 2. Both INTOSC1 and INTOSC2 can be independently chosen for the Watchdog block, core and CPU-Timer 2.
- **Crystal/Resonator Operation:** The on-chip (crystal) oscillator enables the use of an external crystal/ resonator attached to the device to provide the time base. The crystal/resonator is connected to the X1/X2 pins. Some devices may not have the X1/X2 pins. See 节 7.2.1 for details.
- **External Clock Source Operation:** If the on-chip (crystal) oscillator is not used, this mode allows it to be bypassed. The device clocks are generated from an external clock source input on the XCLKIN pin. The XCLKIN is multiplexed with GPIO19 or GPIO38 pin. The XCLKIN input can be selected as GPIO19 or GPIO38 through the XCLKINSEL bit in XCLK register. The CLKCTL[XCLKINOFF] bit disables this clock input (forced low). If the clock source is not used or the respective pins are used as GPIOs, the user should disable at boot time.

Before changing clock sources, ensure that the target clock is present. If a clock is not present, then that clock source must be disabled (using the CLKCTL register) before switching clocks.

表 9-16. Possible PLL Configuration Modes

PLL MODE	REMARKS	PLLSTS[DIVSEL]	CLKIN AND SYSCLKOUT
PLL Off	Invoked by the user setting the PLLOFF bit in the PLLSTS register. The PLL block is disabled in this mode. This can be useful to reduce system noise and for low-power operation. The PLLCR register must first be set to 0x0000 (PLL Bypass) before entering this mode. The CPU clock (CLKIN) is derived directly from the input clock on either X1/X2, X1 or XCLKIN.	0, 1 2 3	OSCCLK/4 OSCCLK/2 OSCCLK/1
PLL Bypass	PLL Bypass is the default PLL configuration upon power-up or after an external reset ($\overline{\text{XRS}}$). This mode is selected when the PLLCR register is set to 0x0000 or while the PLL locks to a new frequency after the PLLCR register has been modified. In this mode, the PLL is bypassed but the PLL is not turned off.	0, 1 2 3	OSCCLK/4 OSCCLK/2 OSCCLK/1
PLL Enable	Achieved by writing a nonzero value n into the PLLCR register. Upon writing to the PLLCR the device will switch to PLL Bypass mode until the PLL locks.	0, 1 2 3	OSCCLK * n/4 OSCCLK * n/2 OSCCLK * n/1

9.6.4 输入时钟的损耗 (NMI 看门狗功能)

2802x 器件可由两个内部零引脚振荡器 (INTOSC1/INTOSC2) 的其中任一个、片上晶体振荡器、或者一个外部时钟输入提供时钟信号。无论时钟源是什么，在 PLL 启用和 PLL 旁路模式中，如果到 PLL 的输入时钟消失，PLL 将在其输出上发出一个跛行模式时钟。这个跛行模式时钟持续为 CPU 和外设提供一个典型值为 1-5MHz 的时钟。

当跛行模式被激活时，一个被锁存为 NMI 中断的 $\overline{\text{CLOCLFAIL}}$ 信号被生成。根据 NMIRESETSEL 位的配置方式，器件复位可能会被立即触发或者 NMI 看门狗计数器溢出时发出复位。除此之外，会设置丢失时钟状态 (MCLKSTS) 位。应用可使用 NMI 中断来检测输入时钟故障并启动所需的校正操作，例如切换到另一个时钟源 (如果有的话) 或者为系统启动一个关断过程。

如果软件对于时钟故障情况没有响应，NMI 看门狗将在一个预编程的时间间隔后触发复位。图 9-11 显示了涉及的中断机制。

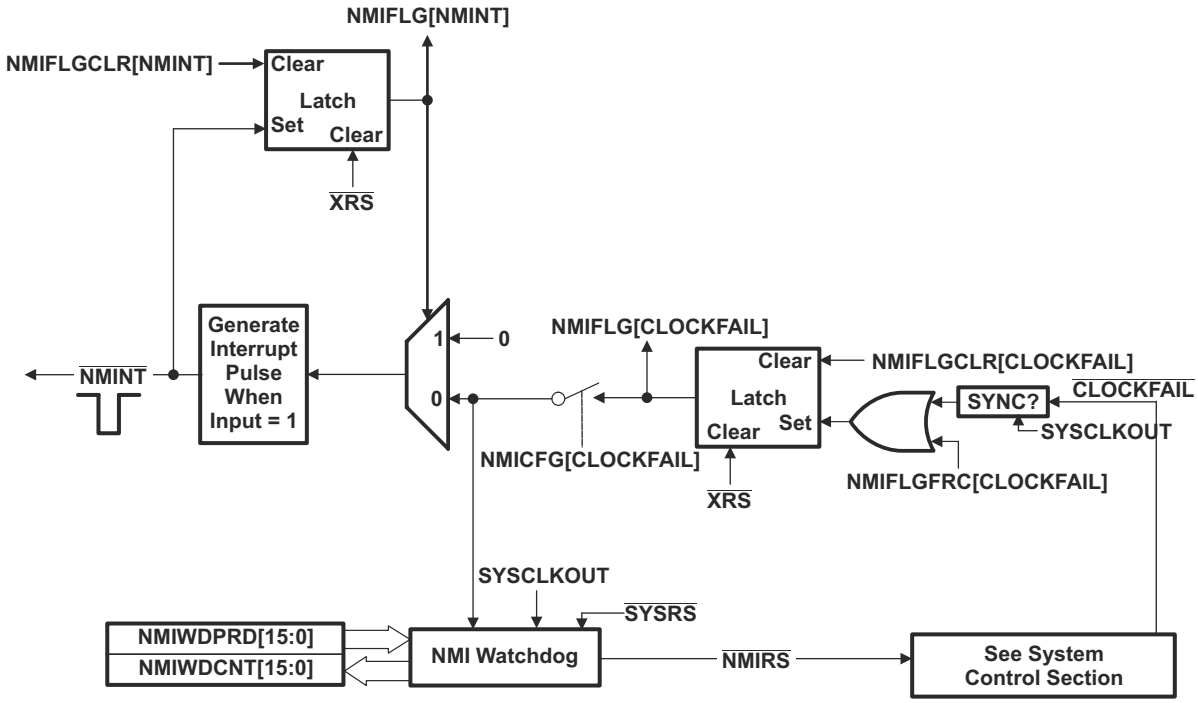


图 9-11. NMI 看门狗

9.6.5 CPU 看门狗模块

2802x 器件上的 CPU 看门狗模块与 281x/280x/283x 器件上所使用的类似。只要 8 位看门狗递增计数器达到了它的最大值，这个模块就生成一个输出脉冲，512 振荡器时钟宽度 (OSCCLK)。为防止这一情况，用户必须禁用计数器，或者软件必须定期向看门狗键值寄存器写入一个 0x55 + 0xAA 序列，用于复位看门狗计数器。图 9-12 显示了看门狗模块内的各种功能块。

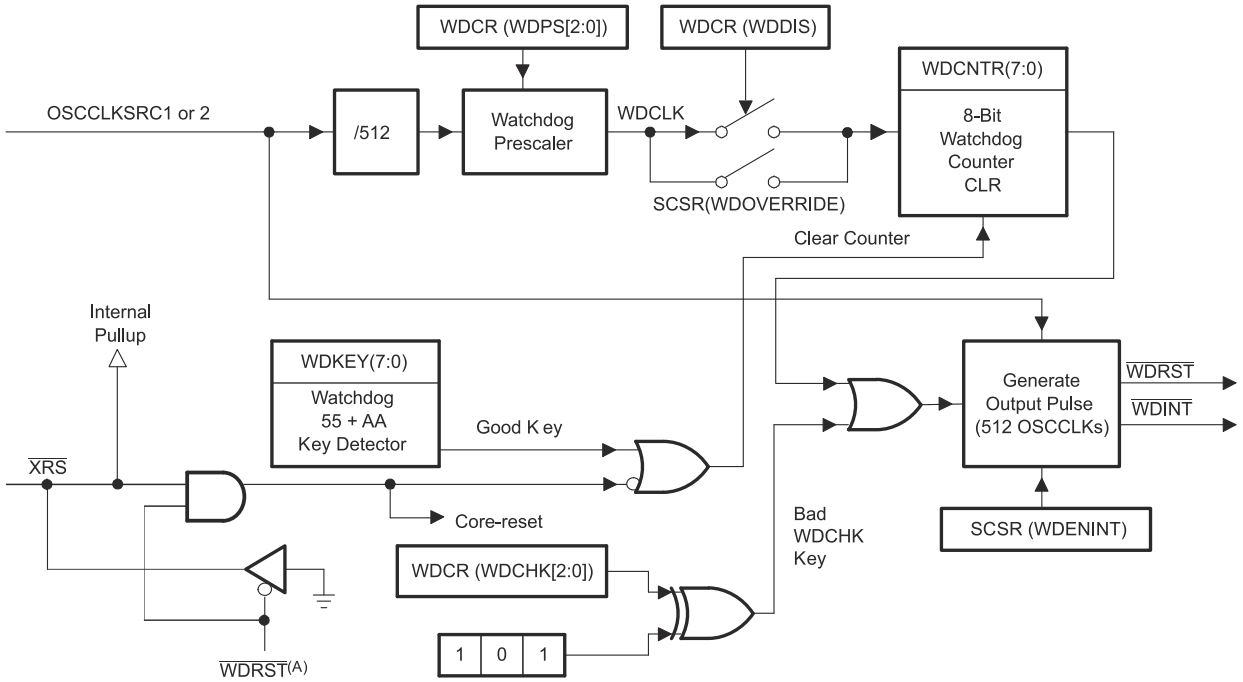
通常情况下，当输入时钟出现时，CPU 看门狗计数器会递减，以便启动 CPU 看门狗复位或 WDINT 中断。但是，当外部输入时钟故障时，CPU 看门狗计数器会停止递减（即看门狗计数器不随跛行模式时钟而变化）。

备注

CPU 看门狗与 NMI 看门狗不同。它是出现在所有 28x 器件中的老版看门狗。

备注

在正确 CPU 运行频率绝对关键的应用中应该执行一个机制，通过这个机制，只要输入时钟出现故障，MCU 就被保持在复位状态。例如，只要电容器充满电，一个 R-C 电路可被用于触发 MCU 的 $\overline{\text{XRS}}$ 引脚。一个 I/O 引脚可被用于定期为电容器放电以防止其被完全充满。这样一个电路也有助于检测闪存存储器的故障。



A. $\overline{\text{WDRST}}$ 信号在 512 个 OSCCLK 周期内被驱动为低电平。

图 9-12. CPU 看门狗模块

$\overline{\text{WDINT}}$ 信号支持使用看门狗从空闲/待机模式唤醒。

在待机模式中，器件上的所有外设关闭。唯一保持正常运行的外设是 CPU 看门狗。这个模块将关闭 OSCCLK。$\overline{\text{WDINT}}$ 信号被馈送到 LPM 块以便它可以将器件从待机唤醒（如已启用）。请参阅节 9.7 低功耗模式块，了解更多详细信息。

在空闲模式下，$\overline{\text{WDINT}}$ 信号可通过 PIE 对 CPU 生成一个中断，以便使 CPU 退出空闲模式。

在停机模式下，CPU 看门狗可用来通过器件复位唤醒器件。

9.7 Low-power Modes Block

表 9-17 summarizes the various modes.

表 9-17. Low-power Modes

MODE	LPMCR0(1:0)	OSCCLK	CLKIN	SYSCLKOUT	EXIT(1)
IDLE	00	On	On	On	$\overline{\text{XRS}}$, CPU watchdog interrupt, any enabled interrupt
STANDBY	01	On (CPU watchdog still running)	Off	Off	$\overline{\text{XRS}}$, CPU watchdog interrupt, GPIO Port A signal, debugger(2)
HALT(3)	1X	Off (on-chip crystal oscillator and PLL turned off, zero-pin oscillator and CPU watchdog state dependent on user code.)	Off	Off	$\overline{\text{XRS}}$, GPIO Port A signal, debugger(2), CPU watchdog

(1) The EXIT column lists which signals or under what conditions the low-power mode is exited. A low signal, on any of the signals, exits the low-power condition. This signal must be kept low long enough for an interrupt to be recognized by the device. Otherwise, the low-power mode will not be exited and the device will go back into the indicated low-power mode.
(2) The JTAG port can still function even if the CPU clock (CLKIN) is turned off.
(3) The WDCLK must be active for the device to go into HALT mode.

The various low-power modes operate as follows:

IDLE Mode: This mode is exited by any enabled interrupt that is recognized by the processor. The LPM block performs no tasks during this mode as long as the LPMCR0(LPM) bits are set to 0,0.

STANDBY Mode: Any GPIO port A signal (GPIO[31:0]) can wake the device from STANDBY mode. The user must select which signal(s) will wake the device in the GPIOLPMSEL register. The selected signal(s) are also qualified by the OSCCLK before waking the device. The number of OSCCLKs is specified in the LPMCR0 register.

HALT Mode: CPU watchdog, $\overline{\text{XRS}}$, and any GPIO port A signal (GPIO[31:0]) can wake the device from HALT mode. The user selects the signal in the GPIOLPMSEL register.

备注

The low-power modes do not affect the state of the output pins (PWM pins included). They will be in whatever state the code left them in when the IDLE instruction was executed. See the System Control chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual* for more details.

9.8 Interrupts

图 9-13 shows how the various interrupt sources are multiplexed.

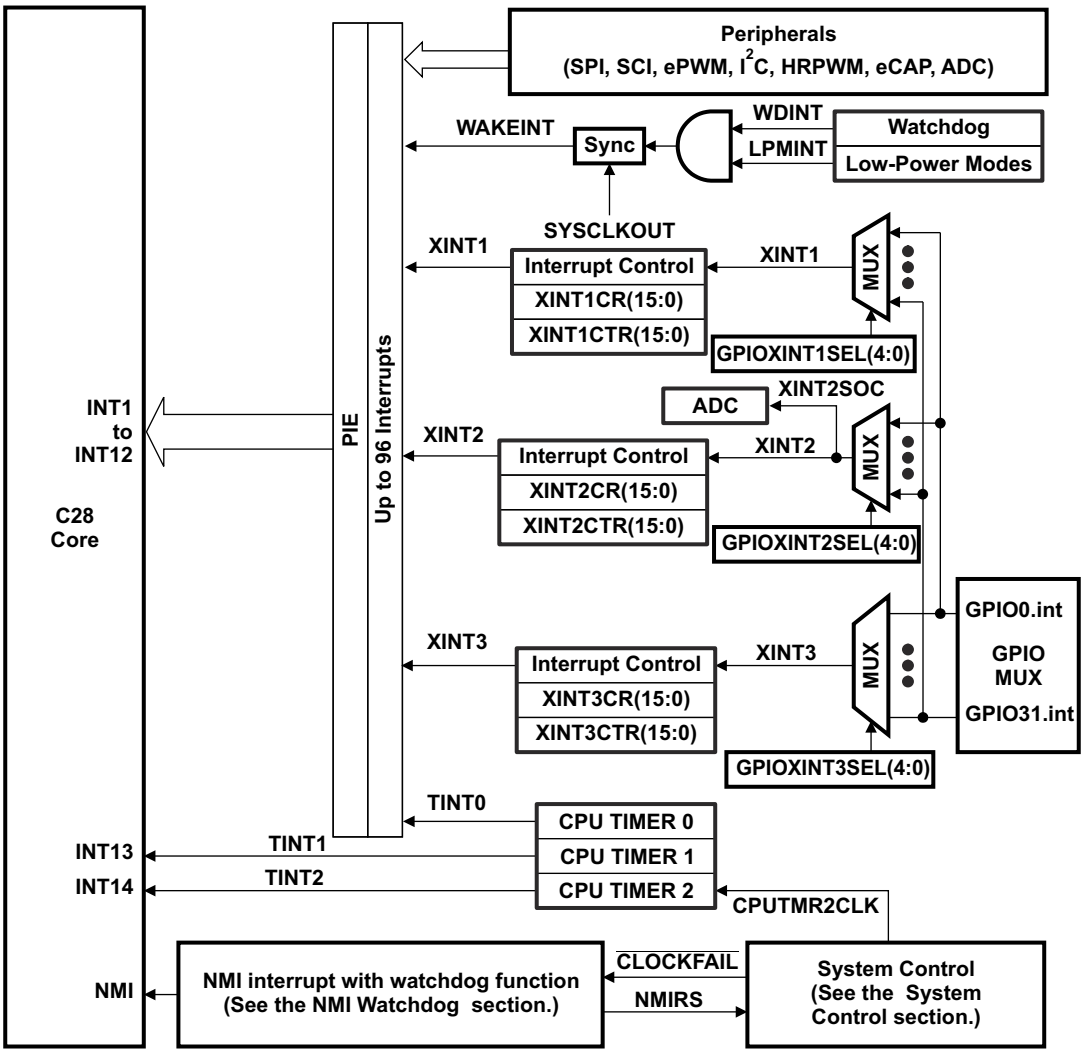


图 9-13. External and PIE Interrupt Sources

Eight PIE block interrupts are grouped into one CPU interrupt. In total, 12 CPU interrupt groups, with 8 interrupts per group equals 96 possible interrupts. 表 9-18 shows the interrupts used by 2802x devices.

The TRAP #VectorNumber instruction transfers program control to the interrupt service routine corresponding to the vector specified. The TRAP #0 instruction attempts to transfer program control to the address pointed to by the reset vector. The PIE vector table does not, however, include a reset vector. Therefore, the TRAP #0 instruction should not be used when the PIE is enabled. Doing so will result in undefined behavior.

When the PIE is enabled, the TRAP #1 to TRAP #12 instructions will transfer program control to the interrupt service routine corresponding to the first vector within the PIE group. For example: the TRAP #1 instruction fetches the vector from INT1.1, the TRAP #2 instruction fetches the vector from INT2.1, and so forth.

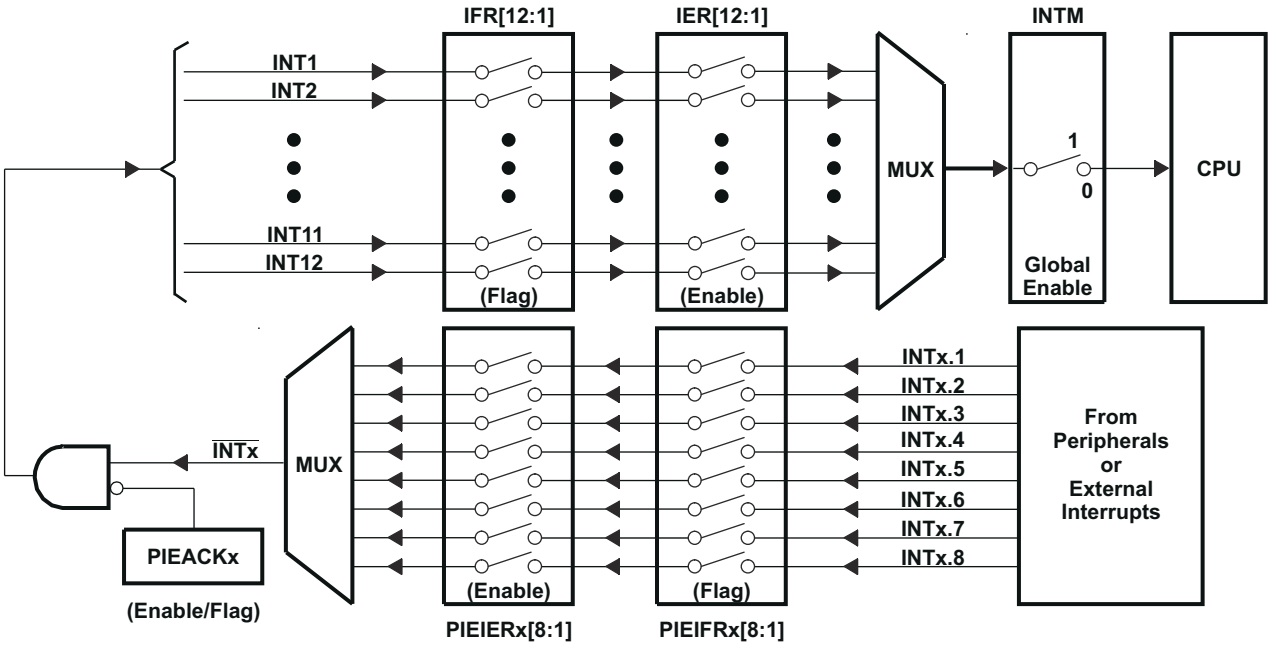


图 9-14. Multiplexing of Interrupts Using the PIE Block

表 9-18. PIE MUXed Peripheral Interrupt Vector Table

	INTx.8[1]	INTx.7	INTx.6	INTx.5	INTx.4	INTx.3	INTx.2	INTx.1
INT1.y	WAKEINT (LPM/WD) 0xD4E	TINT0 (TIMER 0) 0xD4C	ADCINT9 (ADC) 0xD4A	XINT2 Ext. int. 2 0xD48	XINT1 Ext. int. 1 0xD46	Reserved – 0xD44	ADCINT2 (ADC) 0xD42	ADCINT1 (ADC) 0xD40
INT2.y	Reserved – 0xD5E	Reserved – 0xD5C	Reserved – 0xD5A	Reserved – 0xD58	EPWM4_TZINT (ePWM4) 0xD56	EPWM3_TZINT (ePWM3) 0xD54	EPWM2_TZINT (ePWM2) 0xD52	EPWM1_TZINT (ePWM1) 0xD50
INT3.y	Reserved – 0xD6E	Reserved – 0xD6C	Reserved – 0xD6A	Reserved – 0xD68	EPWM4_INT (ePWM4) 0xD66	EPWM3_INT (ePWM3) 0xD64	EPWM2_INT (ePWM2) 0xD62	EPWM1_INT (ePWM1) 0xD60
INT4.y	Reserved – 0xD7E	Reserved – 0xD7C	Reserved – 0xD7A	Reserved – 0xD78	Reserved – 0xD76	Reserved – 0xD74	Reserved – 0xD72	ECAP1_INT (eCAP1) 0xD70
INT5.y	Reserved – 0xD8E	Reserved – 0xD8C	Reserved – 0xD8A	Reserved – 0xD88	Reserved – 0xD86	Reserved – 0xD84	Reserved – 0xD82	Reserved – 0xD80
INT6.y	Reserved – 0xD9E	Reserved – 0xD9C	Reserved – 0xD9A	Reserved – 0xD98	Reserved – 0xD96	Reserved – 0xD94	SPITXINTA (SPI-A) 0xD92	SPIRXINTA (SPI-A) 0xD90
INT7.y	Reserved – 0xDAE	Reserved – 0xDAC	Reserved – 0xDAA	Reserved – 0xDA8	Reserved – 0xDA6	Reserved – 0xDA4	Reserved – 0xDA2	Reserved – 0xDA0
INT8.y	Reserved – 0xDBE	Reserved – 0xDBC	Reserved – 0xDBA	Reserved – 0xDB8	Reserved – 0xDB6	Reserved – 0xDB4	I2CINT2A (I2C-A) 0xDB2	I2CINT1A (I2C-A) 0xDB0
INT9.y	Reserved – 0xDCE	Reserved – 0xDCC	Reserved – 0xDCA	Reserved – 0xDC8	Reserved – 0xDC6	Reserved – 0xDC4	SCITXINTA (SCI-A) 0xDC2	SCIRXINTA (SCI-A) 0xDC0
INT10.y	ADCINT8 (ADC) 0xDDE	ADCINT7 (ADC) 0xDDC	ADCINT6 (ADC) 0xDDA	ADCINT5 (ADC) 0xDD8	ADCINT4 (ADC) 0xDD6	ADCINT3 (ADC) 0xDD4	ADCINT2 (ADC) 0xDD2	ADCINT1 (ADC) 0xDD0
INT11.y	Reserved – 0xDEE	Reserved – 0xDEC	Reserved – 0xDEA	Reserved – 0xDE8	Reserved – 0xDE6	Reserved – 0xDE4	Reserved – 0xDE2	Reserved – 0xDE0
INT12.y	Reserved – 0xDFE	Reserved – 0xDFC	Reserved – 0xDFA	Reserved – 0xDF8	Reserved – 0xDF6	Reserved – 0xDF4	Reserved – 0xDF2	XINT3 Ext. Int. 3 0xDF0

(1) Out of 96 possible interrupts, some interrupts are not used. These interrupts are reserved for future devices. These interrupts can be used as software interrupts if they are enabled at the PIEIFRx level, provided none of the interrupts within the group is being used by a peripheral. Otherwise, interrupts coming in from peripherals may be lost by accidentally clearing their flag while modifying the PIEIFR. To summarize, there are two safe cases when the reserved interrupts could be used as software interrupts:

a. No peripheral within the group is asserting interrupts.

b. No peripheral interrupts are assigned to the group (for example, PIE groups 5, 7, or 11) .

表 9-19. PIE Configuration and Control Registers

NAME	ADDRESS	SIZE (x16)	DESCRIPTION(1)
PIECTRL	0x0CE0	1	PIE, Control Register
PIEACK	0x0CE1	1	PIE, Acknowledge Register
PIEIER1	0x0CE2	1	PIE, INT1 Group Enable Register
PIEIFR1	0x0CE3	1	PIE, INT1 Group Flag Register
PIEIER2	0x0CE4	1	PIE, INT2 Group Enable Register
PIEIFR2	0x0CE5	1	PIE, INT2 Group Flag Register
PIEIER3	0x0CE6	1	PIE, INT3 Group Enable Register
PIEIFR3	0x0CE7	1	PIE, INT3 Group Flag Register
PIEIER4	0x0CE8	1	PIE, INT4 Group Enable Register
PIEIFR4	0x0CE9	1	PIE, INT4 Group Flag Register
PIEIER5	0x0CEA	1	PIE, INT5 Group Enable Register
PIEIFR5	0x0CEB	1	PIE, INT5 Group Flag Register
PIEIER6	0x0CEC	1	PIE, INT6 Group Enable Register
PIEIFR6	0x0CED	1	PIE, INT6 Group Flag Register
PIEIER7	0x0CEE	1	PIE, INT7 Group Enable Register
PIEIFR7	0x0CEF	1	PIE, INT7 Group Flag Register
PIEIER8	0x0CF0	1	PIE, INT8 Group Enable Register
PIEIFR8	0x0CF1	1	PIE, INT8 Group Flag Register
PIEIER9	0x0CF2	1	PIE, INT9 Group Enable Register
PIEIFR9	0x0CF3	1	PIE, INT9 Group Flag Register
PIEIER10	0x0CF4	1	PIE, INT10 Group Enable Register
PIEIFR10	0x0CF5	1	PIE, INT10 Group Flag Register
PIEIER11	0x0CF6	1	PIE, INT11 Group Enable Register
PIEIFR11	0x0CF7	1	PIE, INT11 Group Flag Register
PIEIER12	0x0CF8	1	PIE, INT12 Group Enable Register
PIEIFR12	0x0CF9	1	PIE, INT12 Group Flag Register
Reserved	0x0CFA – 0x0CFF	6	Reserved

(1) The PIE configuration and control registers are not protected by EALLOW mode. The PIE vector table is protected.

9.8.1 External Interrupts

表 9-20. External Interrupt Registers

NAME	ADDRESS	SIZE (x16)	DESCRIPTION
XINT1CR	0x00 7070	1	XINT1 configuration register
XINT2CR	0x00 7071	1	XINT2 configuration register
XINT3CR	0x00 7072	1	XINT3 configuration register
XINT1CTR	0x00 7078	1	XINT1 counter register
XINT2CTR	0x00 7079	1	XINT2 counter register
XINT3CTR	0x00 707A	1	XINT3 counter register

Each external interrupt can be enabled/disabled or qualified using positive, negative, or both positive and negative edge. For more information, see the System Control chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

9.8.1.1 外部中断电子数据/定时

9.8.1.1.1 External Interrupt Timing Requirements

			MIN(1)	MAX	UNIT
$t_{w(INT)}$ (2)	Pulse duration, INT input low/high	Synchronous	$1t_{c(SCO)}$		cycles
		With qualifier	$1t_{c(SCO)} + t_{w(IQSW)}$		cycles

(1) For an explanation of the input qualifier parameters, see 节 9.9.10.1.2.1.
(2) This timing is applicable to any GPIO pin configured for ADCSOC functionality.

9.8.1.1.2 External Interrupt Switching Characteristics

over recommended operating conditions (unless otherwise noted)

PARAMETER		MIN(1)	MAX	UNIT
$t_{d(INT)}$	Delay time, INT low/high to interrupt-vector fetch		$t_{w(IQSW)} + 12t_{c(SCO)}$	cycles

(1) For an explanation of the input qualifier parameters, see 节 9.9.10.1.2.1.

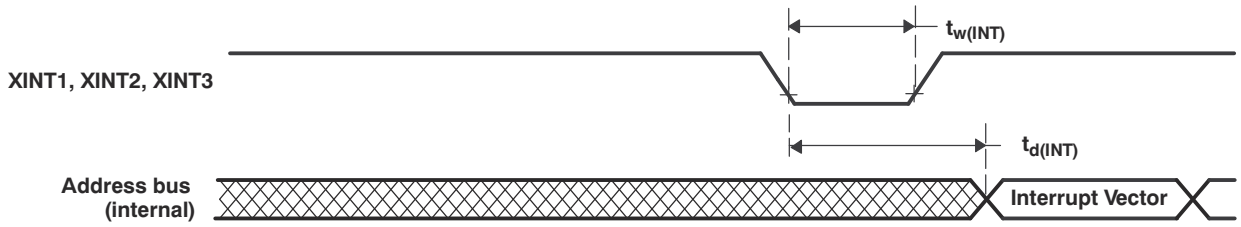


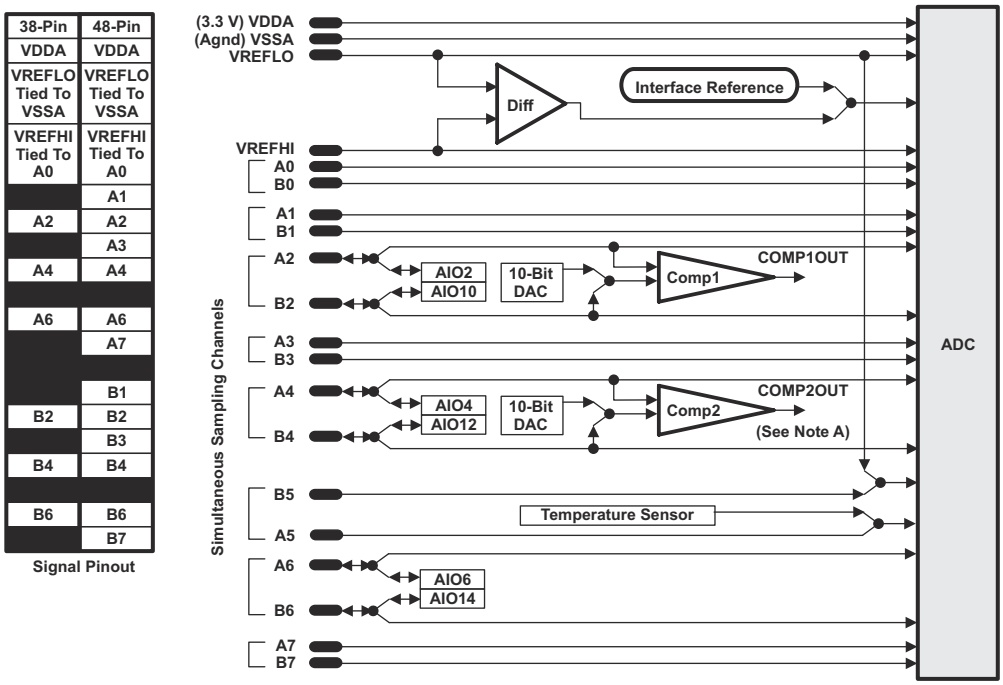
图 9-15. External Interrupt Timing

9.9 外设

9.9.1 Analog Block

A 12-bit ADC core is implemented that has different timings than the 12-bit ADC used on F280x/F2833x. The ADC wrapper is modified to incorporate the new timings and also other enhancements to improve the timing control of start of conversions. 图 9-16 shows the interaction of the analog module with the rest of the F2802x system.

For more information on the ADC, see the Analog-to-Digital Converter and Comparator chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.



A. Comparator 2 is available only on the 48-pin PT package.

图 9-16. Analog Pin Configurations

9.9.1.1 模数转换器 (ADC)

9.9.1.1.1 特性

ADC 的内核包含有一个单一 12 位转换器，此转换器由两个采样保持电路供源。可以对这两个采样保持电路进行同步采样或顺序采样。按顺序，这些电路由总共高达 13 个模拟输入通道供源。此转换器可配置为采用内部带隙基准运行，以便形成基于实际电压的转换，或者采用一对外部电压基准 (V_{REFHI}/V_{REFLO}) 运行，形成基于比率的转换。

与之前的 ADC 类型不同，此 ADC 并非基于序列发生器。对于用户来讲，他们可以很容易地从一个单触发来创建一系列的转换。然而，操作的基本原则是以单个转换的配置为中心，被称为 SOC，或者转换启动。

ADC 模块的功能包括：

- 具有内置双采样保持 (S/H) 的 12 位 ADC 内核
- 同步采样模式或顺序采样模式
- 全范围模拟输入：0V 至 3.3V 固定电压，或 V_{REFHI}/V_{REFLO} 比率。输入模拟电压的数值源自：
  - 内部基准（$V_{REFLO}=V_{SSA}$。当使用内部或者外部基准模式时，V_{REFHI} 不得超过 V_{DDA}。）

$$\text{Digital Value} = 0, \quad \text{when input} \le 0\ \text{V}$$

$$\text{Digital Value} = 4096 \times \frac{\text{Input Analog Voltage} - V_{REFLO}}{3.3}, \quad \text{when } 0\ \text{V} < \text{input} < 3.3\ \text{V}$$

$$\text{Digital Value} = 4095, \quad \text{when input} \ge 3.3\ \text{V}$$

  - 外部基准（V_{REFHI}/V_{REFLO} 被连接至外部基准。当使用内部或者外部基准模式时，V_{REFHI} 不得超过 V_{DDA}。）

$$\text{Digital Value} = 0, \quad \text{when input} \le 0\ \text{V}$$

$$\text{Digital Value} = 4096 \times \frac{\text{Input Analog Voltage} - V_{REFLO}}{V_{REFHI} - V_{REFLO}}, \quad \text{when } 0\ \text{V} < \text{input} < V_{REFHI}$$

$$\text{Digital Value} = 4095, \quad \text{when input} \ge V_{REFHI}$$

- 多达 16 个通道，多路复用输入
- 16 个 SOC，可针对触发、采样窗口和通道进行配置
- 用于存储转换值的 16 个结果寄存器（可单独寻址）
- 多个触发源
  - S/W - 软件立即启动
  - ePWM 1-4
  - GPIO XINT2
  - CPU 计时器 0/1/2
  - ADCINT1/2
- 9 个灵活的 PIE 中断，可在任一个转换后配置中断请求

表 9-21. ADC 配置和控制寄存器

寄存器名称	地址	大小 (x16)	受 EALLOW 保护	说明
ADCCTL1	0x7100	1	是	控制 1 寄存器
ADCCTL2	0x7101	1	是	控制 2 寄存器
ADCINTFLG	0x7104	1	否	中断标志寄存器
ADCINTFLGCLR	0x7105	1	否	中断标志清除寄存器
ADCINTOVF	0x7106	1	否	中断溢出寄存器
ADCINTOVFCLR	0x7107	1	否	中断溢出清除寄存器
INTSEL1N2	0x7108	1	是	中断 1 和 2 选择寄存器
INTSEL3N4	0x7109	1	是	中断 3 和 4 选择寄存器
INTSEL5N6	0x710A	1	是	中断 5 和 6 选择寄存器
INTSEL7N8	0x710B	1	是	中断 7 和 8 选择寄存器
INTSEL9N10	0x710C	1	是	中断 9 选择寄存器 (被保留的中断 10 选择)
SOCPRICTL	0x7110	1	是	SOC 优先级控制寄存器
ADCSAMPLEMODE	0x7112	1	是	采样模式寄存器
ADCINTSOCSEL1	0x7114	1	是	中断 SOC 选择 1 寄存器 (用于 8 个通道)
ADCINTSOCSEL2	0x7115	1	是	中断 SOC 选择 2 寄存器 (用于 8 个通道)
ADCSOCFLG1	0x7118	1	否	SOC 标志 1 寄存器 (用于 16 个通道)
ADCSOCFRC1	0x711A	1	否	SOC 强制 1 寄存器 (用于 16 个通道)
ADCSOCOVF1	0x711C	1	否	SOC 溢出 1 寄存器 (用于 16 个通道)
ADCSOCOVFCLR1	0x711E	1	否	SOC 溢出清除 1 寄存器 (用于 16 个通道)
ADCSOC0CTL 至 ADCSOC15CTL	0x7120-0x712F	1	是	SOC0 控制寄存器至 SOC15 控制寄存器
ADCREFTRIM	0x7140	1	是	基准调整寄存器
ADCOFFTRIM	0x7141	1	是	偏移调整寄存器
COMPHYSTCTL	0x714C	1	是	比较器滞后控制寄存器
ADCREV	0x714F	1	否	修订版本寄存器

表 9-22. ADC 结果寄存器 (被映射至 PF0)

寄存器名称	地址	大小 (x16)	受 EALLOW 保护	说明
ADCRESULT0 至 ADCRESULT15	0xB00 至 0xB0F	1	否	ADC 结果 0 寄存器至 ADC 结果 15 寄存器

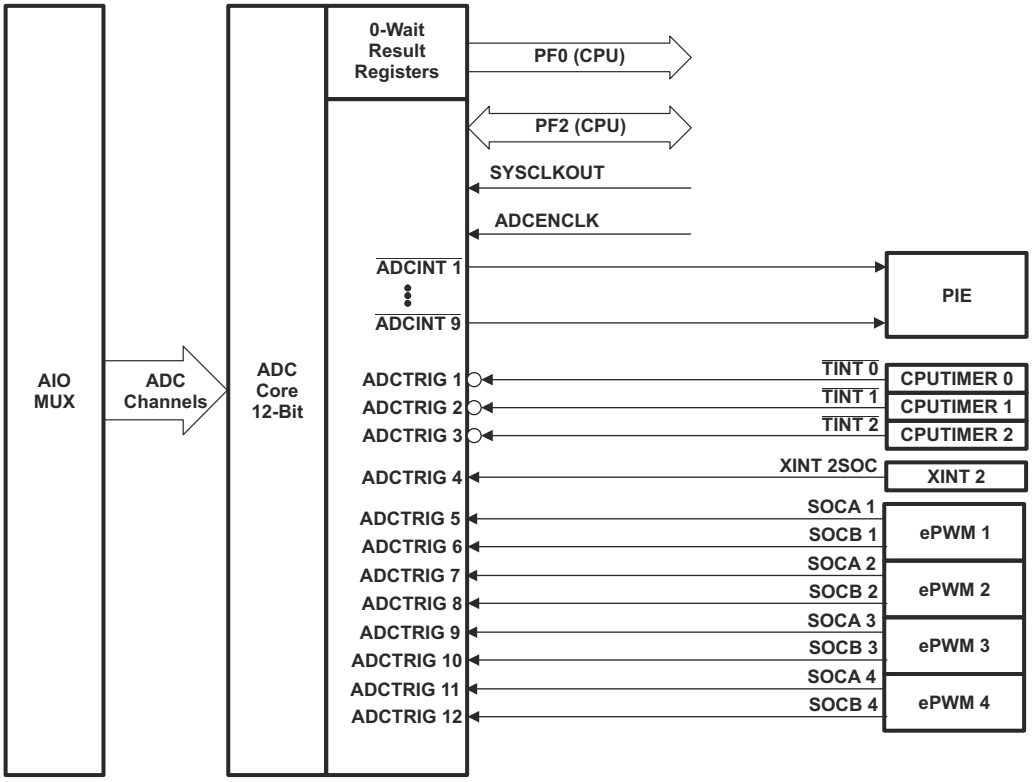


图 9-17. ADC 连接

不使用 ADC 时的 ADC 连接

TI 建议即使不使用 ADC，也应保持模拟电源引脚的连接。下面总结了如果 ADC 未在应用中使用，应该如何连接 ADC 引脚：

- V_{DDA} - 连接到 V_{DDIO}
- V_{SSA} - 连接到 V_{SS}
- V_{REFLO} - 连接到 V_{SS}
- ADCINAn，ADCINBn，V_{REFHI} - 连接到 V_{SSA}

当在一个应用中使用 ADC 模块时，未使用的 ADC 输入引脚应被连接至模拟接地 (V_{SSA})。

备注

与 AIO 功能复用的未使用 ADCIN 引脚不应直接连接到模拟地。它们应该通过一个 1kΩ 电阻器接地。这是为了防止一个错误代码将这些引脚配置为 AIO 输出并将接地的引脚驱动至一个逻辑高电平状态。

当 ADC 未被使用时，为了达到节能的目的，请确保到 ADC 模块的时钟未被打开。

9.9.1.1.2 ADC 转换开始电子数据/定时

9.9.1.1.2.1 外部 ADC 转换启动开关特性

在推荐的运行条件下 (除非另有说明)

参数		最小值	最大值	单位
$t_{w(ADCSOCL)}$	脉冲持续时间，$\overline{ADCSOCxO}$ 低电平的时间	$32t_{c(HCO)}$		周期

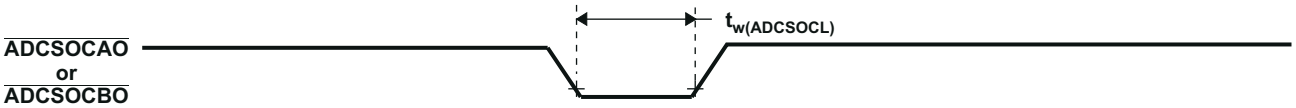


图 9-18. $\overline{ADCSOCAO}$ 或者 $\overline{ADCSOCBO}$ 时序

9.9.1.1.3 片载模数转换器 (ADC) 电子数据/定时

9.9.1.1.3.1 ADC Electrical Characteristics

PARAMETER		MIN	TYP	MAX	UNIT
DC SPECIFICATIONS					
Resolution		12			Bits
ADC clock	60-MHz device	0.001		60	MHz
Sample Window	28027/26/23/22	7		64	ADC Clocks
	28021/20/200	14		64	
ACCURACY					
INL (Integral nonlinearity) at ADC Clock ≤ 30 MHz(1)		–4		4	LSB
DNL (Differential nonlinearity) at ADC Clock ≤ 30 MHz, no missing codes		–1		1	LSB
Offset error (2)	Executing Device_Cal function	–20	0	20	LSB
	Executing periodic self-recalibration(3)	–4	0	4	
Overall gain error with internal reference		–60		60	LSB
Overall gain error with external reference		–40		40	LSB
Channel-to-channel offset variation		–4		4	LSB
Channel-to-channel gain variation		–4		4	LSB
ADC temperature coefficient with internal reference			–50		ppm/°C
ADC temperature coefficient with external reference			–20		ppm/°C
V_{REFLO}			–100		µA
V_{REFHI}			100		µA
ANALOG INPUT					
Analog input voltage with internal reference		0		3.3	V
Analog input voltage with external reference		V_{REFLO}		V_{REFHI}	V
V_{REFLO} input voltage(4)		V_{SSA}		V_{SSA}	V
V_{REFHI} input voltage(5)	with $V_{REFLO} = V_{SSA}$	1.98		V_{DDA}	V
Input capacitance			5		pF
Input leakage current			±5		µA

(1) INL will degrade when the ADC input voltage goes above V_{DDA}.
(2) 1 LSB has the weighted value of full-scale range (FSR)/4096. FSR is 3.3 V with internal reference and V_{REFHI} - V_{REFLO} for external reference.
(3) Periodic self-recalibration will remove system-level and temperature dependencies on the ADC zero offset error. This can be performed as needed in the application without sacrificing an ADC channel by using the procedure listed in the "ADC Zero Offset Calibration" section of the Analog-to-Digital Converter and Comparator chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.
(4) V_{REFLO} is always connected to V_{SSA} .
(5) V_{REFHI} must not exceed V_{DDA} when using either internal or external reference modes. Because V_{REFHI} is tied to ADCINA0 , the input signal on ADCINA0 must not exceed V_{DDA}.

9.9.1.1.3.2 ADC 电源模式

ADC 工作模式	条件	I_{DDA}	单位
模式 A - 工作模式	ADC 时钟启用 带隙开启 (ADCBGPWD = 1) 基准开启 (ADCREFPWD = 1) ADC 加电 (ADCPWDN = 1)	13	mA
模式 B - 快速唤醒模式	ADC 时钟启用 带隙开启 (ADCBGPWD = 1) 基准开启 (ADCREFPWD = 1) ADC 加电 (ADCPWDN = 0)	4	mA
模式 C - 仅比较器模式	ADC 时钟启用 带隙开启 (ADCBGPWD = 1) 基准开启 (ADCREFPWD = 0) ADC 加电 (ADCPWDN = 0)	1.5	mA
模式 D - 关闭模式	ADC 时钟启用 带隙开启 (ADCBGPWD = 0) 基准开启 (ADCREFPWD = 0) ADC 加电 (ADCPWDN = 0)	0.075	mA

9.9.1.1.3.3 内部温度传感器

9.9.1.1.3.3.1 Temperature Sensor Coefficient

PARAMETER(1)		MIN	TYP	MAX	UNIT
T_{SLOPE}	Degrees C of temperature movement per measured ADC LSB change of the temperature sensor		0.18(3) (2)		°C/LSB
T_{OFFSET}	ADC output at 0°C of the temperature sensor		1750		LSB

(1) The temperature sensor slope and offset are given in terms of ADC LSBs using the internal reference of the ADC. Values must be adjusted accordingly in external reference mode to the external reference voltage.
(2) Output of the temperature sensor (in terms of LSBs) is sign-consistent with the direction of the temperature movement. Increasing temperatures will give increasing ADC values relative to an initial value; decreasing temperatures will give decreasing ADC values relative to an initial value.
(3) ADC temperature coeffieicient is accounted for in this specification

9.9.1.1.3.4 ADC 加电控制位时序

9.9.1.1.3.4.1 ADC 加电延迟

参数(1)		最小值	最大值	单位
$t_{d(PWD)}$	加电后，ADC 的延迟时间将稳定		1	ms

(1) 时序保持与 ADC 模块的兼容性。在首次转换前 $t_{d(PWD)}$ ms，2802x ADC 支持同时驱动所有 3 个位。

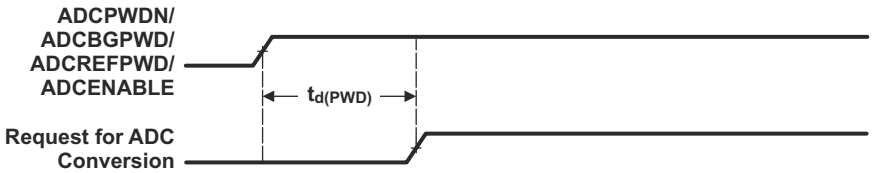
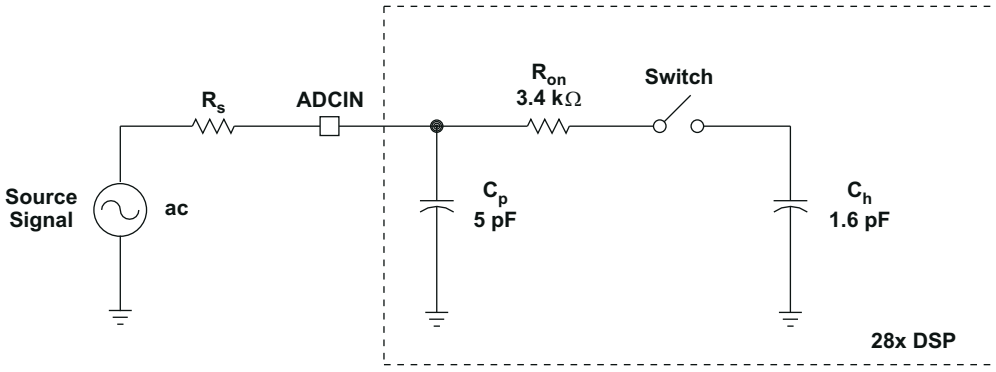


图 9-19. ADC 转换时序



Typical Values of the Input Circuit Components:

Switch Resistance (R_{on}): 3.4 kΩ
Sampling Capacitor (C_h): 1.6 pF
Parasitic Capacitance (C_p): 5 pF
Source Resistance (R_s): 50 Ω

图 9-20. ADC 输入阻抗模型

9.9.1.1.3.5 ADC 顺序模式时序和同步模式时序

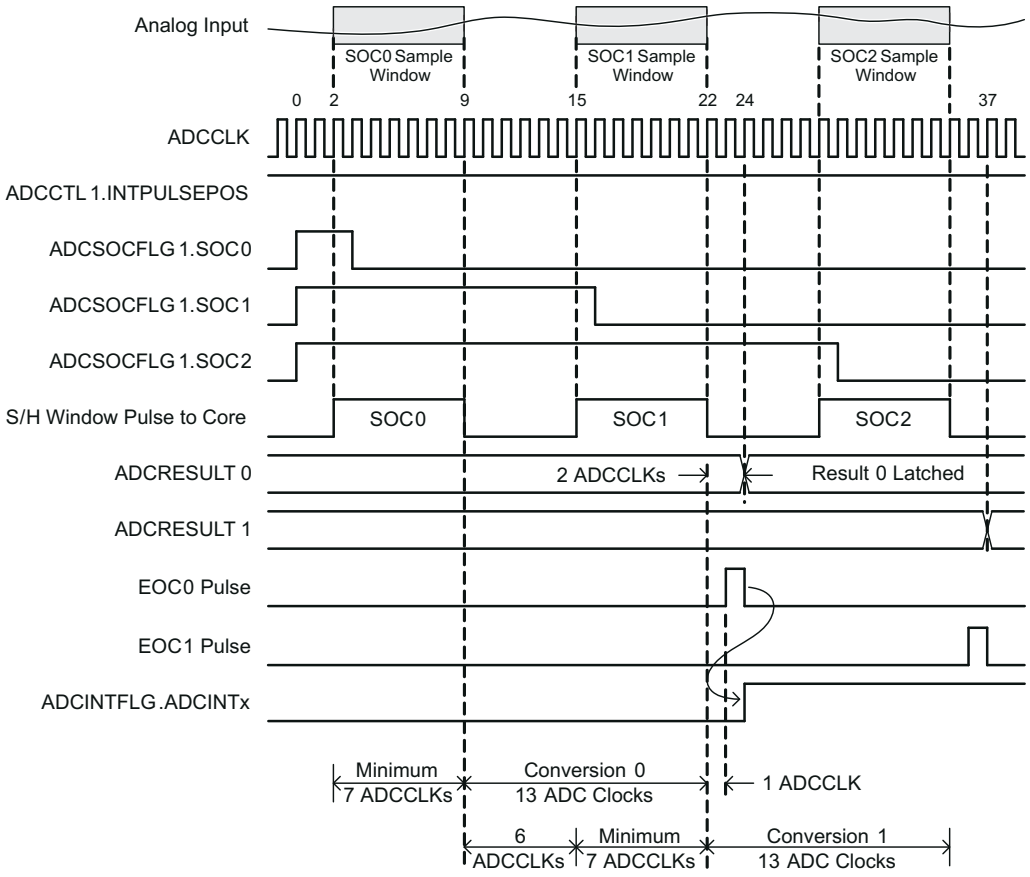


图 9-21. 顺序模式/后期中断脉冲的时序示例

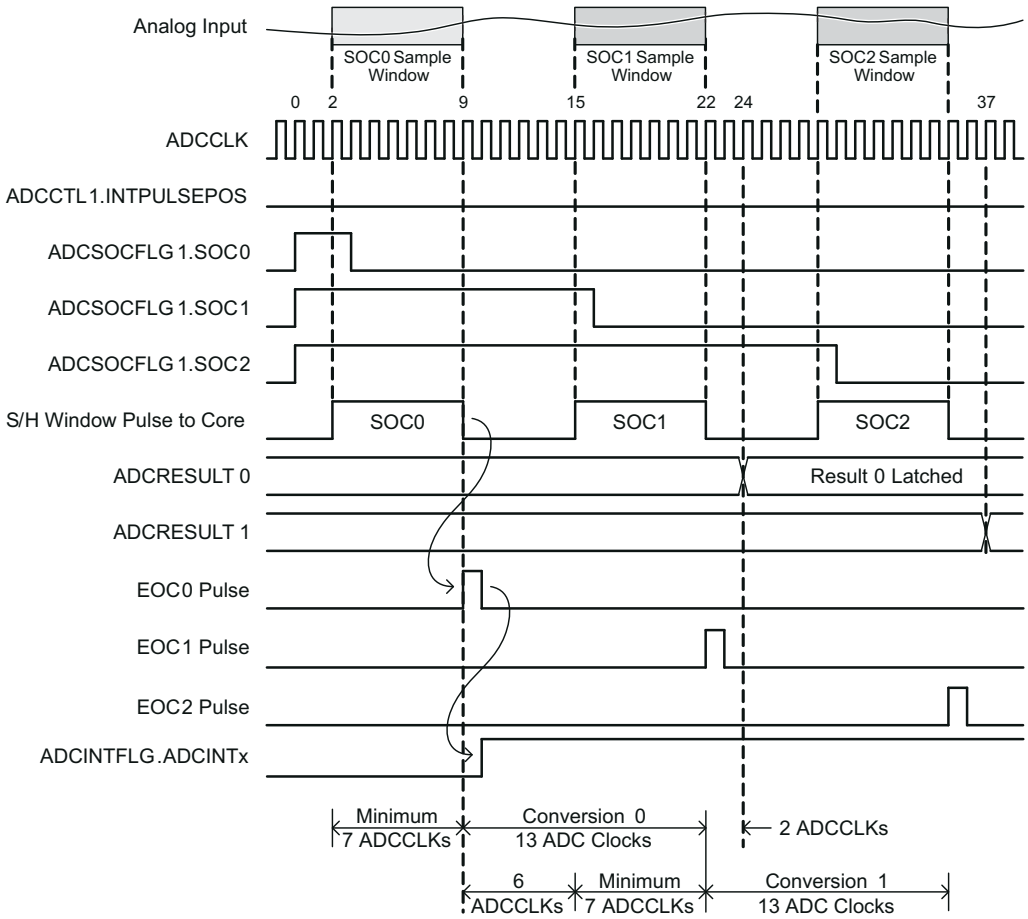


图 9-22. 顺序模式/提前中断脉冲的时序示例

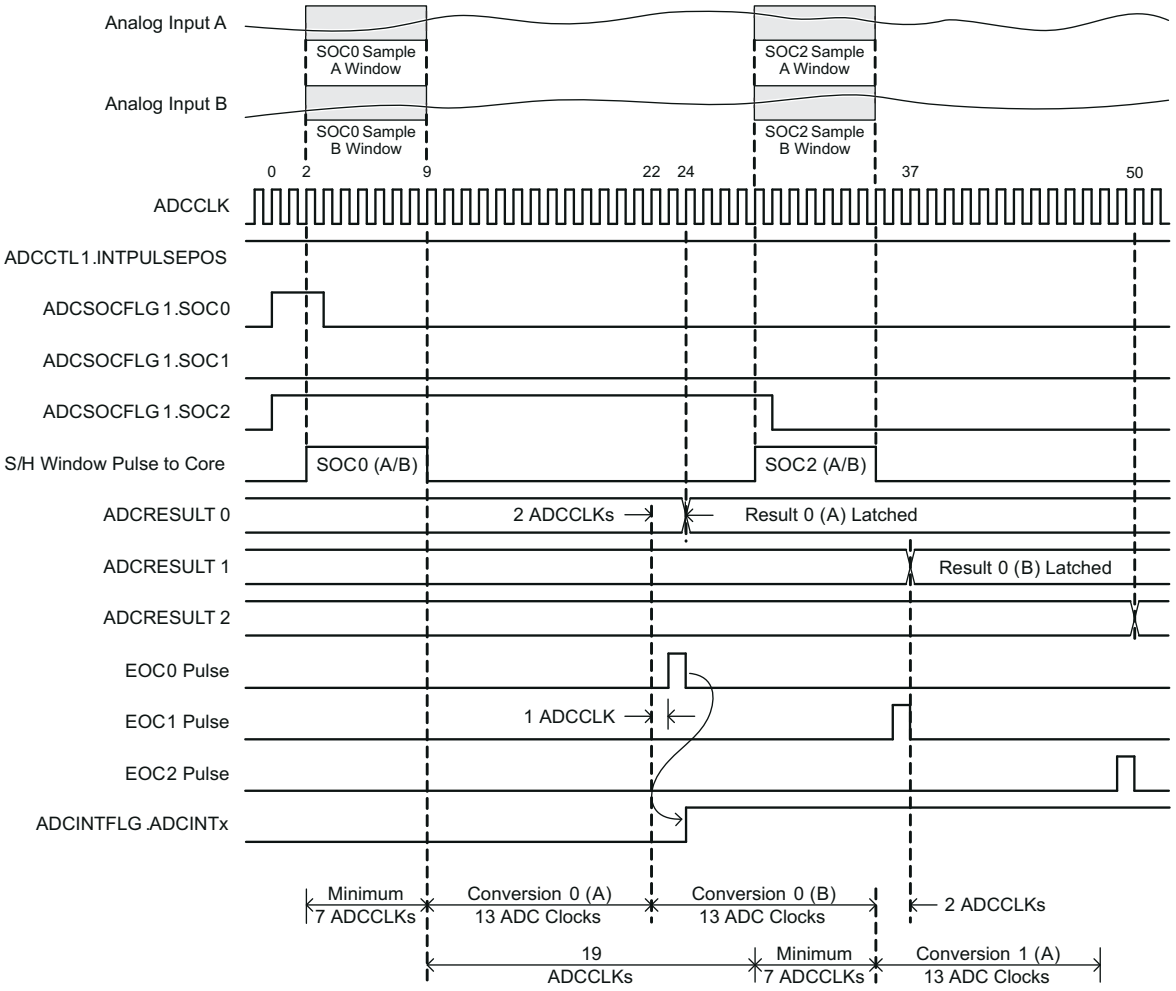


图 9-23. 同步模式/后期中断脉冲的时序示例

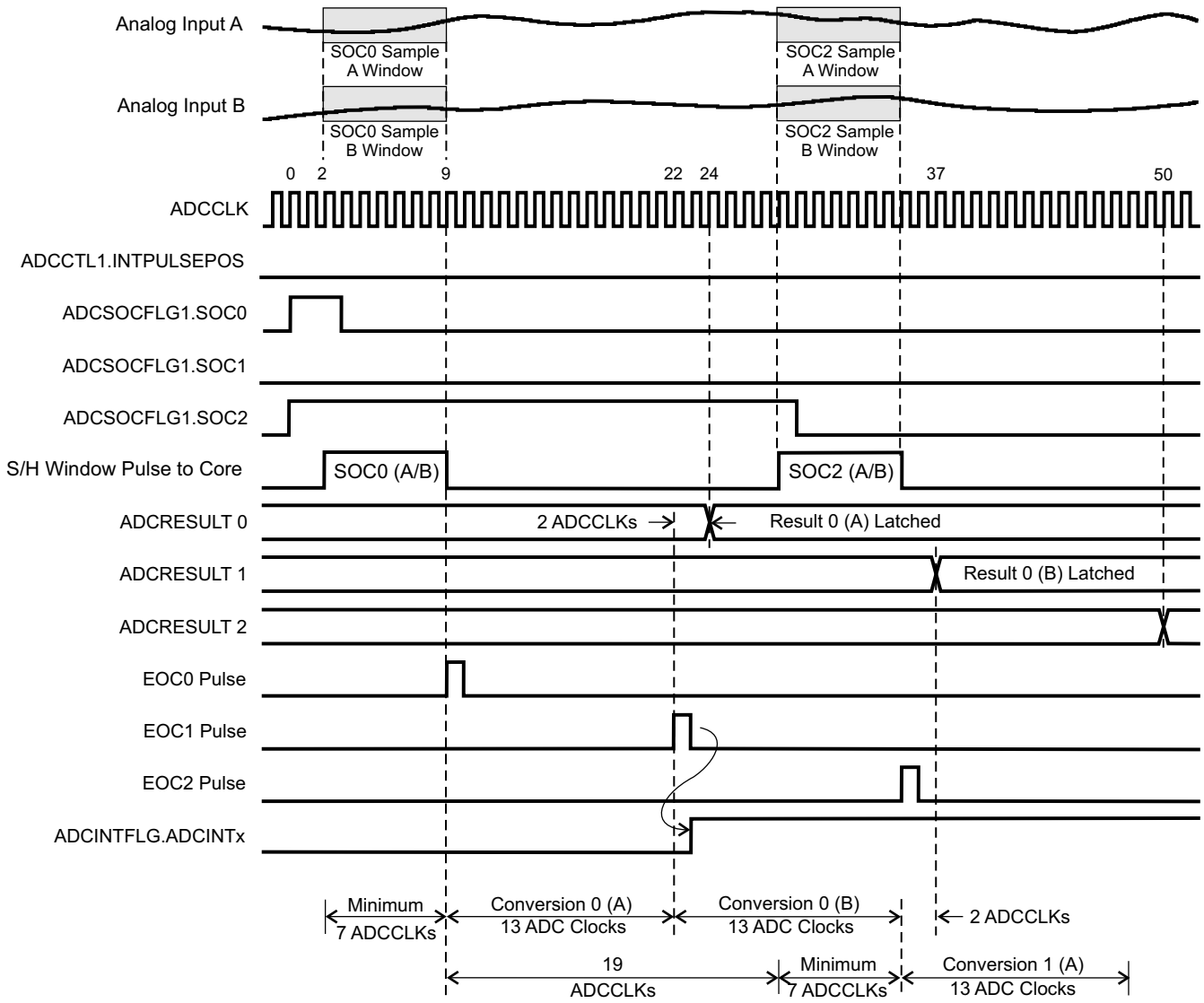


图 9-24. 同步模式/提前中断脉冲的时序示例

9.9.1.2 ADC 多路复用器

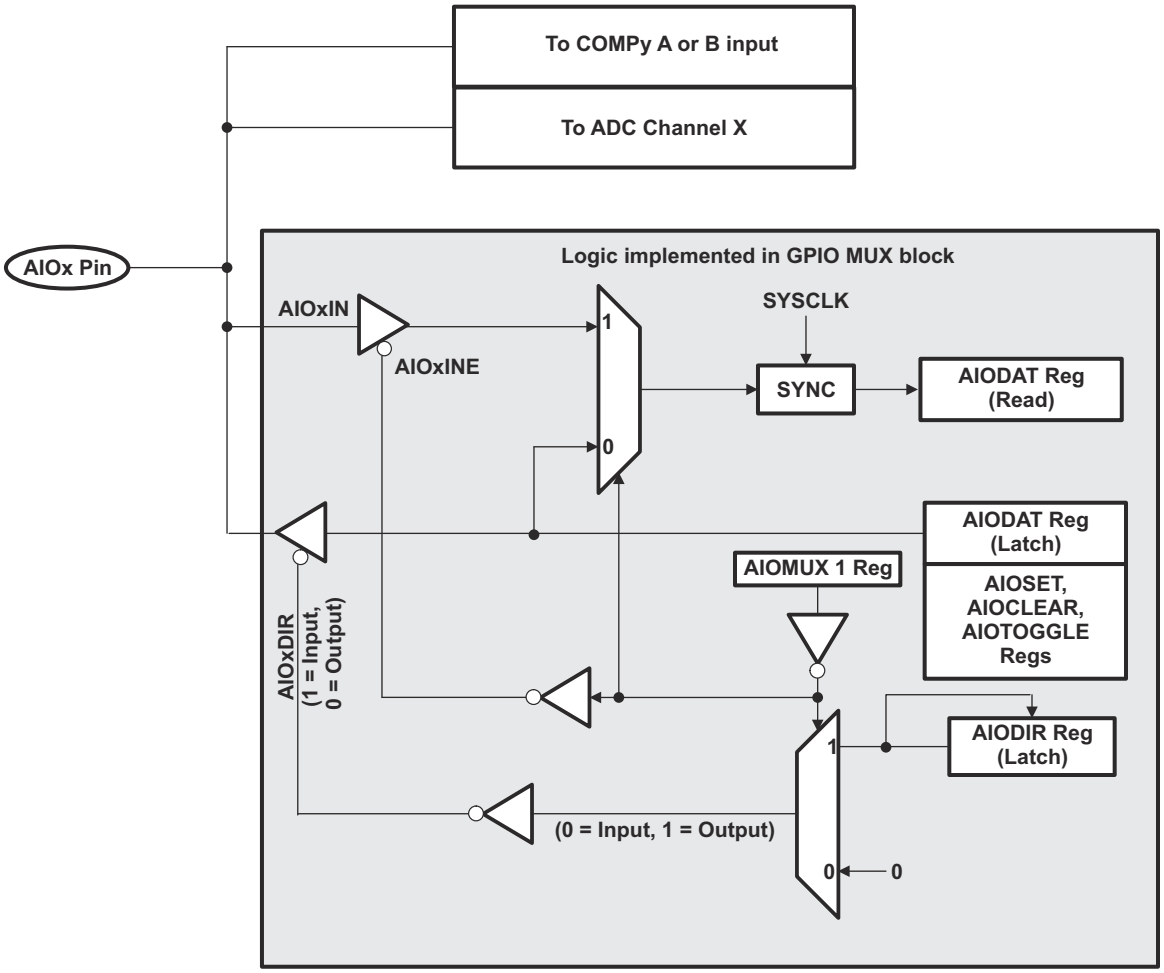


图 9-25. AIOx 引脚多路复用

ADC 通道和比较器功能始终可用。数字 I/O 功能只有当 AIOMUX1 寄存器中的相应位为 0 时可用。在此模式下，读取 AIODAT 寄存器会反映实际引脚状态。

数字 I/O 功能在 AIOMUX1 寄存器中的相应位为 1 时停用。在此模式下，读取 AIODAT 寄存器会反映 AIODAT 寄存器的输出锁存器，并且输入数字 I/O 缓冲器将会停用以防止模拟信号生成噪声。

复位时，数字功能会停用。如果此引脚用作模拟输入，则用户应该确保该引脚持续停用 AIO 功能。

9.9.1.3 比较器块

图 9-26 显示了比较器，模块与系统其余部分的相互作用。

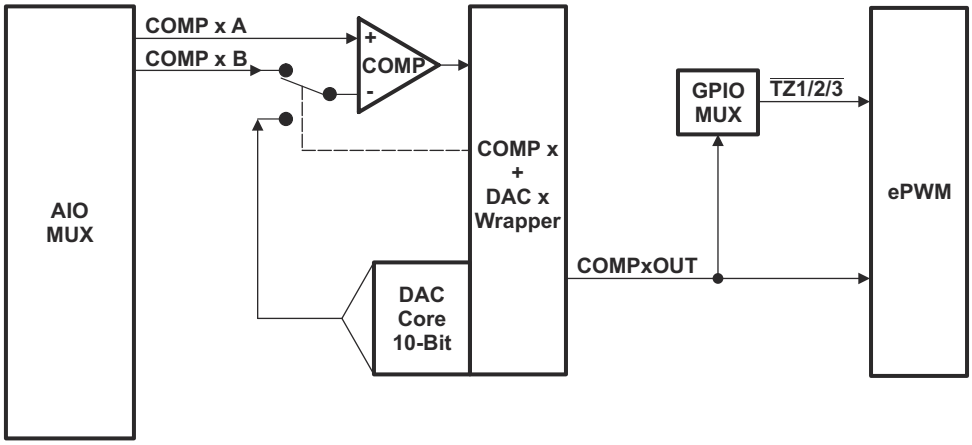


图 9-26. 比较器块图

表 9-23. 比较器控制寄存器

寄存器名称	COMP1 地址	COMP2 地址(1)	大小 (x 16)	受 EALLOW 保护	说明
COMPCTL	0x6400	0x6420	1	是	比较器控制寄存器
COMPSTS	0x6402	0x6422	1	否	比较器状态寄存器
DACCTL	0x6404	0x6424	1	是	DAC 控制寄存器
DACVAL	0x6406	0x6426	1	否	DAC 值寄存器
RAMPMAXREF_ACTIVE	0x6408	0x6428	1	否	斜坡发生器最大基准（有效）寄存器
RAMPMAXREF_SHDW	0x640A	0x642A	1	否	斜坡发生器最大基准（阴影）寄存器
RAMPDECVAL_ACTIVE	0x640C	0x642C	1	否	斜坡发生器减量值（有效）寄存器
RAMPDECVAL_SHDW	0x640E	0x642E	1	否	斜坡发生器减量值（阴影）寄存器
RAMPSTS	0x6410	0x6430	1	否	斜坡发生器状态寄存器

(1) 比较器 2 只在 48 引脚 PT 封装内可用。

9.9.1.3.1 片载比较器 / DAC 电子数据/定时

9.9.1.3.1.1 Electrical Characteristics of the Comparator/DAC

PARAMETER	MIN	TYP	MAX	UNITS
Comparator				
Comparator Input Range		V_{SSA} – V_{DDA}		V
Comparator response time to PWM Trip Zone (Async)		30		ns
Input Offset		±5		mV
Input Hysteresis(1)		35		mV
DAC				
DAC Output Range		V_{SSA} – V_{DDA}		V
DAC resolution		10		bits
DAC settling time		See 图 9-27		
DAC Gain		– 1.5%		
DAC Offset		10		mV
Monotonic		Yes		
INL		±3		LSB

(1) Hysteresis on the comparator inputs is achieved with a Schmidt trigger configuration. This results in an effective 100-kΩ feedback resistance between the output of the comparator and the noninverting input of the comparator. There is an option to disable the hysteresis and, with it, the feedback resistance; see the Analog-to-Digital Converter and Comparator chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual* for more information on this option if needed in your system.

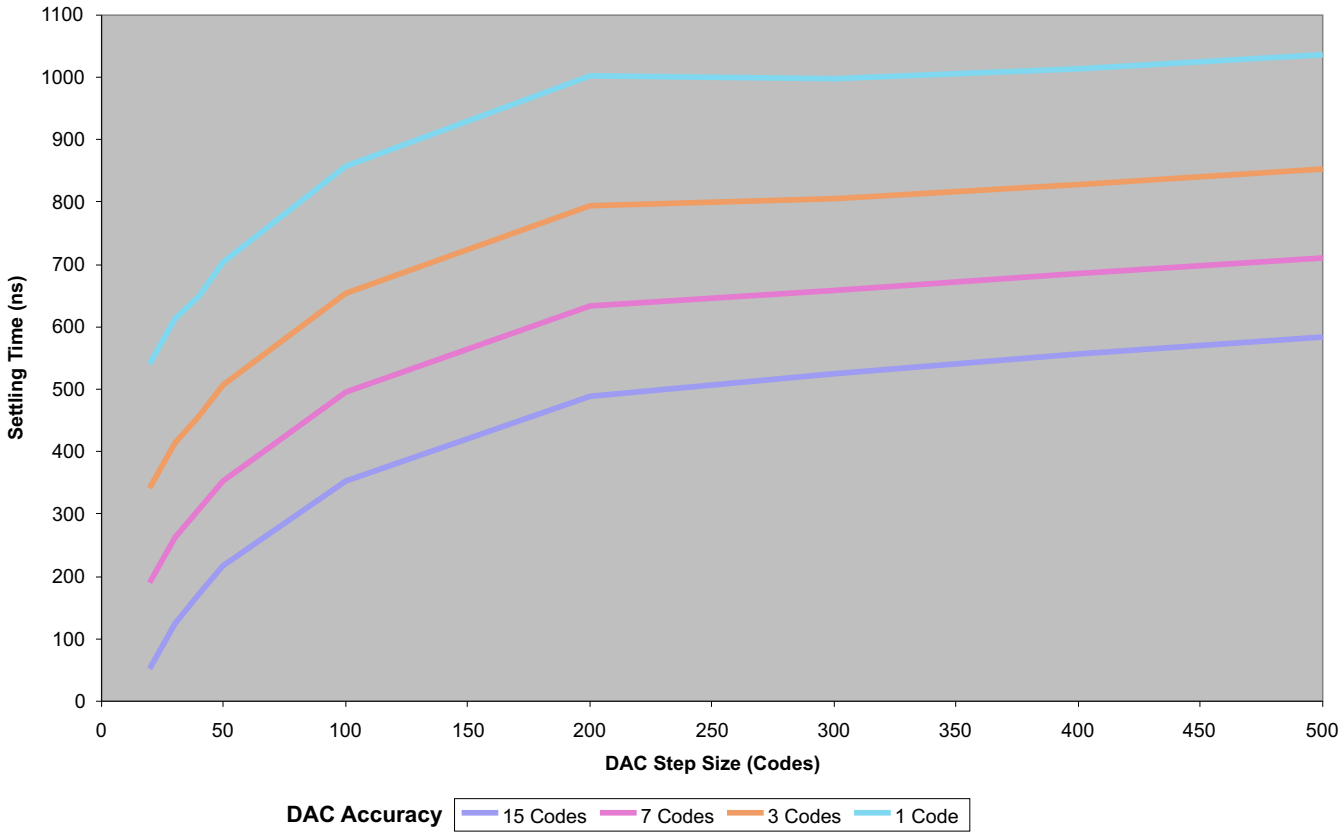


图 9-27. DAC Settling Time

9.9.2 详细说明

积分非线性

积分非线性是指各个代码与从零到满量程绘制的直线的偏差。在首次代码转换前，作为零点的点出现一半 LSB。满刻度点被定义为超过最后一次代码转换的级别一半 LSB。这个偏离为每一个特定代码的中心到这两个点之间的精确直线的距离。

微分非线性

一个理想 ADC 显示分开距离恰好为 1 个 LSB 的代码转换。DNL 是从这个理想值的偏离。一个少于 ±1 LSB 的微分非线性误差可确保无丢码。

零偏移

当模拟输入为零伏时，应当发生主进位转换。零误差被定义为实际转换到那个点的偏离。

增益误差

第一个代码转换应该出现在高于负满刻度的一个模拟值一半 LSB 上。最后一次转换应该出现在低于标称满刻度的一个模拟值一倍半 LSB 上。增益误差是首次和末次代码转换间的实际差异以及它们之间的理想差异。

信噪比 + 失真 (SINAD)

SINAD 是测得的输入信号的均方根值与所有其它低于那奎斯特频率的频谱分量（包括谐波但不包括 dc）的均方根总和的比。SINAD 的值用分贝表示。

有效位数 (ENOB)

对于一个正弦波，SINAD 可用位的数量表示。使用下面的公式，$N = \frac{(SINAD - 1.76)}{6.02}$ 有可能获得一个用 N（位的有效数）表达的性能测量值。因此，对于在给定输入频率上用于正弦波输入的器件的有效位数量可从这个测得的 SINAD 直接计算。

总谐波失真 (THD)

THD 是头九个谐波分量的均方根总和与测得的输入信号的均方根值的比并表达为一个百分比或者分贝值。

无伪波动态范围 (SFDR)

SFDR 是输入信号均方根振幅与峰值寄生信号间以分贝为单位的差异。

9.9.3 Serial Peripheral Interface (SPI) Module

The device includes the four-pin serial peripheral interface (SPI) module. One SPI module (SPI-A) is available. The SPI is a high-speed, synchronous serial I/O port that allows a serial bit stream of programmed length (1 to 16 bits) to be shifted into and out of the device at a programmable bit-transfer rate. Normally, the SPI is used for communications between the MCU and external peripherals or another processor. Typical applications include external I/O or peripheral expansion through devices such as shift registers, display drivers, and ADCs. Multidevice communications are supported by the master/slave operation of the SPI.

The SPI module features include:

- Four external pins:
  - SPISOMI: SPI slave-output/master-input pin
  - SPISIMO: SPI slave-input/master-output pin
  - $\overline{\text{SPISTE}}$: SPI slave transmit-enable pin
  - SPICLK: SPI serial-clock pin

备注

All four pins can be used as GPIO if the SPI module is not used.

- Two operational modes: master and slave

  Baud rate: 125 different programmable rates.

$$\text{Baud rate} = \frac{\text{LSPCLK}}{(\text{SPIBRR} + 1)} \qquad \text{when SPIBRR} = 3 \text{ to } 127$$

$$\text{Baud rate} = \frac{\text{LSPCLK}}{4} \qquad \text{when SPIBRR} = 0, 1, 2$$

- Data word length: 1 to 16 data bits
- Four clocking schemes (controlled by clock polarity and clock phase bits) include:
  - Falling edge without phase delay: SPICLK active-high. SPI transmits data on the falling edge of the SPICLK signal and receives data on the rising edge of the SPICLK signal.
  - Falling edge with phase delay: SPICLK active-high. SPI transmits data one half-cycle ahead of the falling edge of the SPICLK signal and receives data on the falling edge of the SPICLK signal.
  - Rising edge without phase delay: SPICLK inactive-low. SPI transmits data on the rising edge of the SPICLK signal and receives data on the falling edge of the SPICLK signal.
  - Rising edge with phase delay: SPICLK inactive-low. SPI transmits data one half-cycle ahead of the rising edge of the SPICLK signal and receives data on the rising edge of the SPICLK signal.
- Simultaneous receive and transmit operation (transmit function can be disabled in software)
- Transmitter and receiver operations are accomplished through either interrupt-driven or polled algorithms.
- Nine SPI module control registers: In control register frame beginning at address 7040h.

备注

All registers in this module are 16-bit registers that are connected to Peripheral Frame 2. When a register is accessed, the register data is in the lower byte (7 – 0), and the upper byte (15 – 8) is read as zeros. Writing to the upper byte has no effect.

Enhanced feature:

- 4-level transmit/receive FIFO
- Delayed transmit control
- Bidirectional 3 wire SPI mode support

The SPI port operation is configured and controlled by the registers listed in 表 9-24 .

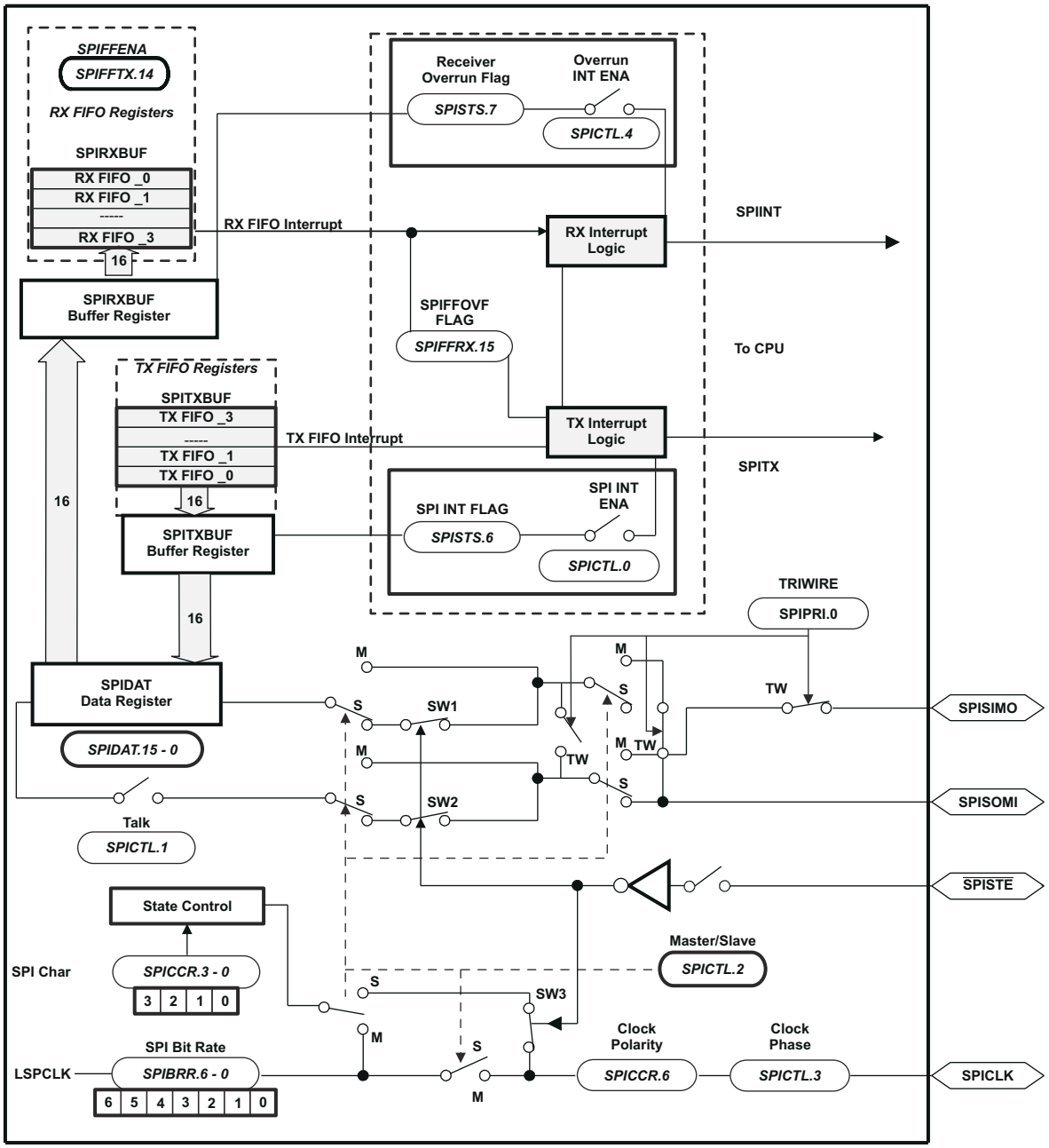
表 9-24. SPI-A Registers

NAME	ADDRESS	SIZE (x16)	EALLOW PROTECTED	DESCRIPTION(1)
SPICCR	0x7040	1	No	SPI-A Configuration Control Register
SPICTL	0x7041	1	No	SPI-A Operation Control Register
SPISTS	0x7042	1	No	SPI-A Status Register
SPIBRR	0x7044	1	No	SPI-A Baud Rate Register
SPIRXEMU	0x7046	1	No	SPI-A Receive Emulation Buffer Register
SPIRXBUF	0x7047	1	No	SPI-A Serial Input Buffer Register
SPITXBUF	0x7048	1	No	SPI-A Serial Output Buffer Register
SPIDAT	0x7049	1	No	SPI-A Serial Data Register
SPIFFTX	0x704A	1	No	SPI-A FIFO Transmit Register
SPIFFRX	0x704B	1	No	SPI-A FIFO Receive Register
SPIFFCT	0x704C	1	No	SPI-A FIFO Control Register
SPIPRI	0x704F	1	No	SPI-A Priority Control Register

(1) Registers in this table are mapped to Peripheral Frame 2. This space only allows 16-bit accesses. 32-bit accesses produce undefined results.

For more information on the SPI, see the Serial Peripheral Interface (SPI) chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

图 9-28 is a block diagram of the SPI in slave mode.



A. $\overline{\text{SPISTE}}$ is driven low by the master for a slave device.

图 9-28. SPI Module Block Diagram (Slave Mode)

9.9.3.1 SPI 主模式电气数据/时序

节 9.9.3.1.1 列出了主模式时序（时钟相位 = 0），节 9.9.3.1.2 列出了主模式时序（时钟相位 = 1）。图 9-29 和图 9-30 显示了时序波形。

9.9.3.1.1 SPI Master Mode External Timing (Clock Phase = 0)

NO.(1) (2) (3) (4) (5)	PARAMETER		BRR EVEN		BRR ODD		UNIT
			MIN	MAX	MIN	MAX	
1	$t_{c(SPC)M}$	Cycle time, SPICLK	$4t_{c(LSPCLK)}$	$128t_{c(LSPCLK)}$	$5t_{c(LSPCLK)}$	$127t_{c(LSPCLK)}$	ns
2	$t_{w(SPC1)M}$	Pulse duration, SPICLK first pulse	$0.5t_{c(SPC)M} - 10$	$0.5t_{c(SPC)M} + 10$	$0.5t_{c(SPC)M} + 0.5t_{c(LSPCLK)} - 10$	$0.5t_{c(SPC)M} + 0.5t_{c(LSPCLK)} + 10$	ns
3	$t_{w(SPC2)M}$	Pulse duration, SPICLK second pulse	$0.5t_{c(SPC)M} - 10$	$0.5t_{c(SPC)M} + 10$	$0.5t_{c(SPC)M} - 0.5t_{c(LSPCLK)} - 10$	$0.5t_{c(SPC)M} - 0.5t_{c(LSPCLK)} + 10$	ns
4	$t_{d(SIMO)M}$	Delay time, SPICLK to SPISIMO valid		10		10	ns
5	$t_{v(SIMO)M}$	Valid time, SPISIMO valid after SPICLK	$0.5t_{c(SPC)M} - 10$		$0.5t_{c(SPC)M} - 0.5t_{c(LSPCLK)} - 10$		ns
8	$t_{su(SOMI)M}$	Setup time, SPISOMI before SPICLK	26		26		ns
9	$t_{h(SOMI)M}$	Hold time, SPISOMI valid after SPICLK	0		0		ns
23	$t_{d(SPC)M}$	Delay time, $\overline{\text{SPISTE}}$ active to SPICLK	$1.5t_{c(SPC)M} - 3t_{c(SYSCLK)} - 10$		$1.5t_{c(SPC)M} - 3t_{c(SYSCLK)} - 10$		ns
24	$t_{d(STE)M}$	Delay time, SPICLK to $\overline{\text{SPISTE}}$ inactive	$0.5t_{c(SPC)M} - 10$		$0.5t_{c(SPC)M} - 0.5t_{c(LSPCLK)} - 10$		ns

(1) The MASTER / SLAVE bit (SPICTL.2) is set and the CLOCK PHASE bit (SPICTL.3) is cleared.
(2) $t_{c(SPC)}$ = SPI clock cycle time = LSPCLK/4 or LSPCLK/(SPIBRR +1)
(3) $t_{c(LCO)}$ = LSPCLK cycle time
(4) Internal clock prescalers must be adjusted such that the SPI clock speed is limited to the following SPI clock rate:
Master mode transmit 25-MHz MAX, master mode receive 12.5-MHz MAX
Slave mode transmit 12.5-MAX, slave mode receive 12.5-MHz MAX.
(5) The active edge of the SPICLK signal referenced is controlled by the clock polarity bit (SPICCR.6).

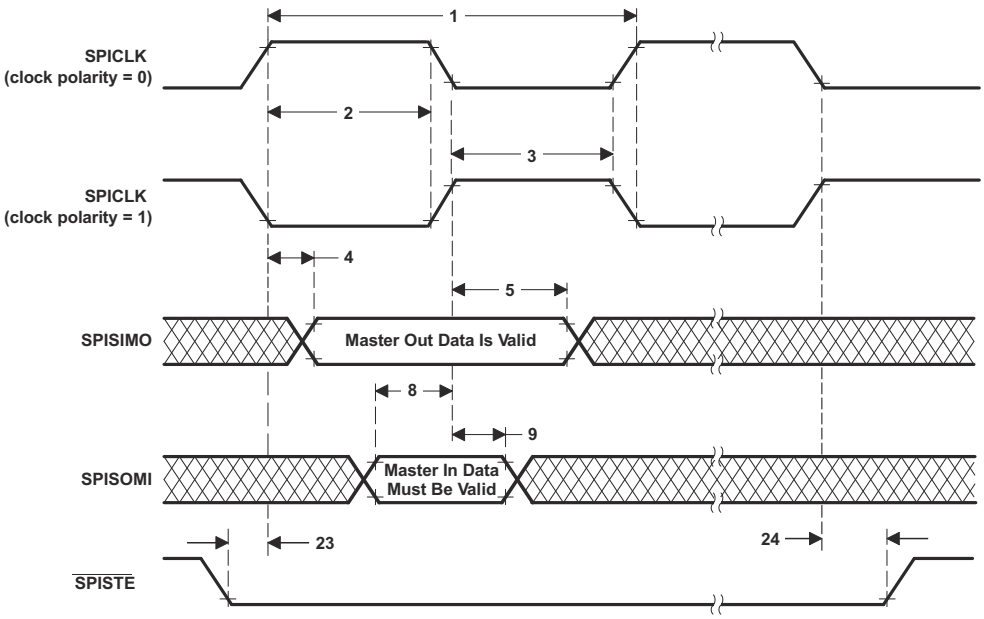


图 9-29. SPI Master Mode External Timing (Clock Phase = 0)

9.9.3.1.2 SPI Master Mode External Timing (Clock Phase = 1)

NO.(1) (2) (3) (4) (5)	PARAMETER		BRR EVEN		BRR ODD		UNIT
			MIN	MAX	MIN	MAX	
1	$t_{c(SPC)M}$	Cycle time, SPICLK	$4t_{c(LSPCLK)}$	$128t_{c(LSPCLK)}$	$5t_{c(LSPCLK)}$	$127t_{c(LSPCLK)}$	ns
2	$t_{w(SPC1)M}$	Pulse duration, SPICLK first pulse	$0.5t_{c(SPC)M} - 10$	$0.5t_{c(SPC)M} + 10$	$0.5t_{c(SPC)M} - 0.5t_{c(LSPCLK)} - 10$	$0.5t_{c(SPC)M} - 0.5t_{c(LSPCLK)} + 10$	ns
3	$t_{w(SPC2)M}$	Pulse duration, SPICLK second pulse	$0.5t_{c(SPC)M} - 10$	$0.5t_{c(SPC)M} + 10$	$0.5t_{c(SPC)M} + 0.5t_{c(LSPCLK)} - 10$	$0.5t_{c(SPC)M} + 0.5t_{c(LSPCLK)} + 10$	ns
6	$t_{d(SIMO)M}$	Delay time, SPISIMO valid to SPICLK	$0.5t_{c(SPC)M} - 10$		$0.5t_{c(SPC)M} + 0.5t_{c(LSPCLK)} - 10$		ns
7	$t_{v(SIMO)M}$	Valid time, SPISIMO valid after SPICLK	$0.5t_{c(SPC)M} - 10$		$0.5t_{c(SPC)M} - 0.5t_{c(LSPCLK)} - 10$		ns
10	$t_{su(SOMI)M}$	Setup time, SPISOMI before SPICLK	26		26		ns
11	$t_{h(SOMI)M}$	Hold time, SPISOMI valid after SPICLK	0		0		ns
23	$t_{d(SPC)M}$	Delay time, $\overline{\text{SPISTE}}$ active to SPICLK	$2t_{c(SPC)M} - 3t_{c(SYSCLK)} - 10$		$2t_{c(SPC)M} - 3t_{c(SYSCLK)} - 10$		ns
24	$t_{d(STE)M}$	Delay time, SPICLK to $\overline{\text{SPISTE}}$ inactive	$0.5t_{c(SPC)} - 10$		$0.5t_{c(SPC)} - 0.5t_{c(LSPCLK)} - 10$		ns

(1) The MASTER/SLAVE bit (SPICTL.2) is set and the CLOCK PHASE bit (SPICTL.3) is set.
(2) $t_{c(SPC)}$ = SPI clock cycle time = LSPCLK/4 or LSPCLK/(SPIBRR + 1)
(3) Internal clock prescalers must be adjusted such that the SPI clock speed is limited to the following SPI clock rate:
Master mode transmit 25 MHz MAX, master mode receive 12.5 MHz MAX
Slave mode transmit 12.5 MHz MAX, slave mode receive 12.5 MHz MAX.
(4) $t_{c(LCO)}$ = LSPCLK cycle time
(5) The active edge of the SPICLK signal referenced is controlled by the CLOCK POLARITY bit (SPICCR.6).

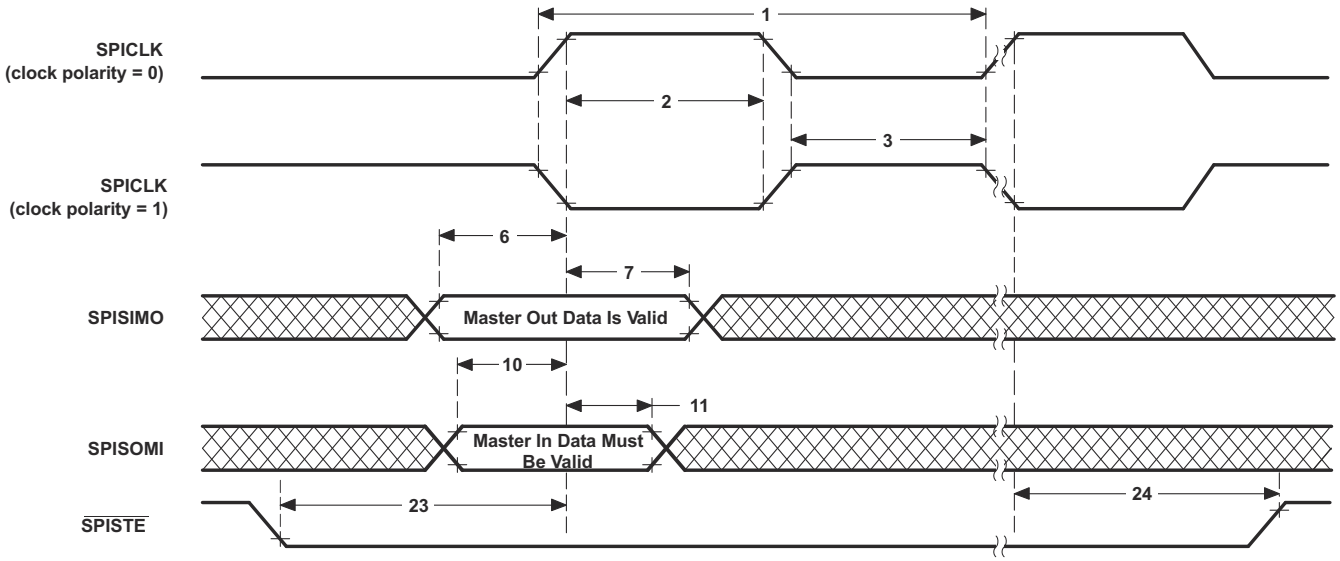


图 9-30. SPI Master Mode External Timing (Clock Phase = 1)

9.9.3.2 SPI 从模式电气数据/时序

节 9.9.3.2.1 列出了从模式时序（时钟相位 = 0），节 9.9.3.2.2 列出了从模式时序（时钟相位 = 1）。图 9-31 和图 9-32 显示了时序波形。

9.9.3.2.1 SPI Slave Mode External Timing (Clock Phase = 0)

NO. (1) (2) (4) (3) (5)	PARAMETER		MIN	MAX	UNIT
12	$t_{c(SPC)S}$	Cycle time, SPICLK	$4t_{c(SYSCLK)}$		ns
13	$t_{w(SPC1)S}$	Pulse duration, SPICLK first pulse	$2t_{c(SYSCLK)} - 1$		ns
14	$t_{w(SPC2)S}$	Pulse duration, SPICLK second pulse	$2t_{c(SYSCLK)} - 1$		ns
15	$t_{d(SOMI)S}$	Delay time, SPICLK to SPISOMI valid		21	ns
16	$t_{v(SOMI)S}$	Valid time, SPISOMI data valid after SPICLK	0		ns
19	$t_{su(SIMO)S}$	Setup time, SPISIMO valid before SPICLK	$1.5t_{c(SYSCLK)}$		ns
20	$t_{h(SIMO)S}$	Hold time, SPISIMO data valid after SPICLK	$1.5t_{c(SYSCLK)}$		ns
25	$t_{su(STE)S}$	Setup time, $\overline{\text{SPISTE}}$ active before SPICLK	$1.5t_{c(SYSCLK)}$		ns
26	$t_{h(STE)S}$	Hold time, $\overline{\text{SPISTE}}$ inactive after SPICLK	$1.5t_{c(SYSCLK)}$		ns

(1) The MASTER / SLAVE bit (SPICTL.2) is cleared and the CLOCK PHASE bit (SPICTL.3) is cleared.
(2) $t_{c(SPC)}$ = SPI clock cycle time = LSPCLK/4 or LSPCLK/(SPIBRR + 1)
(3) $t_{c(LCO)}$ = LSPCLK cycle time
(4) Internal clock prescalers must be adjusted such that the SPI clock speed is limited to the following SPI clock rate:
Master mode transmit 25-MHz MAX, master mode receive 12.5-MHz MAX
Slave mode transmit 12.5-MHz MAX, slave mode receive 12.5-MHz MAX.
(5) The active edge of the SPICLK signal referenced is controlled by the CLOCK POLARITY bit (SPICCR.6).

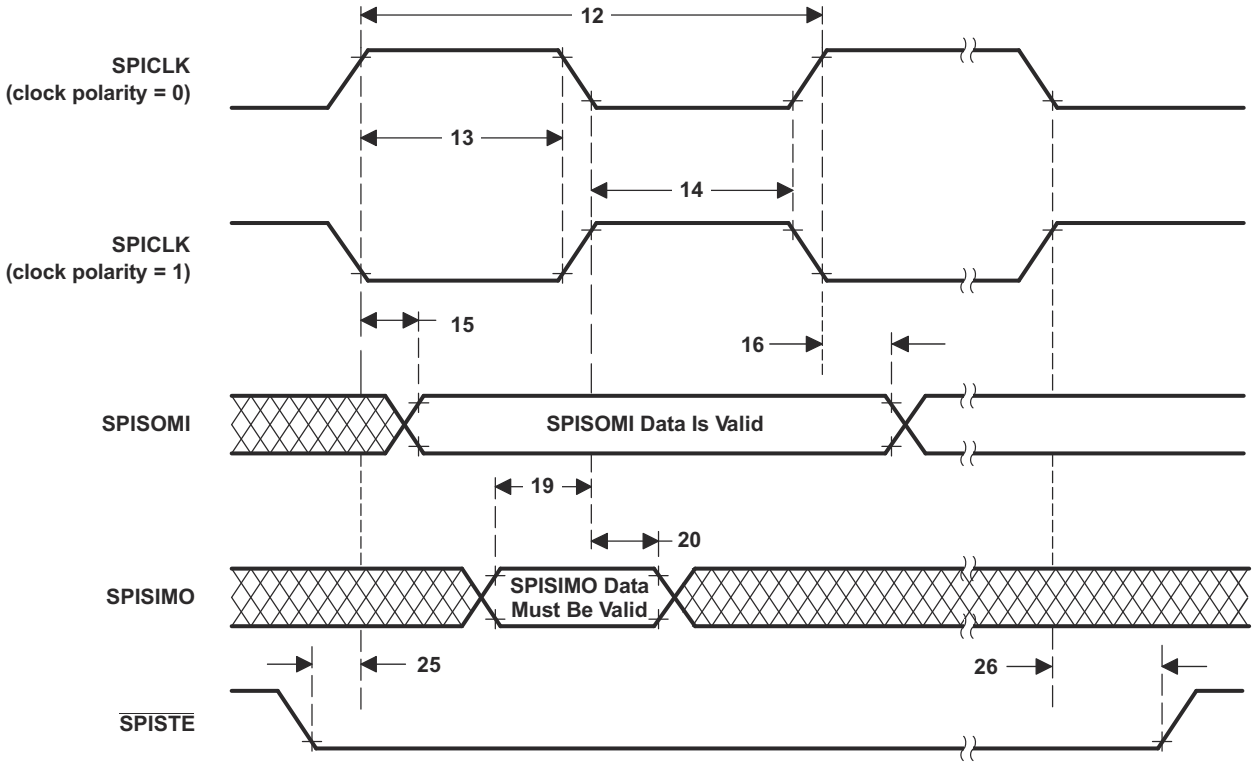


图 9-31. SPI Slave Mode External Timing (Clock Phase = 0)

9.9.3.2.2 SPI Slave Mode External Timing (Clock Phase = 1)

NO. (1) (2) (3) (4)	PARAMETER		MIN	MAX	UNIT
12	$t_{c(SPC)S}$	Cycle time, SPICLK	$4t_{c(SYSCLK)}$		ns
13	$t_{w(SPC1)S}$	Pulse duration, SPICLK first pulse	$2t_{c(SYSCLK)} - 1$		ns
14	$t_{w(SPC2)S}$	Pulse duration, SPICLK second pulse	$2t_{c(SYSCLK)} - 1$		ns
17	$t_{d(SOMI)S}$	Delay time, SPICLK to SPISOMI valid		21	ns
18	$t_{v(SOMI)S}$	Valid time, SPISOMI data valid after SPICLK	0		ns
21	$t_{su(SIMO)S}$	Setup time, SPISIMO valid before SPICLK	$1.5t_{c(SYSCLK)}$		ns
22	$t_{h(SIMO)S}$	Hold time, SPISIMO data valid after SPICLK	$1.5t_{c(SYSCLK)}$		ns
25	$t_{su(STE)S}$	Setup time, $\overline{\text{SPISTE}}$ active before SPICLK	$1.5t_{c(SYSCLK)}$		ns
26	$t_{h(STE)S}$	Hold time, $\overline{\text{SPISTE}}$ inactive after SPICLK	$1.5t_{c(SYSCLK)}$		ns

(1) The MASTER / SLAVE bit (SPICTL.2) is cleared and the CLOCK PHASE bit (SPICTL.3) is cleared.
(2) $t_{c(SPC)}$ = SPI clock cycle time = LSPCLK/4 or LSPCLK/(SPIBRR + 1)
(3) Internal clock prescalers must be adjusted such that the SPI clock speed is limited to the following SPI clock rate:
Master mode transmit 25-MHz MAX, master mode receive 12.5-MHz MAX
Slave mode transmit 12.5-MHz MAX, slave mode receive 12.5-MHz MAX.
(4) The active edge of the SPICLK signal referenced is controlled by the CLOCK POLARITY bit (SPICCR.6).

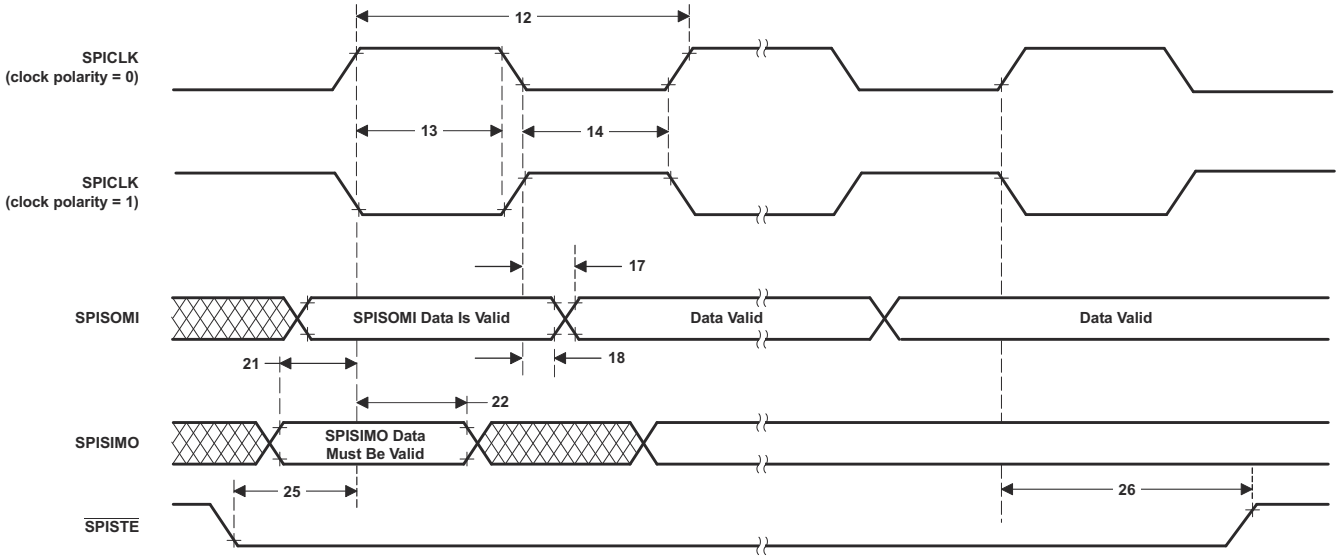


图 9-32. SPI Slave Mode External Timing (Clock Phase = 1)

9.9.4 Serial Communications Interface (SCI) Module

The devices include one serial communications interface (SCI) module (SCI-A). The SCI module supports digital communications between the CPU and other asynchronous peripherals that use the standard nonreturn-to-zero (NRZ) format. The SCI receiver and transmitter are double-buffered, and each has its own separate enable and interrupt bits. Both can be operated independently or simultaneously in the full-duplex mode. To ensure data integrity, the SCI checks received data for break detection, parity, overrun, and framing errors. The bit rate is programmable to over 65000 different speeds through a 16-bit baud-select register.

Features of each SCI module include:

- Two external pins:
  - SCITXD: SCI transmit-output pin
  - SCIRXD: SCI receive-input pin

备注

Both pins can be used as GPIO if not used for SCI.

  - Baud rate programmable to 64K different rates:

$$\text{Baud rate} = \frac{\text{LSPCLK}}{(\text{BRR} + 1) * 8} \qquad \text{when BRR} \neq 0$$

$$\text{Baud rate} = \frac{\text{LSPCLK}}{16} \qquad \text{when BRR} = 0$$

- Data-word format
  - One start bit
  - Data-word length programmable from 1 to 8 bits
  - Optional even/odd/no parity bit
  - One or 2 stop bits
- Four error-detection flags: parity, overrun, framing, and break detection
- Two wake-up multiprocessor modes: idle-line and address bit
- Half- or full-duplex operation
- Double-buffered receive and transmit functions
- Transmitter and receiver operations can be accomplished through interrupt-driven or polled algorithms with status flags.
  - Transmitter: TXRDY flag (transmitter-buffer register is ready to receive another character) and TX EMPTY flag (transmitter-shift register is empty)
  - Receiver: RXRDY flag (receiver-buffer register is ready to receive another character), BRKDT flag (break condition occurred), and RX ERROR flag (monitoring four interrupt conditions)
- Separate enable bits for transmitter and receiver interrupts (except BRKDT)
- NRZ (nonreturn-to-zero) format

备注

All registers in this module are 8-bit registers that are connected to Peripheral Frame 2. When a register is accessed, the register data is in the lower byte (7 – 0), and the upper byte (15 – 8) is read as zeros. Writing to the upper byte has no effect.

Enhanced features:

- Auto baud-detect hardware logic
- 4-level transmit/receive FIFO

The SCI port operation is configured and controlled by the registers listed in 表 9-25.

表 9-25. SCI-A Registers

NAME(1)	ADDRESS	SIZE (x16)	EALLOW PROTECTED	DESCRIPTION
SCICCRA	0x7050	1	No	SCI-A Communications Control Register
SCICTL1A	0x7051	1	No	SCI-A Control Register 1
SCIHBAUDA	0x7052	1	No	SCI-A Baud Register, High Bits
SCILBAUDA	0x7053	1	No	SCI-A Baud Register, Low Bits
SCICTL2A	0x7054	1	No	SCI-A Control Register 2
SCIRXSTA	0x7055	1	No	SCI-A Receive Status Register
SCIRXEMUA	0x7056	1	No	SCI-A Receive Emulation Data Buffer Register
SCIRXBUFA	0x7057	1	No	SCI-A Receive Data Buffer Register
SCITXBUFA	0x7059	1	No	SCI-A Transmit Data Buffer Register
SCIFFTXA(2)	0x705A	1	No	SCI-A FIFO Transmit Register
SCIFFRXA(2)	0x705B	1	No	SCI-A FIFO Receive Register
SCIFFCTA(2)	0x705C	1	No	SCI-A FIFO Control Register
SCIPRIA	0x705F	1	No	SCI-A Priority Control Register

(1) Registers in this table are mapped to Peripheral Frame 2 space. This space only allows 16-bit accesses. 32-bit accesses produce undefined results.
(2) These registers are new registers for the FIFO mode.

For more information on the SCI, see the Serial Communications Interface (SCI) chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

图 9-33 shows the SCI module block diagram.

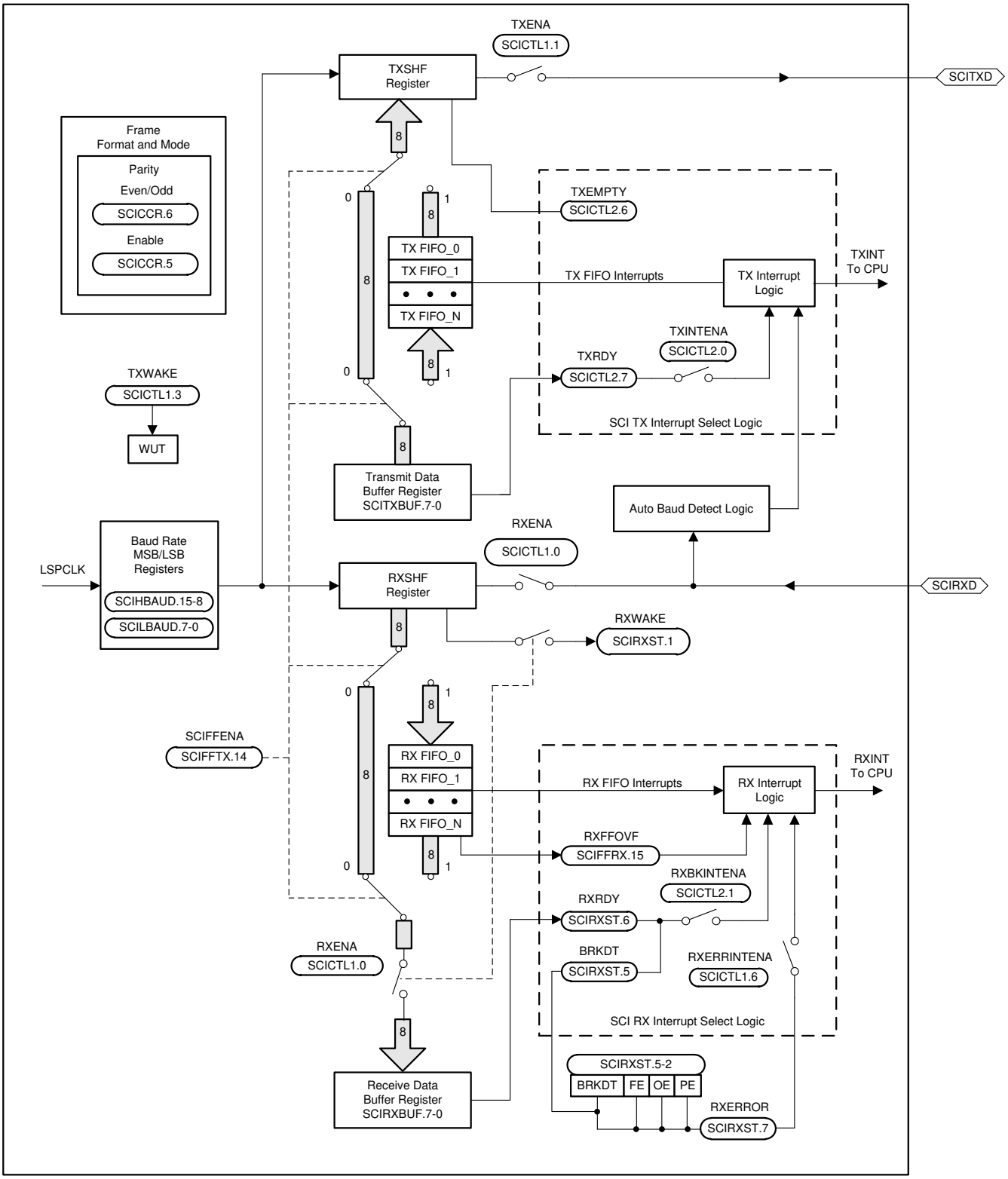


图 9-33. Serial Communications Interface (SCI) Module Block Diagram

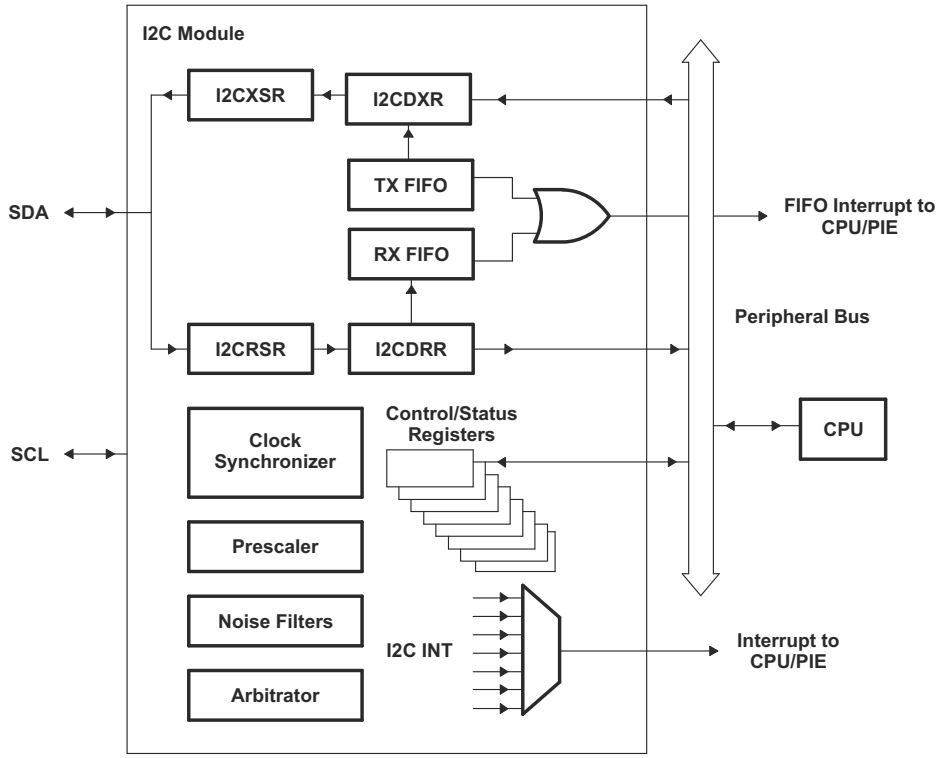
9.9.5 Inter-Integrated Circuit (I2C)

The device contains one I2C Serial Port. 图 9-34 shows how the I2C peripheral module interfaces within the device.

The I2C module has the following features:

- Compliance with the Philips Semiconductors I^2C-bus specification (version 2.1):
  - Support for 1-bit to 8-bit format transfers
  - 7-bit and 10-bit addressing modes
  - General call
  - START byte mode
  - Support for multiple master-transmitters and slave-receivers
  - Support for multiple slave-transmitters and master-receivers
  - Combined master transmit/receive and receive/transmit mode
  - Data transfer rate of from 10 kbps up to 400 kbps (I2C Fast-mode rate)
- One 4-word receive FIFO and one 4-word transmit FIFO
- One interrupt that can be used by the CPU. This interrupt can be generated as a result of one of the following conditions:
  - Transmit-data ready
  - Receive-data ready
  - Register-access ready
  - No-acknowledgment received
  - Arbitration lost
  - Stop condition detected
  - Addressed as slave
- An additional interrupt that can be used by the CPU when in FIFO mode
- Module enable/disable capability
- Free data format mode

For more information on the I2C, see the Inter-Integrated Circuit Module (I2C) chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.



A. The I2C registers are accessed at the SYSCLKOUT rate. The internal timing and signal waveforms of the I2C port are also at the SYSCLKOUT rate.

B. The clock enable bit (I2CAENCLK) in the PCLKCRO register turns off the clock to the I2C port for low-power operation. Upon reset, I2CAENCLK is clear, which indicates the peripheral internal clocks are off.

图 9-34. I2C Peripheral Module Interfaces

The registers in 表 9-26 configure and control the I2C port operation.

表 9-26. I2C-A Registers

NAME	ADDRESS	EALLOW PROTECTED	DESCRIPTION
I2COAR	0x7900	No	I2C own address register
I2CIER	0x7901	No	I2C interrupt enable register
I2CSTR	0x7902	No	I2C status register
I2CCLKL	0x7903	No	I2C clock low-time divider register
I2CCLKH	0x7904	No	I2C clock high-time divider register
I2CCNT	0x7905	No	I2C data count register
I2CDRR	0x7906	No	I2C data receive register
I2CSAR	0x7907	No	I2C slave address register
I2CDXR	0x7908	No	I2C data transmit register
I2CMDR	0x7909	No	I2C mode register
I2CISRC	0x790A	No	I2C interrupt source register
I2CPSC	0x790C	No	I2C prescaler register
I2CFFTX	0x7920	No	I2C FIFO transmit register
I2CFFRX	0x7921	No	I2C FIFO receive register
I2CRSR	–	No	I2C receive shift register (not accessible to the CPU)
I2CXSR	–	No	I2C transmit shift register (not accessible to the CPU)

9.9.5.1 I2C 电气数据/时序

节 9.9.5.1.1 显示了 I2C 时序要求。节 9.9.5.1.2 显示了 I2C 开关特性。

9.9.5.1.1 I2C 时序要求

			最小值	最大值	单位
$t_{h(SDA-SCL)START}$	保持时间，启动条件，SDA 下降后 SCL 下降延迟		0.6		μs
$t_{su(SCL-SDA)START}$	设置时间，重复启动，SDA 下降延迟之前 SCL 上升		0.6		μs
$t_{h(SCL-DAT)}$	保持时间，SCL 下降后的数据		0		μs
$t_{su(DAT-SCL)}$	设置时间，SCL 上升前的数据		100		ns
$t_{r(SDA)}$	上升时间，SDA	输入容差	20	300	ns
$t_{r(SCL)}$	上升时间，SCL	输入容差	20	300	ns
$t_{f(SDA)}$	下降时间，SDA	输入容差	11.4	300	ns
$t_{f(SCL)}$	下降时间，SCL	输入容差	11.4	300	ns
$t_{su(SCL-SDA)STOP}$	设置时间，停止条件，SDA 上升延迟之前 SCL 上升		0.6		μs

9.9.5.1.2 I2C 开关特性

在推荐的运行条件下（除非另有说明）

参数		测试条件	最小值	最大值	单位
f_{SCL}	SCL 时钟频率	I2C 时钟模块频率介于 7MHz 与 12MHz 之间，并且 I2C 预分频器和时钟分频寄存器进行了适当配置。		400	kHz
V_{il}	低电平输入电压			0.3 V_{DDIO}	V
V_{ih}	高电平输入电压		0.7 V_{DDIO}		V
V_{hys}	输入滞后		0.05 V_{DDIO}		V
V_{ol}	低电平输出电压	3mA 灌电流	0	0.4	V
t_{LOW}	SCL 时钟的低周期	I2C 时钟模块频率介于 7MHz 与 12MHz 之间，并且 I2C 预分频器和时钟分频寄存器进行了适当配置。	1.3		μs
t_{HIGH}	SCL 时钟的高周期	I2C 时钟模块频率介于 7MHz 与 12MHz 之间，并且 I2C 预分频器和时钟分频寄存器进行了适当配置。	0.6		μs
I_I	输入电压介于 0.1 V_{DDIO} 与 0.9 V_{DDIO}（最大值）之间的输入电流		-10	10	μA

9.9.6 Enhanced PWM Modules (ePWM1/2/3/4)

The devices contain up to four enhanced PWM Modules (ePWM). 图 9-35 shows a block diagram of multiple ePWM modules. 图 9-36 shows the signal interconnections with the ePWM. For more details, see the Enhanced Pulse Width Modulator (ePWM) chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

表 9-27 shows the complete ePWM register set per module.

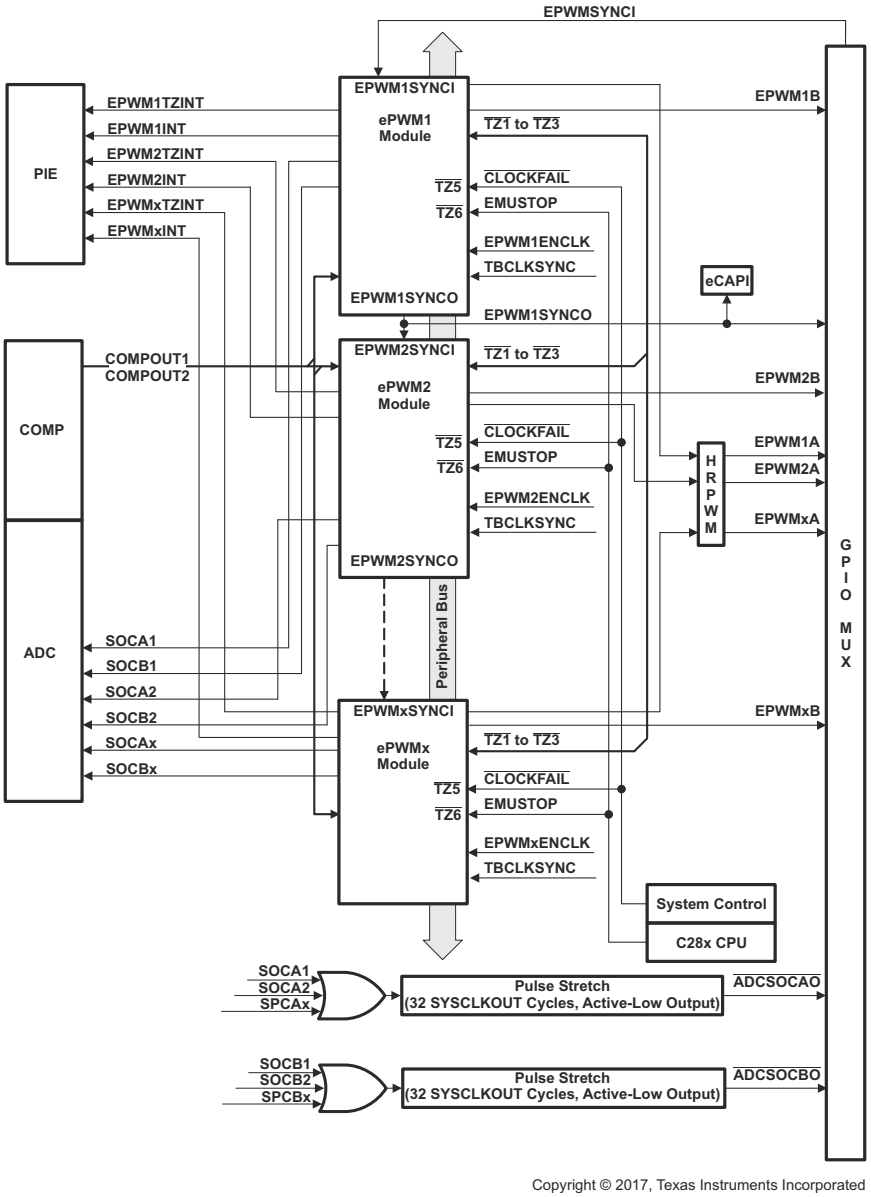


图 9-35. ePWM

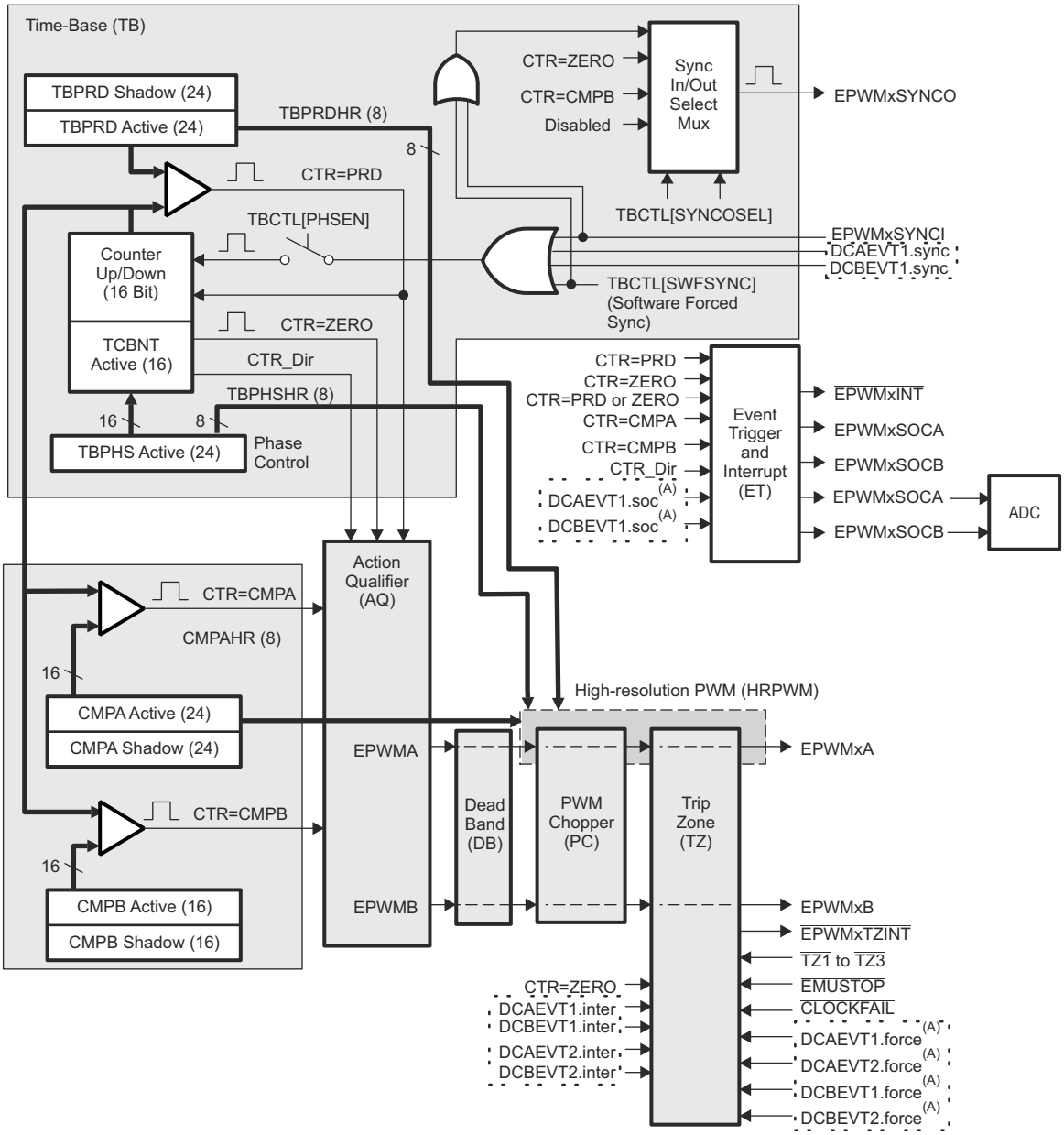
表 9-27. ePWM Control and Status Registers

NAME	ePWM1	ePWM2	ePWM3	ePWM4	SIZE (x16) / #SHADOW	DESCRIPTION
TBCTL	0x6800	0x6840	0x6880	0x68C0	1 / 0	Time Base Control Register
TBSTS	0x6801	0x6841	0x6881	0x68C1	1 / 0	Time Base Status Register
TBPHSHR	0x6802	0x6842	0x6882	0x68C2	1 / 0	Time Base Phase HRPWM Register
TBPHS	0x6803	0x6843	0x6883	0x68C3	1 / 0	Time Base Phase Register
TBCTR	0x6804	0x6844	0x6884	0x68C4	1 / 0	Time Base Counter Register
TBPRD	0x6805	0x6845	0x6885	0x68C5	1 / 1	Time Base Period Register Set
TBPRDHR	0x6806	0x6846	0x6886	0x68C6	1 / 1	Time Base Period High Resolution Register(1)
CMPCTL	0x6807	0x6847	0x6887	0x68C7	1 / 0	Counter Compare Control Register
CMPAHR	0x6808	0x6848	0x6888	0x68C8	1 / 1	Time Base Compare A HRPWM Register
CMPA	0x6809	0x6849	0x6889	0x68C9	1 / 1	Counter Compare A Register Set
CMPB	0x680A	0x684A	0x688A	0x68CA	1 / 1	Counter Compare B Register Set
AQCTLA	0x680B	0x684B	0x688B	0x68CB	1 / 0	Action Qualifier Control Register For Output A
AQCTLB	0x680C	0x684C	0x688C	0x68CC	1 / 0	Action Qualifier Control Register For Output B
AQSFRC	0x680D	0x684D	0x688D	0x68CD	1 / 0	Action Qualifier Software Force Register
AQCSFRC	0x680E	0x684E	0x688E	0x68CE	1 / 1	Action Qualifier Continuous S/W Force Register Set
DBCTL	0x680F	0x684F	0x688F	0x68CF	1 / 1	Dead-Band Generator Control Register
DBRED	0x6810	0x6850	0x6890	0x68D0	1 / 0	Dead-Band Generator Rising Edge Delay Count Register
DBFED	0x6811	0x6851	0x6891	0x68D1	1 / 0	Dead-Band Generator Falling Edge Delay Count Register
TZSEL	0x6812	0x6852	0x6892	0x68D2	1 / 0	Trip Zone Select Register(1)
TZDCSEL	0x6813	0x6853	0x6893	0x98D3	1 / 0	Trip Zone Digital Compare Register
TZCTL	0x6814	0x6854	0x6894	0x68D4	1 / 0	Trip Zone Control Register(1)
TZEINT	0x6815	0x6855	0x6895	0x68D5	1 / 0	Trip Zone Enable Interrupt Register(1)
TZFLG	0x6816	0x6856	0x6896	0x68D6	1 / 0	Trip Zone Flag Register (1)
TZCLR	0x6817	0x6857	0x6897	0x68D7	1 / 0	Trip Zone Clear Register(1)
TZFRC	0x6818	0x6858	0x6898	0x68D8	1 / 0	Trip Zone Force Register(1)
ETSEL	0x6819	0x6859	0x6899	0x68D9	1 / 0	Event Trigger Selection Register
ETPS	0x681A	0x685A	0x689A	0x68DA	1 / 0	Event Trigger Prescale Register
ETFLG	0x681B	0x685B	0x689B	0x68DB	1 / 0	Event Trigger Flag Register
ETCLR	0x681C	0x685C	0x689C	0x68DC	1 / 0	Event Trigger Clear Register
ETFRC	0x681D	0x685D	0x689D	0x68DD	1 / 0	Event Trigger Force Register
PCCTL	0x681E	0x685E	0x689E	0x68DE	1 / 0	PWM Chopper Control Register
HRCNFG	0x6820	0x6860	0x68A0	0x68E0	1 / 0	HRPWM Configuration Register(1)
HRPWR	0x6821	-	-	-	1 / 0	HRPWM Power Register
HRMSTEP	0x6826	-	-	-	1 / 0	HRPWM MEP Step Register
HRPCTL	0x6828	0x6868	0x68A8	0x68E8	1 / 0	High resolution Period Control Register(1)
TBPRDHRM	0x682A	0x686A	0x68AA	0x68EA	1 / W(2)	Time Base Period HRPWM Register Mirror
TBPRDM	0x682B	0x686B	0x68AB	0x68EB	1 / W(2)	Time Base Period Register Mirror
CMPAHRM	0x682C	0x686C	0x68AC	0x68EC	1 / W(2)	Compare A HRPWM Register Mirror
CMPAM	0x682D	0x686D	0x68AD	0x68ED	1 / W(2)	Compare A Register Mirror
DCTRIPSEL	0x6830	0x6870	0x68B0	0x68F0	1 / 0	Digital Compare Trip Select Register (1)
DCACTL	0x6831	0x6871	0x68B1	0x68F1	1 / 0	Digital Compare A Control Register(1)
DCBCTL	0x6832	0x6872	0x68B2	0x68F2	1 / 0	Digital Compare B Control Register(1)
DCFCTL	0x6833	0x6873	0x68B3	0x68F3	1 / 0	Digital Compare Filter Control Register(1)

表 9-27. ePWM Control and Status Registers (continued)

NAME	ePWM1	ePWM2	ePWM3	ePWM4	SIZE (x16) / #SHADOW	DESCRIPTION
DCCAPCT	0x6834	0x6874	0x68B4	0x68F4	1 / 0	Digital Compare Capture Control Register(1)
DCFOFFSET	0x6835	0x6875	0x68B5	0x68F5	1 / 1	Digital Compare Filter Offset Register
DCFOFFSETCNT	0x6836	0x6876	0x68B6	0x68F6	1 / 0	Digital Compare Filter Offset Counter Register
DCFWINDOW	0x6837	0x6877	0x68B7	0x68F7	1 / 0	Digital Compare Filter Window Register
DCFWINDOWCNT	0x6838	0x6878	0x68B8	0x68F8	1 / 0	Digital Compare Filter Window Counter Register
DCCAP	0x6839	0x6879	0x68B9	0x68F9	1 / 1	Digital Compare Counter Capture Register

(1) Registers that are EALLOW protected.
(2) W = Write to shadow register



A. These events are generated by the Type 1 ePWM digital compare (DC) submodule based on the levels of the COMPxOUT and $\overline{TZ}$ signals.

图 9-36. ePWM Submodules Showing Critical Internal Signal Interconnections

9.9.6.1 ePWM 电气数据/时序

PWM 是指 ePWM1-4 上的 PWM 输出。节 9.9.6.1.1 显示了 PWM 时序要求和节 9.9.6.1.2，开关特性。

9.9.6.1.1 ePWM Timing Requirements

			MIN(1)	MAX	UNIT
$t_{w(SYCIN)}$	Sync input pulse width	Asynchronous	$2t_{c(SCO)}$		cycles
		Synchronous	$2t_{c(SCO)}$		cycles
		With input qualifier	$1t_{c(SCO)} + t_{w(IQSW)}$		cycles

(1) For an explanation of the input qualifier parameters, see 节 9.9.10.1.2.1.

9.9.6.1.2 ePWM 开关特性

在推荐的运行条件下（除非另有说明）

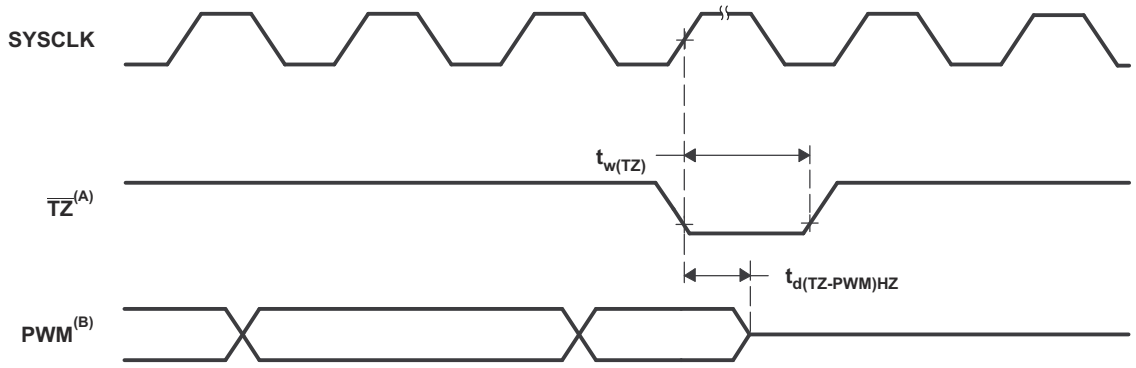
参数		测试条件	最小值	最大值	单位
$t_{w(PWM)}$	脉冲持续时间，PWMx 输出高电平/低电平的时间		33.33		ns
$t_{w(SYNCOUT)}$	同步输出脉冲宽度		$8t_{c(SCO)}$		周期
$t_{d(PWM)tza}$	延迟时间，跳闸有源输入到 PWM 强制高电平 延迟时间，跳闸有源输入到 PWM 强制低电平	无引脚负载		25	ns
$t_{d(TZ-PWM)HZ}$	延迟时间，触发输入有效至 PWM 高阻抗 (Hi-Z) 的时间			20	ns

9.9.6.2 触发区输入时序

9.9.6.2.1 Trip-Zone Input Timing Requirements

			MIN(1)	MAX	UNIT
$t_{w(TZ)}$	Pulse duration, $\overline{TZ}$x input low	Asynchronous	$2t_{c(TBCLK)}$		cycles
		Synchronous	$2t_{c(TBCLK)}$		cycles
		With input qualifier	$2t_{c(TBCLK)} + t_{w(IQSW)}$		cycles

(1) For an explanation of the input qualifier parameters, see 节 9.9.10.1.2.1.



A. $\overline{TZ}$ - $\overline{TZ1}$, $\overline{TZ2}$, $\overline{TZ3}$

B. PWM refers to all the PWM pins in the device. The state of the PWM pins after $\overline{TZ}$ is taken high depends on the PWM recovery software.

图 9-37. PWM Hi-Z Characteristics

9.9.7 High-Resolution PWM (HRPWM)

This module combines multiple delay lines in a single module and a simplified calibration system by using a dedicated calibration delay line. For each ePWM module there is one HR delay line.

The HRPWM module offers PWM resolution (time granularity) that is significantly better than what can be achieved using conventionally derived digital PWM methods. The key points for the HRPWM module are:

- Significantly extends the time resolution capabilities of conventionally derived digital PWM
- This capability can be used in both single edge (duty cycle and phase-shift control) as well as dual edge control for frequency/period modulation.
- Finer time granularity control or edge positioning is controlled through extensions to the Compare A and Phase registers of the ePWM module.
- HRPWM capabilities, when available on a particular device, are offered only on the A signal path of an ePWM module (that is, on the EPWMxA output). EPWMxB output has conventional PWM capabilities.

备注

The minimum SYSCLKOUT frequency allowed for HRPWM is 50 MHz.

备注

When dual-edge high-resolution is enabled (high-resolution period mode), the PWMxB output is not available for use.

9.9.7.1 HRPWM 电气数据/时序

节 9.9.7.1.1 显示了高分辨率 PWM 的开关特性。

9.9.7.1.1 SYSCLKOUT = 50MHz – 60MHz 下的高分辨率 PWM 特性

参数(1)	最小值	典型值	最大值	单位
微边沿定位 (MEP) 步长(2)		150	310	ps

(1) HRPWM 运行在一个最少 50MHz 的 SYSCLKOUT 频率上。低于 50MHz，在器件过程变化时，MEP 阶跃尺寸有可能下降至低于冷却温度并且高内核电压达到一个要求的值以至于 255 MEP 阶跃将不能跨过整个 SYSCLKOUT 周期。

(2) 在高温和 V_{DD} 上的电压最低时，MEP 步长将达到最大。MEP 步长会随温度升高和电压降低而增加，同时随温度降低和电压升高而减小。
使用 HRPWM 特性的应用应该使用 MEP 比例因子优化器 (SFO) 估计软件功能。有关在最终应用中使用 SFO 函数的详细信息，请参阅 TI 软件库。SFO 函数有助于在 HRPWM 运行时动态地估计每个 SYSCLKOUT 周期内的 MEP 步数量。

9.9.8 Enhanced Capture Module (eCAP1)

The device contains an enhanced capture (eCAP) module. 图 9-38 shows a functional block diagram of a module.

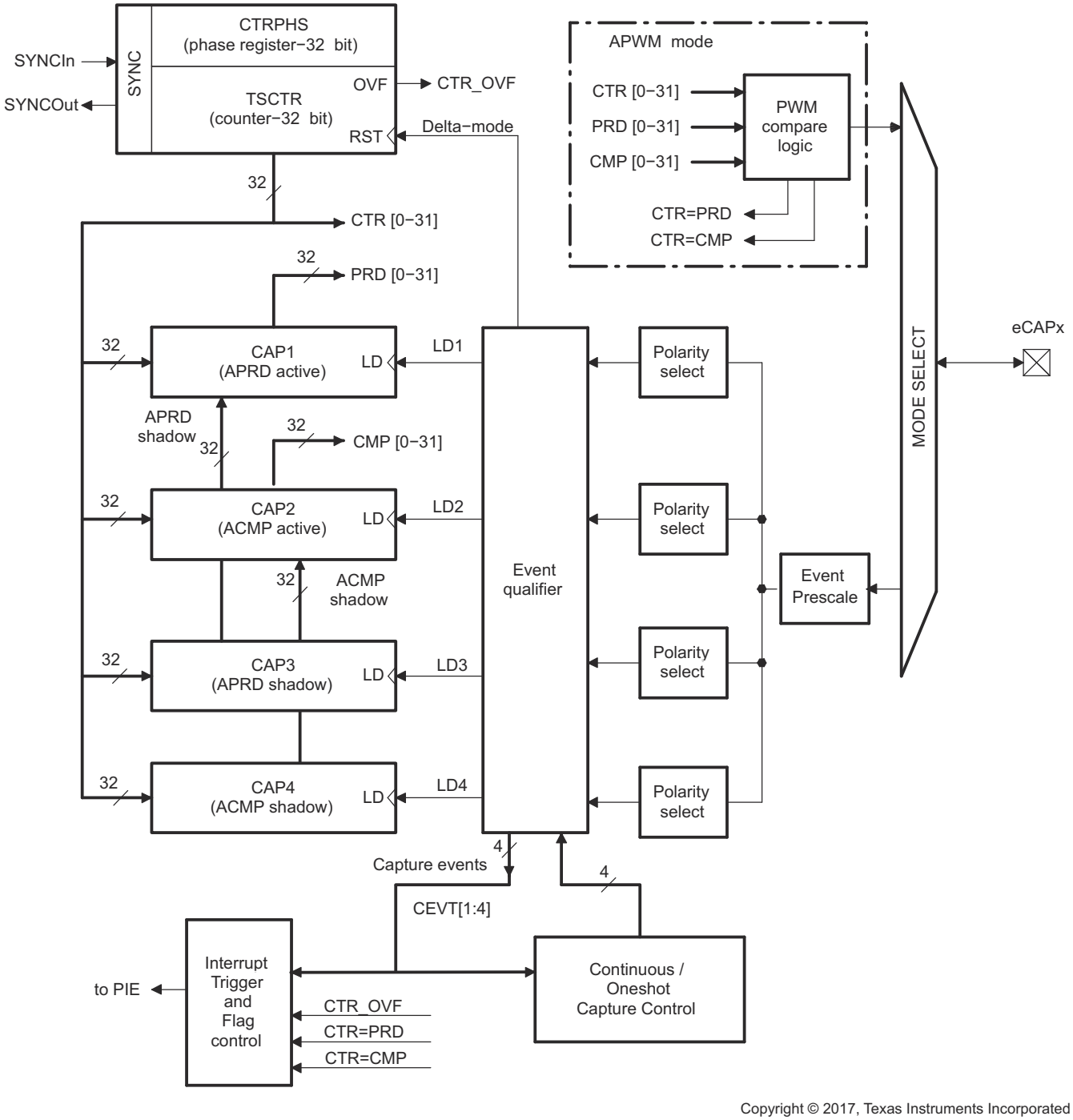


图 9-38. eCAP Functional Block Diagram

The eCAP module is clocked at the SYSCLKOUT rate.

The clock enable bits (ECAP1 ENCLK) in the PCLKCR1 register turn off the eCAP module individually (for low-power operation). Upon reset, ECAP1ENCLK is set to low, indicating that the peripheral clock is off.

表 9-28. eCAP Control and Status Registers

NAME	eCAP1	SIZE (x16)	EALLOW PROTECTED	DESCRIPTION
TSCTR	0x6A00	2		Time-Stamp Counter
CTRPHS	0x6A02	2		Counter Phase Offset Value Register
CAP1	0x6A04	2		Capture 1 Register
CAP2	0x6A06	2		Capture 2 Register
CAP3	0x6A08	2		Capture 3 Register
CAP4	0x6A0A	2		Capture 4 Register
Reserved	0x6A0C to 0x6A12	8		Reserved
ECCTL1	0x6A14	1		Capture Control Register 1
ECCTL2	0x6A15	1		Capture Control Register 2
ECEINT	0x6A16	1		Capture Interrupt Enable Register
ECFLG	0x6A17	1		Capture Interrupt Flag Register
ECCLR	0x6A18	1		Capture Interrupt Clear Register
ECFRC	0x6A19	1		Capture Interrupt Force Register
Reserved	0x6A1A to 0x6A1F	6		Reserved

For more information on the eCAP, see the Enhanced Capture (eCAP) Module chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

9.9.8.1 eCAP 电气数据/时序

节 9.9.8.1.1 显示了 eCAP 时序要求，而节 9.9.8.1.2 显示了 eCAP 开关特性。

9.9.8.1.1 Enhanced Capture (eCAP) Timing Requirement

			MIN(1) MAX	UNIT
$t_{w(CAP)}$	Capture input pulse width	Asynchronous	$2t_{c(SCO)}$	cycles
		Synchronous	$2t_{c(SCO)}$	cycles
		With input qualifier	$1t_{c(SCO)} + t_{w(IQSW)}$	cycles

(1) For an explanation of the input qualifier parameters, see 节 9.9.10.1.2.1.

9.9.8.1.2 eCAP 开关特性

在推荐的运行条件下（除非额外注明）

参数		测试条件	最小值 最大值	单位
$t_{w(APWM)}$	脉冲持续时间，APWMx 输出高电平/低电平的时间		20	ns

9.9.9 JTAG 端口

在 2802x 器件上，JTAG 端口减少到 5 个引脚（$\overline{\text{TRST}}$、TCK、TDI、TMS、TDO）。TCK、TDI、TMS 和 TDO 引脚也是 GPIO 引脚。$\overline{\text{TRST}}$ 信号在图 9-39 中为引脚选择 JTAG 或者 GPIO 运行模式。在仿真/调试期间，这些引脚的 GPIO 功能并不可用。如果 GPIO38/TCK/XCLKIN 引脚用于提供外部时钟，则应使用替代时钟源在仿真/调试期间为器件计时，这是因为 TCK 功能需要此引脚。

备注

在 2802x 器件中，JTAG 引脚也可被用作 GPIO 引脚。在电路板设计时应该小心以确保连接到这些引脚的电路不会影响 JTAG 引脚功能的仿真能力。要进行成功调试，连接到这些引脚的任何电路不应导致 JTAG 调试探针无法驱动 JTAG 引脚（或无法受其驱动）。

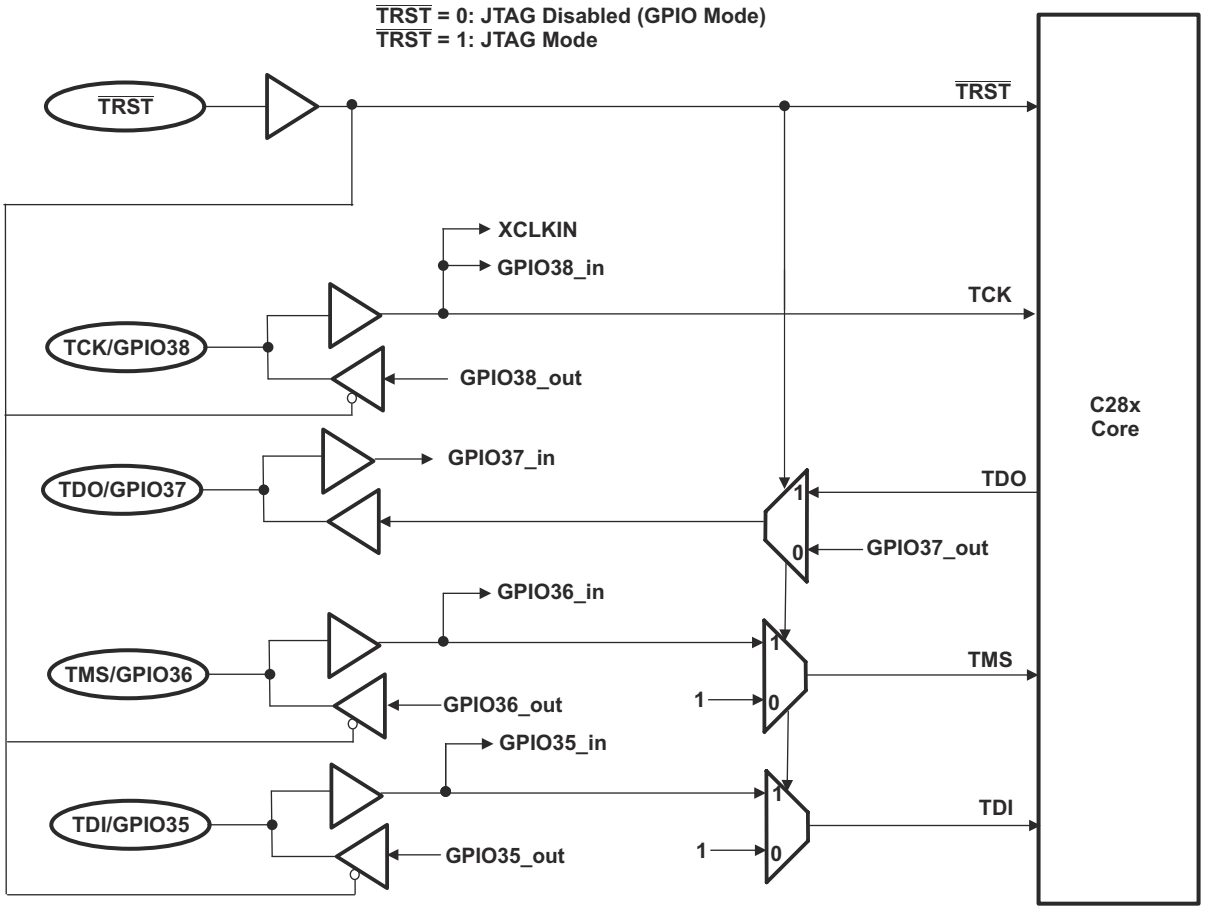


图 9-39. JTAG/GPIO 多路复用

9.9.10 General-Purpose Input/Output (GPIO) MUX

The GPIO MUX can multiplex up to three independent peripheral signals on a single GPIO pin in addition to providing individual pin bit-banging I/O capability.

The device supports 22 GPIO pins. The GPIO control and data registers are mapped to Peripheral Frame 1 to enable 32-bit operations on the registers (along with 16-bit operations). 表 9-29 shows the GPIO register mapping.

表 9-29. GPIO Registers

NAME	ADDRESS	SIZE (x16)	DESCRIPTION
GPIO CONTROL REGISTERS (EALLOW PROTECTED)			
GPACTRL	0x6F80	2	GPIO A Control Register (GPIO0 to 31)
GPAQSEL1	0x6F82	2	GPIO A Qualifier Select 1 Register (GPIO0 to 15)
GPAQSEL2	0x6F84	2	GPIO A Qualifier Select 2 Register (GPIO16 to 31)
GPAMUX1	0x6F86	2	GPIO A MUX 1 Register (GPIO0 to 15)
GPAMUX2	0x6F88	2	GPIO A MUX 2 Register (GPIO16 to 31)
GPADIR	0x6F8A	2	GPIO A Direction Register (GPIO0 to 31)
GPAPUD	0x6F8C	2	GPIO A Pullup Disable Register (GPIO0 to 31)
GPBCTRL	0x6F90	2	GPIO B Control Register (GPIO32 to 38)
GPBQSEL1	0x6F92	2	GPIO B Qualifier Select 1 Register (GPIO32 to 38)
GPBMUX1	0x6F96	2	GPIO B MUX 1 Register (GPIO32 to 38)
GPBDIR	0x6F9A	2	GPIO B Direction Register (GPIO32 to 38)
GPBPUD	0x6F9C	2	GPIO B Pullup Disable Register (GPIO32 to 38)
AIOMUX1	0x6FB6	2	Analog, I/O mux 1 register (AIO0 to AIO15)
AIODIR	0x6FBA	2	Analog, I/O Direction Register (AIO0 to AIO15)
GPIO DATA REGISTERS (NOT EALLOW PROTECTED)			
GPADAT	0x6FC0	2	GPIO A Data Register (GPIO0 to 31)
GPASET	0x6FC2	2	GPIO A Data Set Register (GPIO0 to 31)
GPACLEAR	0x6FC4	2	GPIO A Data Clear Register (GPIO0 to 31)
GPATOGGLE	0x6FC6	2	GPIO A Data Toggle Register (GPIO0 to 31)
GPBDAT	0x6FC8	2	GPIO B Data Register (GPIO32 to 38)
GPBSET	0x6FCA	2	GPIO B Data Set Register (GPIO32 to 38)
GPBCLEAR	0x6FCC	2	GPIO B Data Clear Register (GPIO32 to 38)
GPBTOGGLE	0x6FCE	2	GPIO B Data Toggle Register (GPIO32 to 38)
AIODAT	0x6FD8	2	Analog I/O Data Register (AIO0 to AIO15)
AIOSET	0x6FDA	2	Analog I/O Data Set Register (AIO0 to AIO15)
AIOCLEAR	0x6FDC	2	Analog I/O Data Clear Register (AIO0 to AIO15)
AIOTOGGLE	0x6FDE	2	Analog I/O Data Toggle Register (AIO0 to AIO15)
GPIO INTERRUPT AND LOW-POWER MODES SELECT REGISTERS (EALLOW PROTECTED)			
GPIOXINT1SEL	0x6FE0	1	XINT1 GPIO Input Select Register (GPIO0 to 31)
GPIOXINT2SEL	0x6FE1	1	XINT2 GPIO Input Select Register (GPIO0 to 31)
GPIOXINT3SEL	0x6FE2	1	XINT3 GPIO Input Select Register (GPIO0 to 31)
GPIOLPMSEL	0x6FE8	2	LPM GPIO Select Register (GPIO0 to 31)

备注

There is a two-SYSCLKOUT cycle delay from when the write to the GPxMUXn/AIOMUXn and GPxQSELn registers occurs to when the action is valid.

表 9-30. GPIOA MUX

	DEFAULT AT RESET PRIMARY I/O FUNCTION(1) (2)	PERIPHERAL SELECTION 1	PERIPHERAL SELECTION 2	PERIPHERAL SELECTION 3
GPAMUX1 REGISTER BITS	**(GPAMUX1 BITS = 00)**	**(GPAMUX1 BITS = 01)**	**(GPAMUX1 BITS = 10)**	**(GPAMUX1 BITS = 11)**
1-0	GPIO0	EPWM1A (O)	Reserved	Reserved
3-2	GPIO1	EPWM1B (O)	Reserved	COMP1OUT (O)
5-4	GPIO2	EPWM2A (O)	Reserved	Reserved
7-6	GPIO3	EPWM2B (O)	Reserved	COMP2OUT(3) (O)
9-8	GPIO4	EPWM3A (O)	Reserved	Reserved
11-10	GPIO5	EPWM3B (O)	Reserved	ECAP1 (I/O)
13-12	GPIO6	EPWM4A (O)	EPWMSYNCI (I)	EPWMSYNCO (O)
15-14	GPIO7	EPWM4B (O)	SCIRXDA (I)	Reserved
17-16	Reserved	Reserved	Reserved	Reserved
19-18	Reserved	Reserved	Reserved	Reserved
21-20	Reserved	Reserved	Reserved	Reserved
23-22	Reserved	Reserved	Reserved	Reserved
25-24	GPIO12	$\overline{TZ1}$ (I)	SCITXDA (O)	Reserved
27-26	Reserved	Reserved	Reserved	Reserved
29-28	Reserved	Reserved	Reserved	Reserved
31-30	Reserved	Reserved	Reserved	Reserved
GPAMUX2 REGISTER BITS	**(GPAMUX2 BITS = 00)**	**(GPAMUX2 BITS = 01)**	**(GPAMUX2 BITS = 10)**	**(GPAMUX2 BITS = 11)**
1-0	GPIO16	SPISIMOA (I/O)	Reserved	$\overline{TZ2}$ (I)
3-2	GPIO17	SPISOMIA (I/O)	Reserved	$\overline{TZ3}$ (I)
5-4	GPIO18	SPICLKA (I/O)	SCITXDA (O)	XCLKOUT (O)
7-6	GPIO19/XCLKIN	$\overline{SPISTEA}$ (I/O)	SCIRXDA (I)	ECAP1 (I/O)
9-8	Reserved	Reserved	Reserved	Reserved
11-10	Reserved	Reserved	Reserved	Reserved
13-12	Reserved	Reserved	Reserved	Reserved
15-14	Reserved	Reserved	Reserved	Reserved
17-16	Reserved	Reserved	Reserved	Reserved
19-18	Reserved	Reserved	Reserved	Reserved
21-20	Reserved	Reserved	Reserved	Reserved
23-22	Reserved	Reserved	Reserved	Reserved
25-24	GPIO28	SCIRXDA (I)	SDAA (I/OD)	$\overline{TZ2}$ (I)
27-26	GPIO29	SCITXDA (O)	SCLA (I/OD)	$\overline{TZ3}$ (I)
29-28	Reserved	Reserved	Reserved	Reserved
31-30	Reserved	Reserved	Reserved	Reserved

(1) The word reserved means that there is no peripheral assigned to this GPxMUX1/2 register setting. Should it be selected, the state of the pin will be undefined and the pin may be driven. This selection is a reserved configuration for future expansion.
(2) I = Input, O = Output, OD = Open Drain
(3) These functions are not available in the 38-pin package.

表 9-31. GPIOB MUX

	DEFAULT AT RESET PRIMARY I/O FUNCTION(1)	PERIPHERAL SELECTION 1	PERIPHERAL SELECTION 2	PERIPHERAL SELECTION 3
GPBMUX1 REGISTER BITS	(GPBMUX1 BITS = 00)	(GPBMUX1 BITS = 01)	(GPBMUX1 BITS = 10)	(GPBMUX1 BITS = 11)
1-0	GPIO32(2)	SDAA(2) (I/OD)	EPWMSYNCI(2) (I)	$\overline{\text{ADCSOCAO}}$ (2) (O)
3-2	GPIO33(2)	SCLA(2) (I/OD)	EPWMSYNCO(2) (O)	$\overline{\text{ADCSOCBO}}$ (2) (O)
5-4	GPIO34	COMP2OUT (O)	Reserved	Reserved
7-6	GPIO35 (TDI)	Reserved	Reserved	Reserved
9-8	GPIO36 (TMS)	Reserved	Reserved	Reserved
11-10	GPIO37 (TDO)	Reserved	Reserved	Reserved
13-12	GPIO38/XCLKIN (TCK)	Reserved	Reserved	Reserved
15-14	Reserved	Reserved	Reserved	Reserved
17-16	Reserved	Reserved	Reserved	Reserved
19-18	Reserved	Reserved	Reserved	Reserved
21-20	Reserved	Reserved	Reserved	Reserved
23-22	Reserved	Reserved	Reserved	Reserved
25-24	Reserved	Reserved	Reserved	Reserved
27-26	Reserved	Reserved	Reserved	Reserved
29-28	Reserved	Reserved	Reserved	Reserved
31-30	Reserved	Reserved	Reserved	Reserved

(1) I = Input, O = Output, OD = Open Drain
(2) These pins are not available in the 38-pin package.

表 9-32. Analog MUX for 48-Pin PT Package

		DEFAULT AT RESET(1)
	AIOx AND PERIPHERAL SELECTION 1	PERIPHERAL SELECTION 2 AND PERIPHERAL SELECTION 3
AIOMUX1 REGISTER BITS	AIOMUX1 BITS = 0,x	AIOMUX1 BITS = 1,x
1-0	ADCINA0 (I), V_{REFHI} (I)	ADCINA0 (I), V_{REFHI} (I)
3-2	ADCINA1 (I)	ADCINA1 (I)
5-4	AIO2 (I/O)	ADCINA2 (I), COMP1A (I)
7-6	ADCINA3 (I)	ADCINA3 (I)
9-8	AIO4 (I/O)	ADCINA4 (I), COMP2A (I)
11-10	–	–
13-12	AIO6 (I/O)	ADCINA6 (I)
15-14	ADCINA7 (I)	ADCINA7 (I)
17-16	–	–
19-18	ADCINB1 (I)	ADCINB1 (I)
21-20	AIO10 (I/O)	ADCINB2 (I), COMP1B (I)
23-22	ADCINB3 (I)	ADCINB3 (I)
25-24	AIO12 (I/O)	ADCINB4 (I), COMP2B (I)
27-26	–	–
29-28	AIO14 (I/O)	ADCINB6 (I)
31-30	ADCINB7 (I)	ADCINB7 (I)

(1) I = Input, O = Output

表 9-33. Analog MUX for 38-Pin DA Package

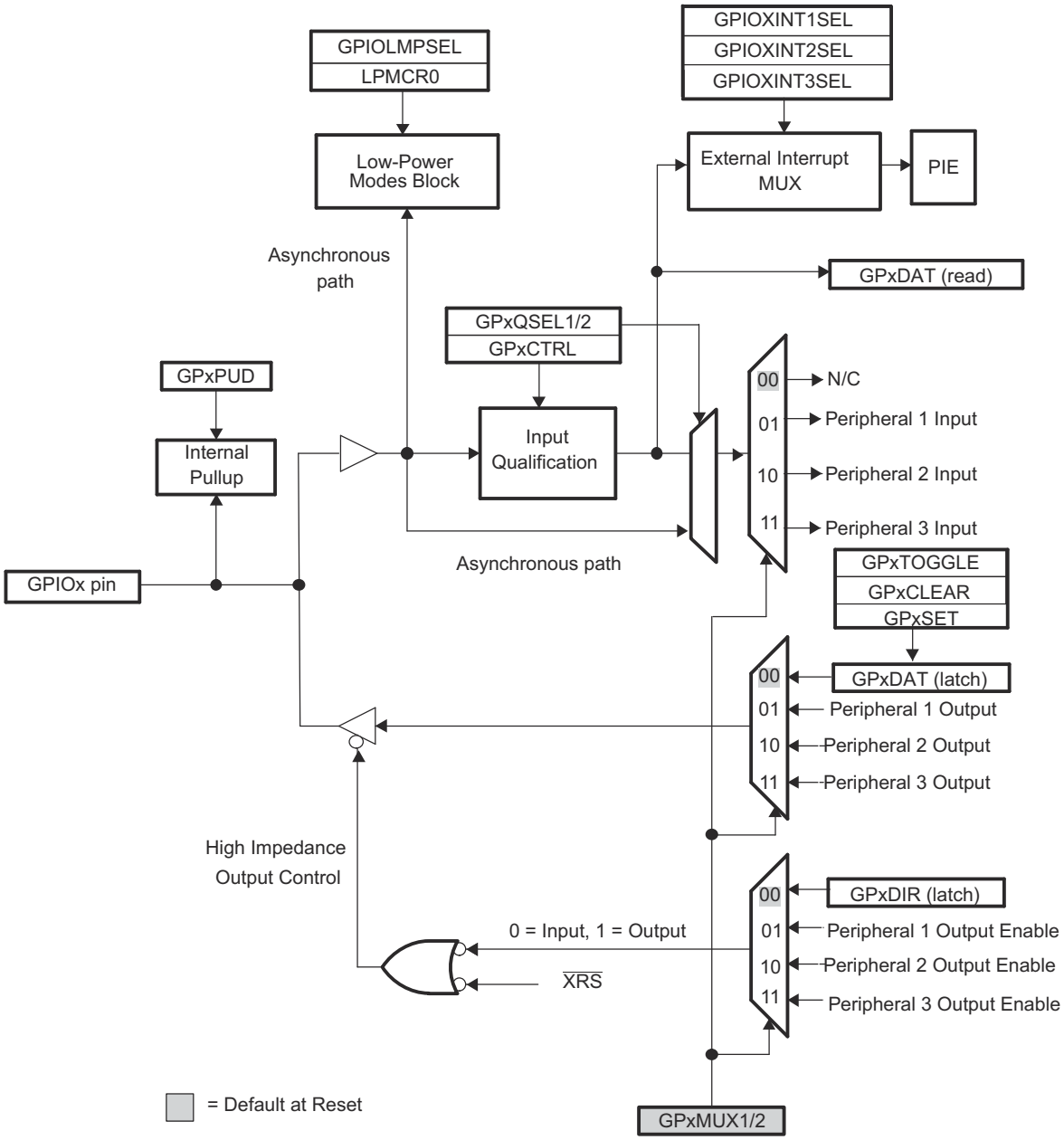
		DEFAULT AT RESET(1)
	AIOx AND PERIPHERAL SELECTION 1	PERIPHERAL SELECTION 2 AND PERIPHERAL SELECTION 3
AIOMUX1 REGISTER BITS	AIOMUX1 BITS = 0,x	AIOMUX1 BITS = 1,x
1-0	ADCINA0 (I), V_{REFHI} (I)	ADCINA0 (I), V_{REFHI} (I)
3-2	–	–
5-4	AIO2 (I/O)	ADCINA2 (I), COMP1A (I)
7-6	–	–
9-8	AIO4 (I/O)	ADCINA4 (I)
11-10	–	–
13-12	AIO6 (I/O)	ADCINA6 (I)
15-14	–	–
17-16	–	–
19-18	–	–
21-20	AIO10 (I/O)	ADCINB2 (I), COMP1B (I)
23-22	–	–
25-24	AIO12 (I/O)	ADCINB4 (I)
27-26	–	–
29-28	AIO14 (I/O)	ADCINB6 (I)
31-30	–	–

(1) I = Input, O = Output

The user can select the type of input qualification for each GPIO pin through the GPxQSEL1/2 registers from four choices:

- Synchronization To SYSCLKOUT Only (GPxQSEL1/2 = 0, 0): This is the default mode of all GPIO pins at reset and it simply synchronizes the input signal to the system clock (SYSCLKOUT).
- Qualification Using Sampling Window (GPxQSEL1/2 = 0, 1 and 1, 0): In this mode the input signal, after synchronization to the system clock (SYSCLKOUT), is qualified by a specified number of cycles before the input is allowed to change.
- The sampling period is specified by the QUALPRD bits in the GPxCTRL register and is configurable in groups of 8 signals. It specifies a multiple of SYSCLKOUT cycles for sampling the input signal. The sampling window is either 3-samples or 6-samples wide and the output is only changed when ALL samples are the same (all 0s or all 1s) as shown in 图 9-42 (for 6 sample mode).
- No Synchronization (GPxQSEL1/2 = 1,1): This mode is used for peripherals where synchronization is not required (synchronization is performed within the peripheral).

Due to the multilevel multiplexing that is required on the device, there may be cases where a peripheral input signal can be mapped to more then one GPIO pin. Also, when an input signal is not selected, the input signal will default to either a 0 or 1 state, depending on the peripheral.



A. x stands for the port, either A or B. For example, GPxDIR refers to either the GPADIR and GPBDIR register depending on the particular GPIO pin selected.

B. GPxDAT latch/read are accessed at the same memory location.

C. This is a generic GPIO MUX block diagram. Not all options may be applicable for all GPIO pins. For pin-specific variations, see the System Control chapter in the *TMS320F2802x,TMS320F2802xx Technical Reference Manual*.

图 9-40. GPIO Multiplexing

9.9.10.1 GPIO 电气数据/时序

9.9.10.1.1 GPIO - 输出时序

9.9.10.1.1.1 通用输出开关特性

在推荐的运行条件下 (除非另有说明)

参数			最小值	最大值	单位
$t_{r(GPO)}$	上升时间，GPIO 从低电平切换至高电平的时间	所有 GPIO		13(1)	ns
$t_{f(GPO)}$	下降时间，GPIO 从高电平切换至低电平的时间	所有 GPIO		13(1)	ns
t_{fGPO}	切换频率			15	MHz

(1) 上升时间和下降时间随着 I/O 引脚上的电力负荷变化。节 9.9.10.1.1.1 中指定的值适用于一个 I/O 引脚上的 40pF 负载。

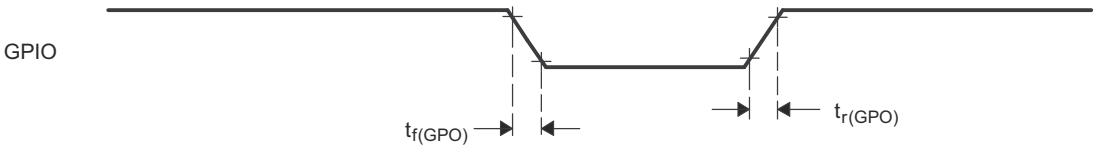


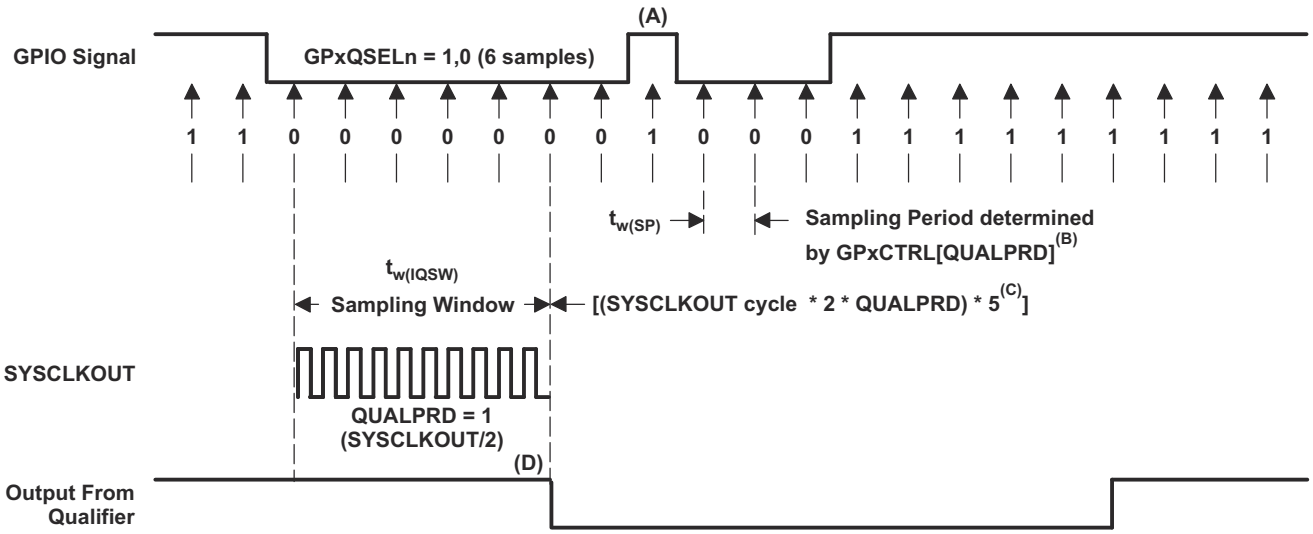
图 9-41. 通用输出定时

9.9.10.1.2 GPIO - 输入时序

9.9.10.1.2.1 通用输入时序要求

			最小值 最大值	单位
$t_{w(SP)}$	采样周期	QUALPRD=0	$1t_{c(SCO)}$	周期
		QUALPRD≠0	$2t_{c(SCO)}$*QUALPRD	周期
$t_{w(IQSW)}$	输入限定器采样窗口		$t_{w(SP)}$*(n(1)-1)	周期
$t_{w(GPI)}$ (2)	脉冲持续时间，GPIO 低电平/高电平的时间	同步模式	$2t_{c(SCO)}$	周期
		带输入限定器	$t_{w(IQSW)} + t_{w(SP)} + 1t_{c(SCO)}$	周期

(1) "n" 代表由 GPxQSELn 寄存器定义的限定采样的数量。
(2) 对于 $t_{w(GPI)}$，对于一个低电平有效信号，脉宽在 V_{IL} 至 V_{IL} 之间进行测量，而对于一个高电平有效信号脉宽在 V_{IH} 至 V_{IH} 之间进行测量。



A. 这个毛刺脉冲将被输入限定器所忽略。QUALPRD 位字段指定了限定采样周期。它可在 00 至 0xFF 间变化。如果 QUALPRD=00，那么采样周期为 1 个 SYSCLKOUT 周期。对于任何其它的 "n" 值，限定采样周期为 2n SYSCLKOUT 周期（也就是说，在每一个 SYSCLKOUT 周期上，GPIO 引脚将被采样）。
B. 通过 GPxCTRL 寄存器选择的限定期会应用于 8 个 GPIO 引脚的组。
C. 此限定块可采样 3 个或者 6 个样本。GPxQSELn 寄存器选择使用的采样模式。
D. 在所示的示例中，为了使限定器检测到变化，输入应该在 10 个 SYSCLKOUT 周期或者更长的时间内保持稳定。换句话说，输入应该在 (5 x QUALPRD x 2) SYSCLKOUT 周期内保持稳定。这将确保发生 5 个用于检测的采样周期。由于外部信号是异步驱动的，因此一个 13 SYSCLKOUT 宽的脉冲将会确保可靠识别。

图 9-42. 采样模式

9.9.10.1.3 针对输入信号的采样窗口宽度

下面的部分总结了不同的输入限定器配置下用于输入信号的采样窗口宽度。

采样频率表明相对于 SYSCLKOUT 的信号采样频率。

如果 QUALPRD≠0 的话，采样频率 = SYSCLKOUT/(2*QUALPRD)

如果 QUALPRD=0 的话，采样频率 = SYSCLKOUT

如果 QUALPRD≠0 的话，采样周期 = SYSCLKOUT 周期 x 2 x QUALPRD

在上面的等式中，SYSCLKOUT 周期表明 SYSCLKOUT 的时间周期。

如果 QUALPRD=0 的话，采样周期 = SYSCLKOUT 周期

在指定的采样窗口中，采取输入信号的 3 个样本或者 6 个样本来确定信号的有效性。这取决于写入 GPxQSELn 寄存器的值。

情况 1：

使用 3 个样本限定

如果 QUALPRD≠0 的话，采样窗口宽度 = (SYSCLKOUT 周期 x 2 x QUALPRD) × 2

如果 QUALPRD=0 的话，采样窗口宽度 = (SYSCLKOUT 周期) x 2

情况 2：

使用 6 个样本限定

如果 QUALPRD≠0 的话，采样窗口宽度 = (SYSCLKOUT 周期 x 2 x QUALPRD) × 5

如果 QUALPRD=0 的话，采样窗口宽度 = (SYSCLKOUT 周期) x 5

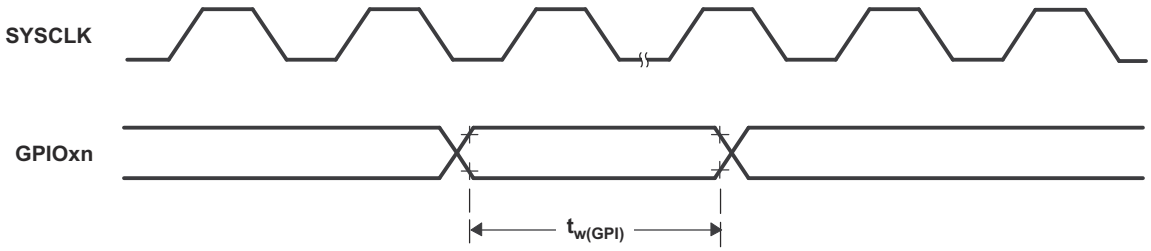


图 9-43. 通用输入时序

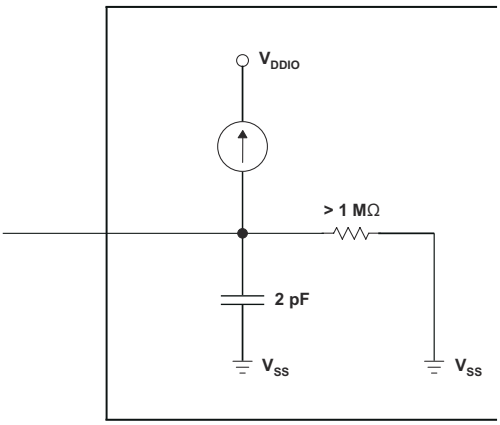


图 9-44. 针对带有内部上拉电阻的 GPIO 引脚的输入电阻模型

9.9.10.1.4 低功耗唤醒时序

节 9.9.10.1.4.1 显示时序要求，节 9.9.10.1.4.2 显示了开关特性，而图 9-45 显示了 IDEL 模式下的时序图

9.9.10.1.4.1 IDLE Mode Timing Requirements

			MIN(1) MAX	UNIT
$t_{w(WAKE-INT)}$	Pulse duration, external wake-up signal	Without input qualifier	$2t_{c(SCO)}$	cycles
		With input qualifier	$5t_{c(SCO)} + t_{w(IQSW)}$	

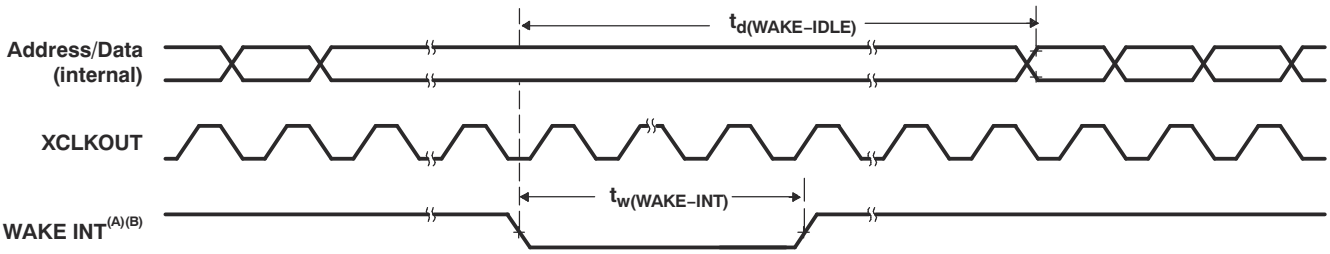
(1) For an explanation of the input qualifier parameters, see 节 9.9.10.1.2.1.

9.9.10.1.4.2 IDLE Mode Switching Characteristics

over recommended operating conditions (unless otherwise noted)

PARAMETER(1)		TEST CONDITIONS	MIN MAX	UNIT
$t_{d(WAKE-IDLE)}$	Delay time, external wake signal to program execution resume (2)			cycles
	• Wake up from Flash – Flash module in active state	Without input qualifier	$20t_{c(SCO)}$	cycles
		With input qualifier	$20t_{c(SCO)} + t_{w(IQSW)}$	
	• Wake up from Flash – Flash module in sleep state	Without input qualifier	$1050t_{c(SCO)}$	cycles
		With input qualifier	$1050t_{c(SCO)} + t_{w(IQSW)}$	
	• Wake up from SARAM	Without input qualifier	$20t_{c(SCO)}$	cycles
		With input qualifier	$20t_{c(SCO)} + t_{w(IQSW)}$	

(1) For an explanation of the input qualifier parameters, see 节 9.9.10.1.2.1.
(2) This is the time taken to begin execution of the instruction that immediately follows the IDLE instruction. Execution of an ISR (triggered by the wake-up signal) involves additional latency.



A. WAKE INT can be any enabled interrupt, $\overline{\text{WDINT}}$ or $\overline{\text{XRS}}$.
B. From the time the IDLE instruction is executed to place the device into low-power mode (LPM), wakeup should not be initiated until at least 4 OSCCLK cycles have elapsed.

图 9-45. IDLE Entry and Exit Timing

9.9.10.1.4.3 待机模式时序要求

			最小值	最大值	单位
$t_{w(WAKE-INT)}$	脉冲持续时间，外部唤醒信号的时间	无输入限定	$3t_{c(OSCCLK)}$		周期
		带输入限定(1)	(2 + QUALSTDBY) * $t_{c(OSCCLK)}$		

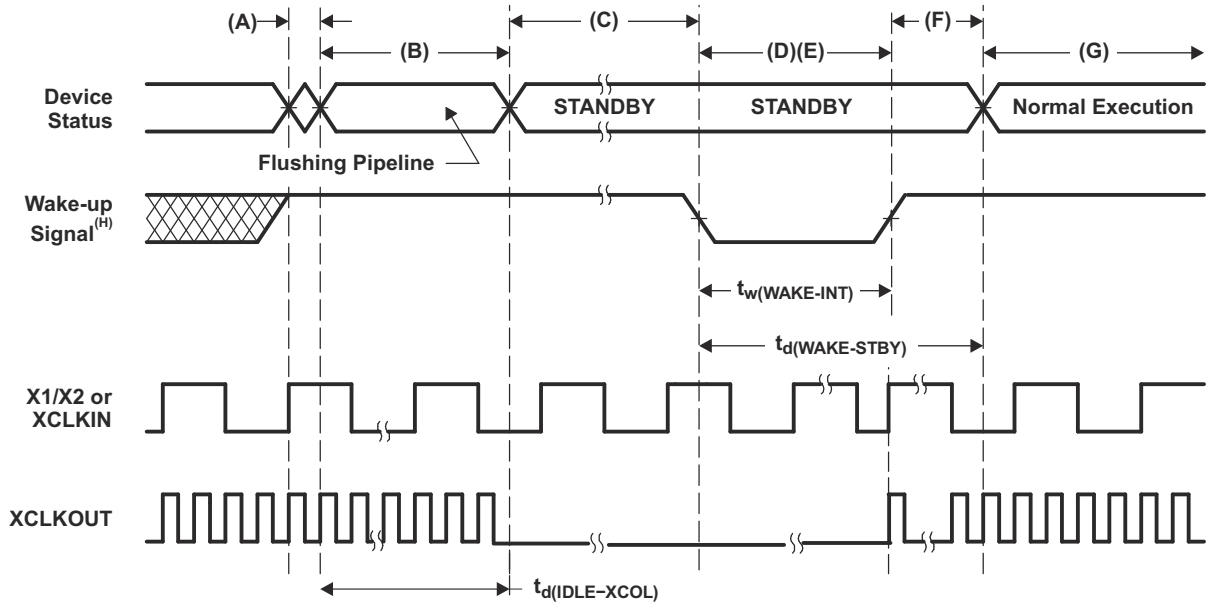
(1) QUALSTDBY 是 LPMCR0 寄存器中的一个 6 位字段。

9.9.10.1.4.4 待机模式开关特性

在推荐的运行条件下（除非另有说明）

参数		测试条件	最小值	最大值	单位
$t_{d(IDLE-XCOL)}$	延迟时间，IDLE 指令执行到 XCLKOUT 低电平的时间		$32t_{c(SCO)}$	$45t_{c(SCO)}$	周期
$t_{d(WAKE-STBY)}$	延迟时间，外部唤醒信号到程序执行重新开始的时间(1)				周期
	• 从闪存唤醒 – 激活状态中的闪存模块	无输入限定器		$100t_{c(SCO)}$	周期
		带输入限定器		$100t_{c(SCO)} + t_{w(WAKE-INT)}$	
	• 从闪存唤醒 – 睡眠状态中的闪存模块	无输入限定器		$1125t_{c(SCO)}$	周期
		带输入限定器		$1125t_{c(SCO)} + t_{w(WAKE-INT)}$	
	• 从 SARAM 中唤醒	无输入限定器		$100t_{c(SCO)}$	周期
		带输入限定器		$100t_{c(SCO)} + t_{w(WAKE-INT)}$	

(1) 这个时间是在 IDLE 指令之后立即开始指令执行的时间。ISR（由唤醒信号触发）的执行需要额外延迟。



A. 执行 IDLE 指令将器件置于待机模式。

B. PLL 块响应待机信号。SYSCLKOUT 在关闭之前保持以下所示数量的周期：
   - 当 DIVSEL=00 或 01 时，16 个周期
   - 当 DIVSEL=10 时，32 个周期
   - 当 DIVSEL=11 时，64 个周期

   此延迟使得 CPU 流水线和其他待定操作适当清除。

C. 外设的时钟关闭。然而，PLL 和看门狗未关闭。此器件现在处于待机模式。

D. 外部唤醒信号驱动为有效。

E. 为唤醒器件而馈送给 GPIO 引脚的唤醒信号必须符合最小脉冲宽度要求。此外，此信号不能有毛刺。如果噪声信号馈送到 GPIO 引脚，器件的唤醒行为将是不确定的并且在随后的唤醒脉冲中器件可能不会退出低功耗模式。

F. 在延迟周期后，退出待机模式。

G. 正常执行重新开始。器件将响应中断（如果启用）。

H. 自执行将器件置于低功耗模式 (LPM) 的 IDLE 指令开始，至少经历 4 个 OSCCLK 周期后才启动唤醒。

图 9-46. 待机进入和退出时序图

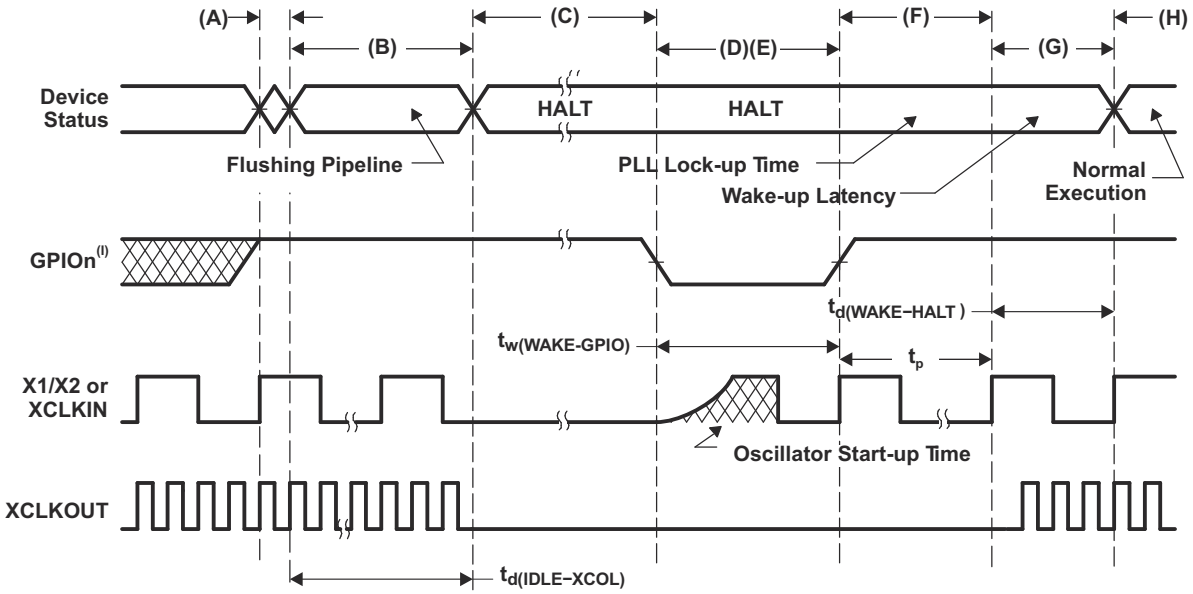
9.9.10.1.4.5 HALT Mode Timing Requirements

		MIN	MAX	UNIT
$t_{w(WAKE-GPIO)}$	Pulse duration, GPIO wake-up signal	$t_{oscst} + 2t_{c(OSCCLK)}$		cycles
$t_{w(WAKE-XRS)}$	Pulse duration, $\overline{XRS}$ wake-up signal	$t_{oscst} + 8t_{c(OSCCLK)}$		cycles

9.9.10.1.4.6 停机模式开关特性

在推荐的运行条件下（除非另有说明）

参数		最小值	最大值	单位
$t_{d(IDLE-XCOL)}$	延迟时间，IDLE 指令执行到 XCLKOUT 低电平的时间	$32t_{c(SCO)}$	$45t_{c(SCO)}$	周期
t_p	PLL 锁存时间		1	ms
$t_{d(WAKE-HALT)}$	延迟时间，PLL 锁存到程序执行重新开始的时间 • 从闪存唤醒 – 睡眠状态中的闪存模块		$1125t_{c(SCO)}$	周期
	• 从 SARAM 中唤醒		$35t_{c(SCO)}$	周期



A. IDLE 指令被执行以将器件置于停机模式。

B. PLL 块响应停机信号。在振荡器被关闭并且到内核的 CLKIN 被停止前 SYSCLKOUT 在下面所示的一定数量的周期内保持：

- 当 DIVSEL=00 或 01 时，16 个周期
- 当 DIVSEL=10 时，32 个周期
- 当 DIVSEL=11 时，64 个周期

此延迟使得 CPU 流水线和其他待定操作适当清除。

C. 到外设的时钟被关闭并且 PLL 被关断。如果一个石英晶振或者陶瓷谐振器被用作时钟源，内部振荡器也被关断。器件现在处于停机模式，消耗绝对最小功率。可在停机模式中保持零引脚内部振荡器（INTOSC1 和 INTOSC2）以及看门狗可用。可通过对 CLKCTL 寄存器中的适当位进行写入操作来实现此功能。

D. 当 GPIOn 引脚（用于使器件脱离停机模式）被驱动为低电平时，振荡器开启并且振荡器唤醒序列被启动。只有当振荡器稳定时，GPIO 才应被驱动为高电平。这样可在 PLL 锁序列期间提供一个洁净的时钟信号。由于 GPIO 引脚的下降边沿会以异步方式开始唤醒过程，因此在进入停机模式之前和在此模式期间，应该注意保持低噪声环境。

E. 为唤醒器件而馈送给 GPIO 引脚的唤醒信号必须符合最小脉冲宽度要求。此外，此信号不能有毛刺。如果噪声信号馈送到 GPIO 引脚，器件的唤醒行为将是不确定的并且在随后的唤醒脉冲中器件可能不会退出低功耗模式。

F. 一旦振荡器已经稳定，PLL 锁序列被启动（耗时 1ms）。

G. 当到内核的 CLKIN 被启用时，在一个延迟后，此器件响应此中断（如果被启用）。现在退出停机模式。

H. 正常运行重新开始。

I. 自执行将器件置于低功耗模式 (LPM) 的 IDLE 指令开始，至少经历 4 个 OSCCLK 周期后才启动唤醒。

图 9-47. 使用 GPIOn 唤醒停机模式

10 应用、实施和布局

备注

以下部分中的信息不属于 TI 器件规范，TI 不保证其准确性和完整性。TI 客户应负责确定这些元件是否适用于其应用。客户应验证并测试其设计实现，以确认系统功能。

10.1 TI 参考设计

TI 参考设计库是一个涵盖模拟、嵌入式处理器和连接的强大参考设计资源库。所有参考设计由 TI 专家构建，旨在帮助您快速开始系统设计，其中包括原理图或方框图、BOM 和设计文件，助您加快产品上市步伐。在精选 TI 参考设计页面上搜索并下载设计。

具有响应时间小于 1us 的堵转电流限制的 36V/1kW 无刷直流电机驱动器参考设计
此参考设计可用作电池供电式园艺工具和电动工具中无刷电机的功率级，额定功率高达 1kW，使用 10 节锂离子电池，电压范围为 36V 至 42V。设计采用 60V、N 沟道 NexFET™ 技术和 SON5x6 SMD 封装，具有极低的 1.8mΩ 漏源极电阻 (RDS_ON)，可实现 57mm × 59mm 的小尺寸 PCB。三相栅极驱动器用于驱动三相 MOSFET 电桥，该电桥可在 6V 至 60V 的电压范围内工作，支持可编程栅极电流（最高 2.3A 灌电流/1.7A 拉电流）。C2000 F28027 LaunchPad™ 开发套件 (LAUNCHXL-F28027) 与此功率级结合使用，并在软件中通过霍尔传感器实现对 BLDC 电机的 120 度梯形控制。栅极驱动器的逐周期电流限制特性将功率级中允许的最大电流限制到安全级别，从而保护电路板免受电机失速期间导致的过流损害。

使用磁通门传感器通过单端信号调节电路进行电流和电压测量
此设计为集成在微控制器中通过磁通门传感器测量电机电流的单端 SAR ADC 提供 4 通道信号调节解决方案。此外还提供带有外部 SAR ADC 的备选测量电路以及高速过流和接地故障检测电路。适当的信号调节可在电机驱动中提高关键电路测量的抗噪性能。此参考设计有助于增加模数转换的有效分辨率，提高电机驱动效率。

11 器件和文档支持

11.1 Device and Development Support Tool Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all TMS320™ MCU devices and support tools. Each TMS320 MCU commercial family member has one of three prefixes: TMX, TMP, or TMS (for example, **TMS**320F28023). Texas Instruments recommends two of three possible prefix designators for its support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX/TMDX) through fully qualified production devices/tools (TMS/TMDS).

Device development evolutionary flow:

TMX	Experimental device that is not necessarily representative of the final device's electrical specifications
TMP	Final silicon die that conforms to the device's electrical specifications but has not completed quality and reliability verification
TMS	Fully qualified production device

Support tool development evolutionary flow:

TMDX	Development-support product that has not yet completed Texas Instruments internal qualification testing
TMDS	Fully qualified development-support product

TMX and TMP devices and TMDX development-support tools are shipped against the following disclaimer: "Developmental product is intended for internal evaluation purposes."

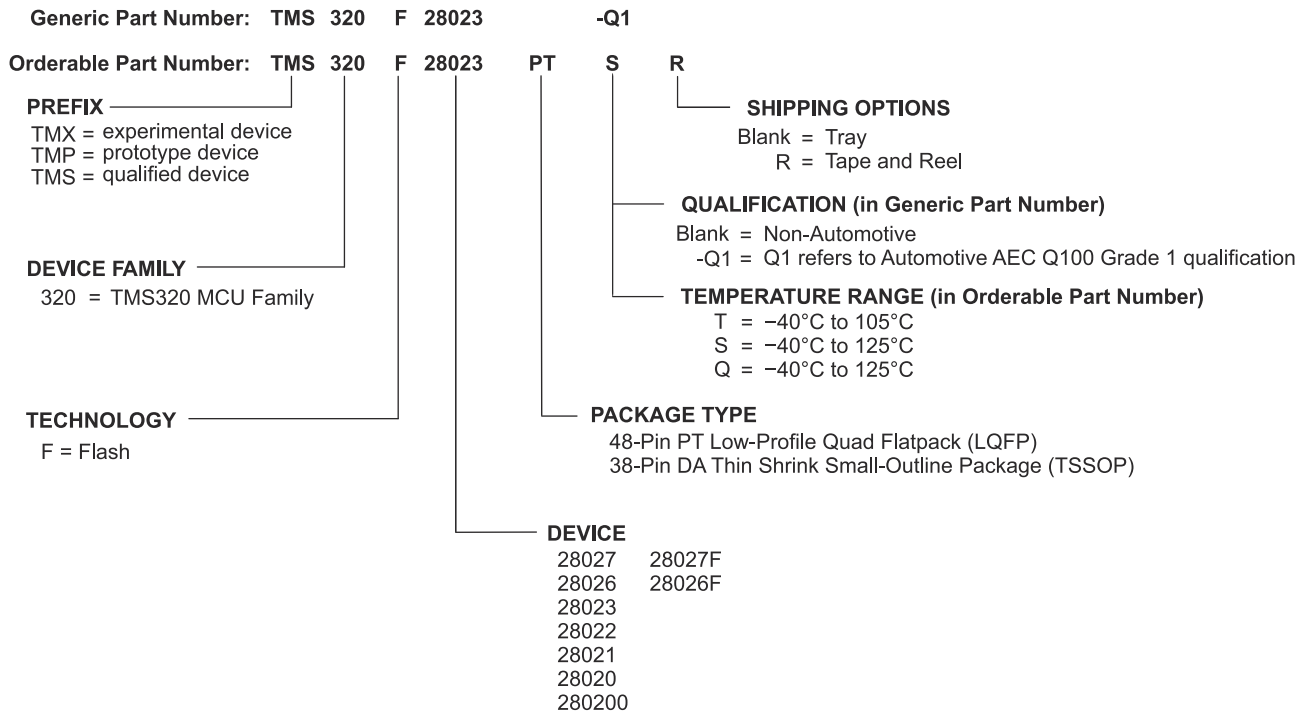
TMS devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (TMX or TMP) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the package type (for example, PT) and temperature range (for example, S). 图 11-1 provides a legend for reading the complete device name for any family member.

For device part numbers and further ordering information, see the TI website (www.ti.com) or contact your TI sales representative.

For additional description of the device nomenclature markings on the die, see the *TMS320F2802x, TMS320F2802xx MCUs Silicon Errata*.



A. For more information on peripheral, temperature, and package availability for a specific device, see 表 6-1.

图 11-1. Device Nomenclature

11.2 Tools and Software

TI offers an extensive line of development tools. Some of the tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below. To view all available tools and software for C2000™ real-time control MCUs, visit the C2000 real-time control MCUs – Design & development page.

Development Tools

Code Composer Studio (CCS) Integrated Development Environment (IDE) for C2000 Microcontrollers
Code Composer Studio is an integrated development environment (IDE) that supports TI's Microcontroller and Embedded Processors portfolio. CCS comprises a suite of tools used to develop and debug embedded applications. It includes an optimizing C/C++ compiler, source code editor, project build environment, debugger, profiler, and many other features. The intuitive IDE provides a single user interface taking you through each step of the application development flow. Familiar tools and interfaces allow users to get started faster than ever before. CCS combines the advantages of the Eclipse software framework with advanced embedded debug capabilities from TI resulting in a compelling feature-rich development environment for embedded developers.

C2000 F28027 LaunchPad™ development kit
The C2000 F28027 LaunchPad™ development kit is an inexpensive, modular, and fun evaluation platform, enabling you to dive into real-time, closed-loop control development with Texas Instruments' C2000 32-bit microcontroller family. This platform provides a great starting point for development of many common power electronics applications, including motor control, digital power supplies, solar inverters, digital LED lighting, precision sensing, and more.

To view all available C2000 LaunchPad development kits and BoosterPack™ plug-in modules, visit the Embedded development hardware kits & boards site.

Software Tools

powerSUITE - Digital Power Supply Design Software Tools for C2000™ MCUs

powerSUITE is a suite of digital power supply design software tools for Texas Instruments' C2000 real-time microcontroller (MCU) family. powerSUITE helps power supply engineers drastically reduce development time as they design digitally-controlled power supplies based on C2000 real-time control MCUs.

C2000Ware for C2000 MCUs

C2000Ware for C2000™ microcontrollers is a cohesive set of development software and documentation designed to minimize software development time. From device-specific drivers and libraries to device peripheral examples, C2000Ware provides a solid foundation to begin development and evaluation of your product.

UniFlash Standalone Flash Tool

UniFlash is a standalone tool used to program on-chip flash memory through a GUI, command line, or scripting interface.

Models

Various models are available for download from the product Tools & Software pages. These include I/O Buffer Information Specification (IBIS) Models and Boundary-Scan Description Language (BSDL) Models. To view all available models, visit the Models section of the Tools & Software page for each device.

Training

To help assist design engineers in taking full advantage of the C2000 microcontroller features and performance, TI has developed a variety of training resources. Utilizing the online training materials and downloadable hands-on workshops provides an easy means for gaining a complete working knowledge of the C2000 microcontroller family. These training resources have been designed to decrease the learning curve, while reducing development time, and accelerating product time to market. For more information on the various training resources, visit the C2000™ real-time control MCUs – Support & training site.

Specific TMS320F2802x hands-on training resources can be found at C2000™ MCU Device Workshops.

InstaSPIN-FOC LaunchPad and BoosterPack

This 6-part series provides information about the C2000 InstaSPIN-FOC Motor Control LaunchPad Development Kit and BoosterPack Plug-in Module.

The InstaSPIN-FOC enabled C2000 F28027 LaunchPad™ development kit is an inexpensive evaluation platform designed to help you leap right into the world of sensorless motor control using the InstaSPIN-FOC solution.

- Part 1: Introduction and Overview
- Part 2: Identifying Your Motor
- Part 3: Zero Speed, Low Speed, & Tuning
- Part 4: Accelerations & Speed Reversals with Texas Instruments
- Part 5: High, Higher, Highest Speeds with Texas Instruments
- BOOSTXL-DRV8301 BoosterPack with Texas Instruments

11.3 文档支持

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击右上角的*通知我*进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

下面列出了介绍处理器、相关外设以及其他配套技术资料的最新文档。

勘误

TMS320F2802x、TMS320F2802xx MCU 器件勘误表介绍了器件上的已知问题并提供了权变措施。

技术参考手册

TMS320F2802x、TMS320F2802xx 技术参考手册详述了器件中每一个外设和子系统的集成、环境、功能说明，以及编程模型。

InstaSPIN 技术参考手册

InstaSPIN-FOC™ 和 InstaSPIN-MOTION™ 用户指南介绍了 InstaSPIN-FOC 和 InstaSPIN-MOTION 器件。

TMS320F28026F、TMS320F28027F InstaSPIN™-FOC 软件技术参考手册介绍了 TMS320F28026F 和 TMS320F28027F InstaSPIN-FOC 软件。

CPU 用户指南

TMS320C28x CPU 和指令集参考指南描述了 TMS320C28x 定点数字信号处理器 (DSP) 的中央处理器 (CPU) 和汇编语言指令。此参考指南还介绍了上述 DSP 所提供的仿真特性。

外设指南

C2000 实时控制外设参考指南介绍了 28x 数字信号处理器 (DSP) 的外设参考指南。

工具指南

TMS320C28x 汇编语言工具 v20.2.0.LTS 用户指南介绍了用于 TMS320C28x 器件的汇编语言工具（用于开发汇编语言代码的汇编器和其他工具）、汇编器指令、宏、通用目标文件格式和符号调试指令。

TMS320C28x 优化 C/C++ 编译器 v20.2.0.LTS 用户指南介绍了 TMS320C28x C/C++ 编译器。此编译器接受 ANSI 标准 C/C++ 源代码，并为 TMS320C28x 器件生成 TMS320 DSP 汇编语言源代码。

应用报告

半导体封装方法介绍了准备半导体器件以发货给最终用户时所用的封装方法。

计算嵌入式处理器的有效使用寿命介绍了如何计算 TI 嵌入式处理器 (EP) 在电子系统中运行时的有效使用寿命。本文档的目标读者为希望确定 TI EP 的可靠性是否符合终端系统可靠性要求的总工程师。

半导体和 IC 封装热指标介绍了以前和更新的热指标，并将它们应用于系统级结温估算。

计算任务剖面的 FIT 说明了如何使用 TI 的可靠性降额工具计算系统任务剖面在加电条件下的元件级 FIT。

振荡器补偿指南介绍了一种为 内部振荡器补偿温度引起的频率漂移的工厂方法。

IBIS（I/O 缓冲器信息规范）建模简介讨论了 IBIS 的各个方面，包括其历史、优势、兼容性、模型生成流程、输入/输出结构建模中的数据要求以及未来趋势。

C2000™ 微控制器串行闪存编程讨论了如何使用闪存内核和 ROM 加载程序对器件进行串行编程。

11.4 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

11.5 商标

InstaSPIN-FOC™, TMS320C2000™, NexFET™, LaunchPad™, TMS320™, BoosterPack™, InstaSPIN-MOTION™, and TI E2E™ are trademarks of Texas Instruments.
I2C 总线® is a registered trademark of NXP B.V. Corporation.
所有商标均为其各自所有者的财产。

11.6 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.7 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

12 机械、封装和可订购信息

12.1 封装信息

下述页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。有关此数据表的基于浏览器的版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F280200DAS	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F280200DAS S320
TMS320F280200DAS.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F280200DAS S320
TMS320F280200DAS.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F280200DAS S320
TMS320F280200DAT	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F280200DAT S320
TMS320F280200DAT.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F280200DAT S320
TMS320F280200DAT.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F280200DAT S320
TMS320F280200PTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	(S320, S320 980) F280200PTT
TMS320F280200PTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F280200PTT
TMS320F280200PTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F280200PTT
TMS320F28020DAS	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28020DAS S320
TMS320F28020DAS.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28020DAS S320
TMS320F28020DAS.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28020DAS S320
TMS320F28020DAT	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F28020DAT S320
TMS320F28020DAT.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28020DAT S320
TMS320F28020DAT.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28020DAT S320
TMS320F28020PTS	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28020PTS

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F28020PTS.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28020PTS
TMS320F28020PTS.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28020PTS
TMS320F28020PTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	(S320, S320 980) F28020PTT
TMS320F28020PTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28020PTT
TMS320F28020PTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28020PTT
TMS320F28021DAS	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28021DAS S320
TMS320F28021DAS.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28021DAS S320
TMS320F28021DAS.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28021DAS S320
TMS320F28021DAT	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F28021DAT S320
TMS320F28021DAT.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28021DAT S320
TMS320F28021DAT.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28021DAT S320
TMS320F28021PTS	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28021PTS
TMS320F28021PTS.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28021PTS
TMS320F28021PTS.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28021PTS
TMS320F28021PTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	(S320, S320 980) F28021PTT
TMS320F28021PTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28021PTT
TMS320F28021PTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28021PTT

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F28022DAQ	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAQ S320
TMS320F28022DAQ.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAQ S320
TMS320F28022DAQ.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAQ S320
TMS320F28022DAQR	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAQ S320
TMS320F28022DAQR.A	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAQ S320
TMS320F28022DAQR.B	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAQ S320
TMS320F28022DAS	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAS S320
TMS320F28022DAS.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAS S320
TMS320F28022DAS.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAS S320
TMS320F28022DAT	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F28022DAT S320
TMS320F28022DAT.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAT S320
TMS320F28022DAT.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28022DAT S320
TMS320F28022PTQ	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28022PTQ
TMS320F28022PTQ.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28022PTQ
TMS320F28022PTQ.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28022PTQ
TMS320F28022PTS	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28022PTS
TMS320F28022PTS.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28022PTS

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F28022PTS.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28022PTS
TMS320F28022PTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28022PTT
TMS320F28022PTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 980 F28022PTT
TMS320F28022PTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 980 F28022PTT
TMS320F28023DAS	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28023DAS S320
TMS320F28023DAS.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28023DAS S320
TMS320F28023DAS.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28023DAS S320
TMS320F28023DAT	Active	Production	TSSOP (DA) | 38	40 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F28023DAT S320
TMS320F28023DAT.A	Active	Production	TSSOP (DA) | 38	40 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28023DAT S320
TMS320F28023DAT.B	Active	Production	TSSOP (DA) | 38	40 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28023DAT S320
TMS320F28023PTQ	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTQ
TMS320F28023PTQ.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTQ
TMS320F28023PTQ.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTQ
TMS320F28023PTS	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTS
TMS320F28023PTS.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTS
TMS320F28023PTS.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTS
TMS320F28023PTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	(S320, S320 980) F28023PTT

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F28023PTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTT
TMS320F28023PTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28023PTT
TMS320F28026DAS	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28026DAS S320
TMS320F28026DAS.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28026DAS S320
TMS320F28026DAS.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28026DAS S320
TMS320F28026DAT	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F28026DAT S320
TMS320F28026DAT.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28026DAT S320
TMS320F28026DAT.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28026DAT S320
TMS320F28026FPTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28026FPTT
TMS320F28026FPTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28026FPTT
TMS320F28026FPTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28026FPTT
TMS320F28026PTQ	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTQ
TMS320F28026PTQ.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTQ
TMS320F28026PTQ.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTQ
TMS320F28026PTS	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTS
TMS320F28026PTS.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTS
TMS320F28026PTS.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTS

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F28026PTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	(S320, S320 980) F28026PTT
TMS320F28026PTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTT
TMS320F28026PTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28026PTT
TMS320F28027DAS	Active	Production	TSSOP (DA) | 38	40 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAS S320
TMS320F28027DAS.A	Active	Production	TSSOP (DA) | 38	40 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAS S320
TMS320F28027DAS.B	Active	Production	TSSOP (DA) | 38	40 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAS S320
TMS320F28027DASR	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAS S320
TMS320F28027DASR.A	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAS S320
TMS320F28027DASR.B	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAS S320
TMS320F28027DAT	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F28027DAT S320
TMS320F28027DAT.A	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAT S320
TMS320F28027DAT.B	Active	Production	TSSOP (DA) | 38	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAT S320
TMS320F28027DATR	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	F28027DAT S320
TMS320F28027DATR.A	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAT S320
TMS320F28027DATR.B	Active	Production	TSSOP (DA) | 38	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	F28027DAT S320
TMS320F28027FPTQ	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027FPTQ
TMS320F28027FPTQ.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027FPTQ

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F28027FPTQ.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027FPTQ
TMS320F28027FPTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28027FPTT
TMS320F28027FPTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28027FPTT
TMS320F28027FPTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28027FPTT
TMS320F28027FPTTR	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28027FPTT
TMS320F28027FPTTR.A	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28027FPTT
TMS320F28027FPTTR.B	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 980 F28027FPTT
TMS320F28027PTQ	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTQ
TMS320F28027PTQ.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTQ
TMS320F28027PTQ.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTQ
TMS320F28027PTQR	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTQ
TMS320F28027PTQR.A	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTQ
TMS320F28027PTQR.B	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTQ
TMS320F28027PTR	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	S320 F28027PTT
TMS320F28027PTR.A	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTT
TMS320F28027PTR.B	Active	Production	LQFP (PT) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTT
TMS320F28027PTS	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTS

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMS320F28027PTS.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTS
TMS320F28027PTS.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTS
TMS320F28027PTSG4	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTS
TMS320F28027PTSG4.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTS
TMS320F28027PTSG4.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (10+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTS
TMS320F28027PTT	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	(S320, S320 980) F28027PTT
TMS320F28027PTT.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTT
TMS320F28027PTT.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	(S320, S320 980) F28027PTT
TMS320F28027PTTG4	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTT
TMS320F28027PTTG4.A	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTT
TMS320F28027PTTG4.B	Active	Production	LQFP (PT) | 48	250 | JEDEC TRAY (5+1)	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	S320 F28027PTT

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TMS320F28022, TMS320F28022-Q1, TMS320F28023, TMS320F28023-Q1, TMS320F28026, TMS320F28026-Q1, TMS320F28027, TMS320F28027-Q1, TMS320F28027F, TMS320F28027F-Q1 :

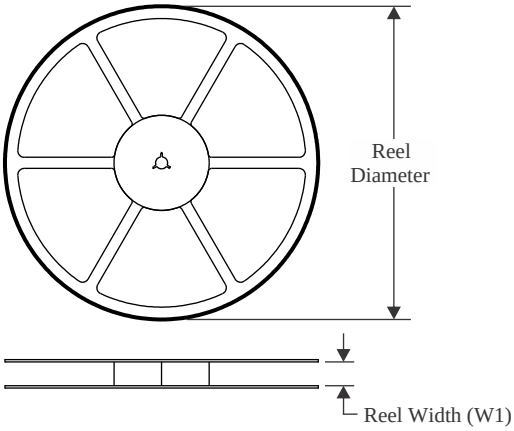
- Catalog : TMS320F28022, TMS320F28023, TMS320F28026, TMS320F28027, TMS320F28027F
- Automotive : TMS320F28022-Q1, TMS320F28023-Q1, TMS320F28026-Q1, TMS320F28027-Q1, TMS320F28027F-Q1

NOTE: Qualified Version Definitions:

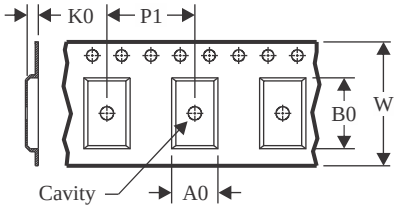
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

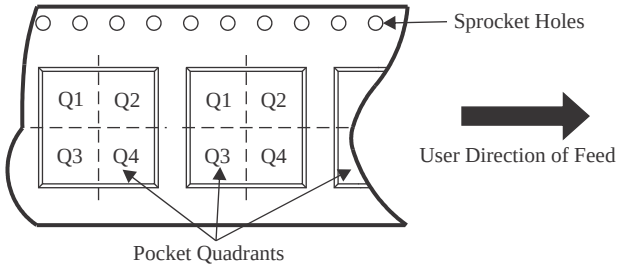


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

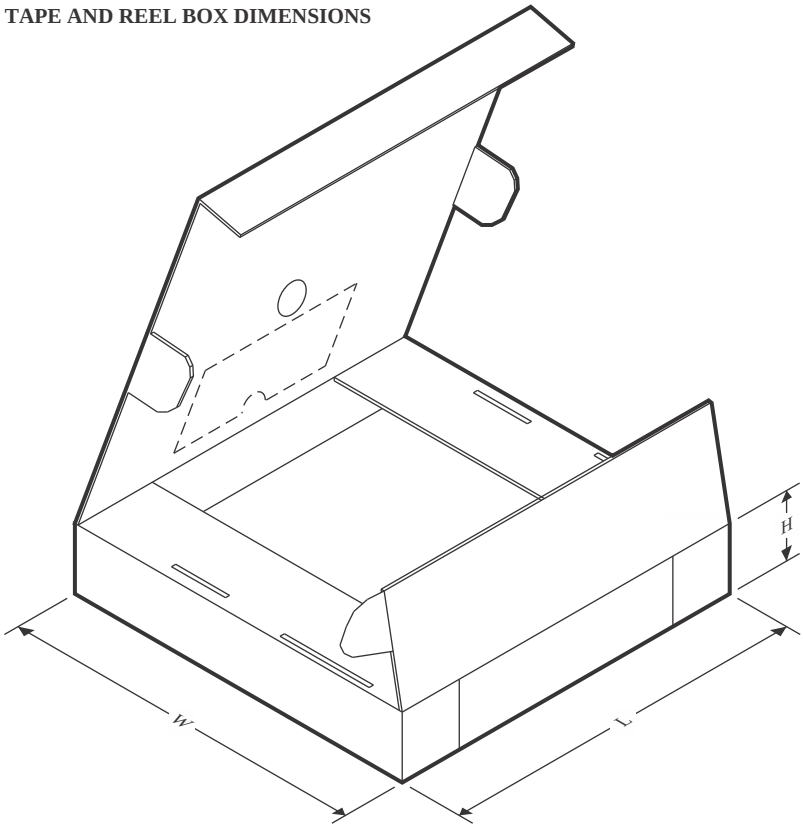
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMS320F28022DAQR	TSSOP	DA	38	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
TMS320F28027DASR	TSSOP	DA	38	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
TMS320F28027DATR	TSSOP	DA	38	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
TMS320F28027PTR	LQFP	PT	48	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS

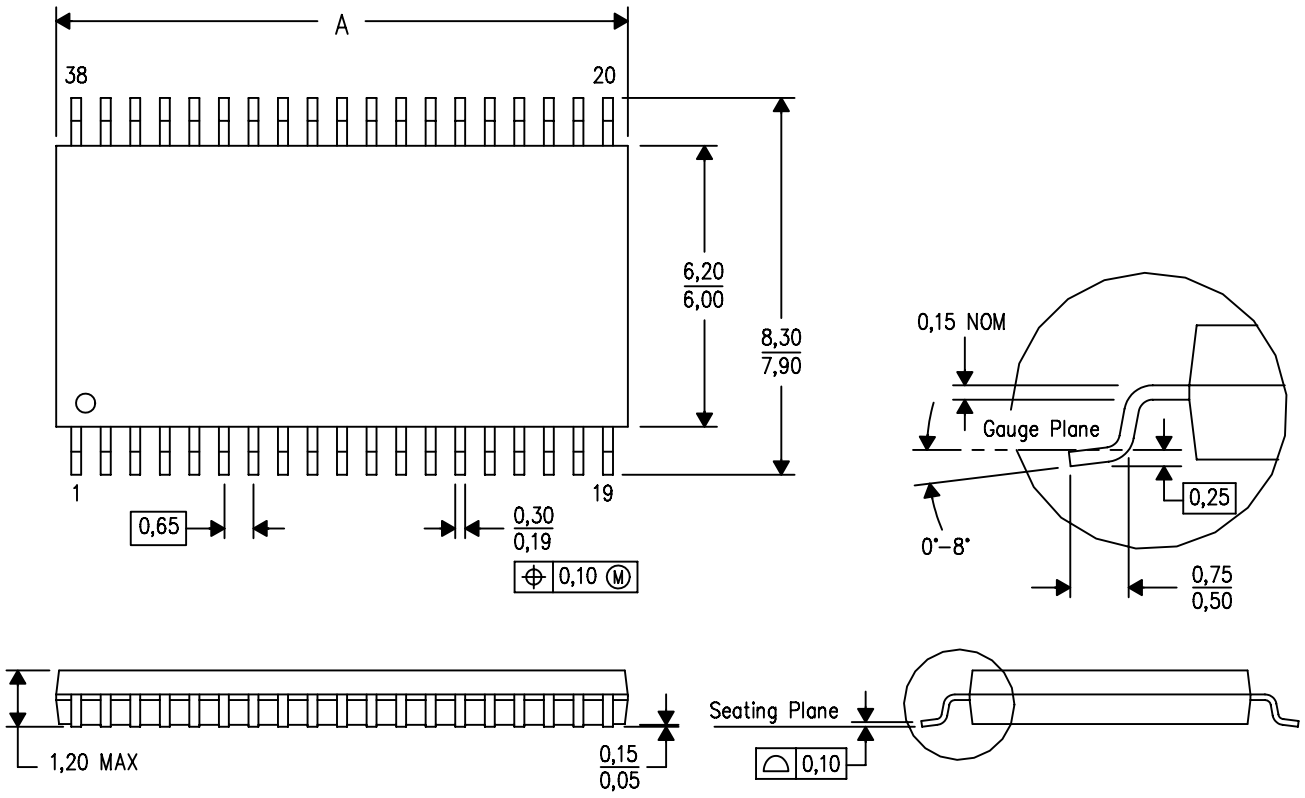


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMS320F28022DAQR	TSSOP	DA	38	2000	350.0	350.0	43.0
TMS320F28027DASR	TSSOP	DA	38	2000	350.0	350.0	43.0
TMS320F28027DATR	TSSOP	DA	38	2000	350.0	350.0	43.0
TMS320F28027PTR	LQFP	PT	48	1000	350.0	350.0	43.0

DA (R–PDSO–G**) PLASTIC SMALL–OUTLINE PACKAGE

38 PIN SHOWN

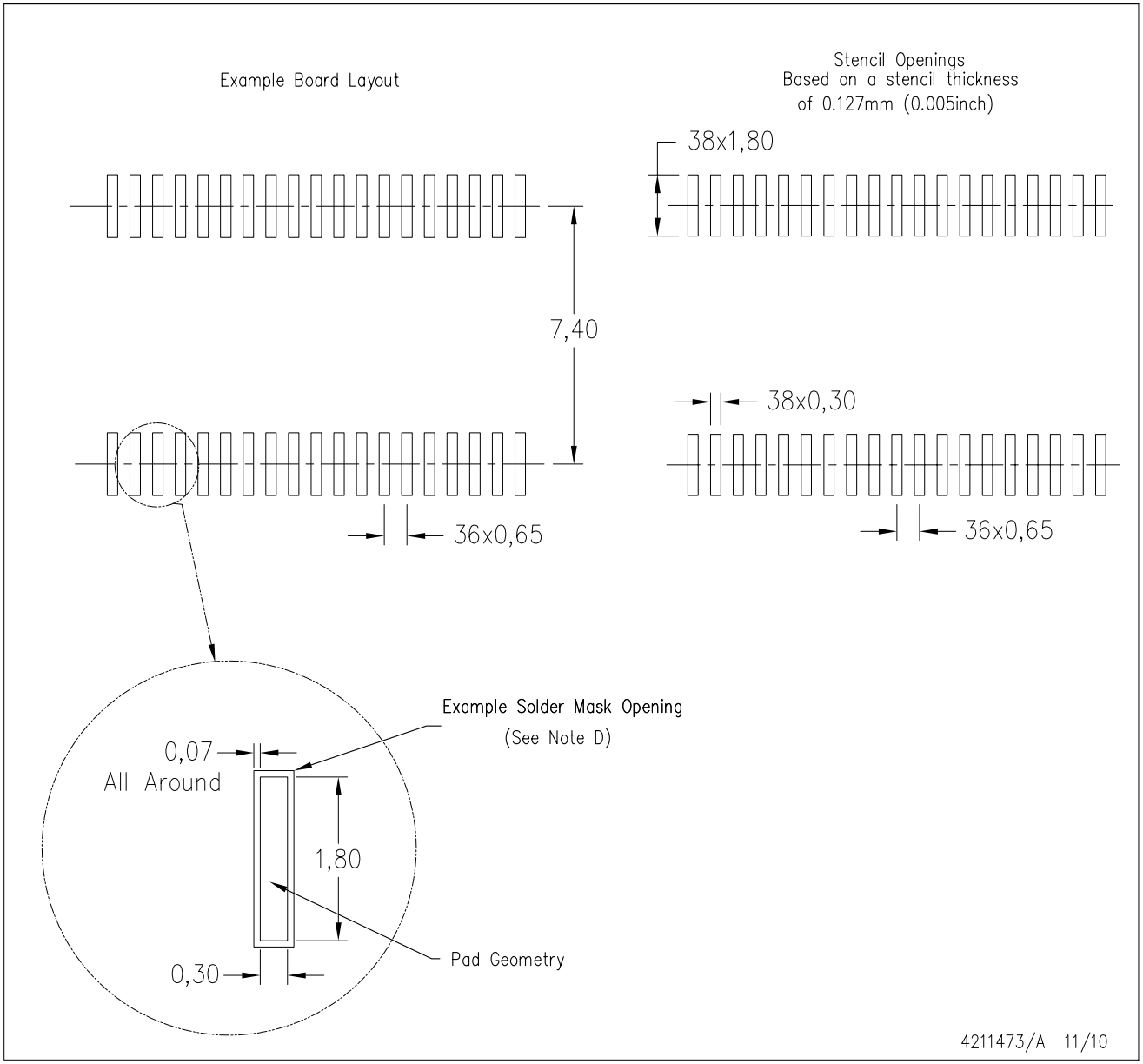


DIM \ PINS **	30	32	38
A MAX	11,10	11,10	12,60
A MIN	10,90	10,90	12,40
△D MO–153 Variation	DB–1	DC	DD–1

4040066/F 01/2009

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
△D Falls within JEDEC MO–153, except 30 pin body length.

DA (R–PDSO–G38) PLASTIC SMALL OUTLINE



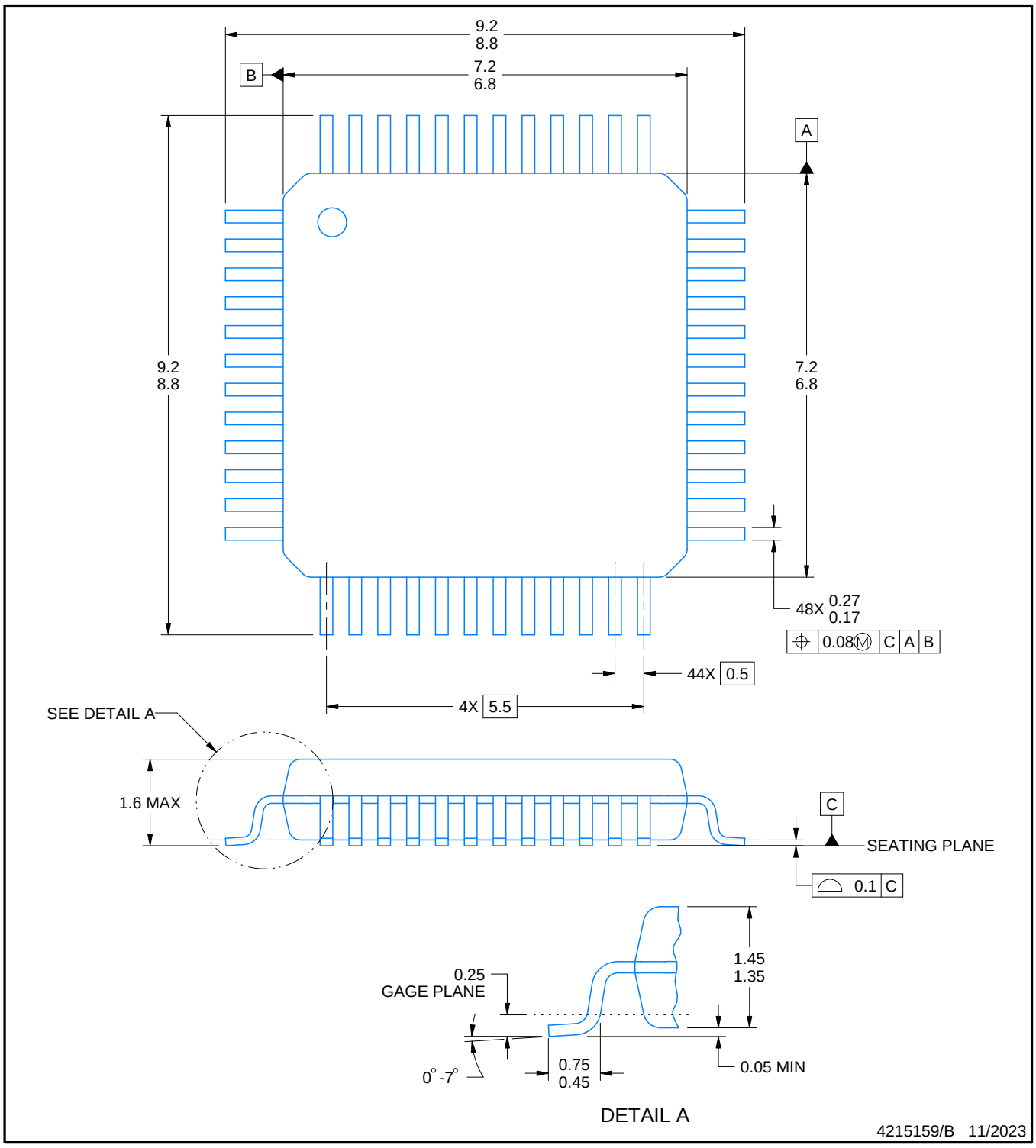
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.
D. Contact the board fabrication site for recommended soldermask tolerances.

PACKAGE OUTLINE

PT0048A

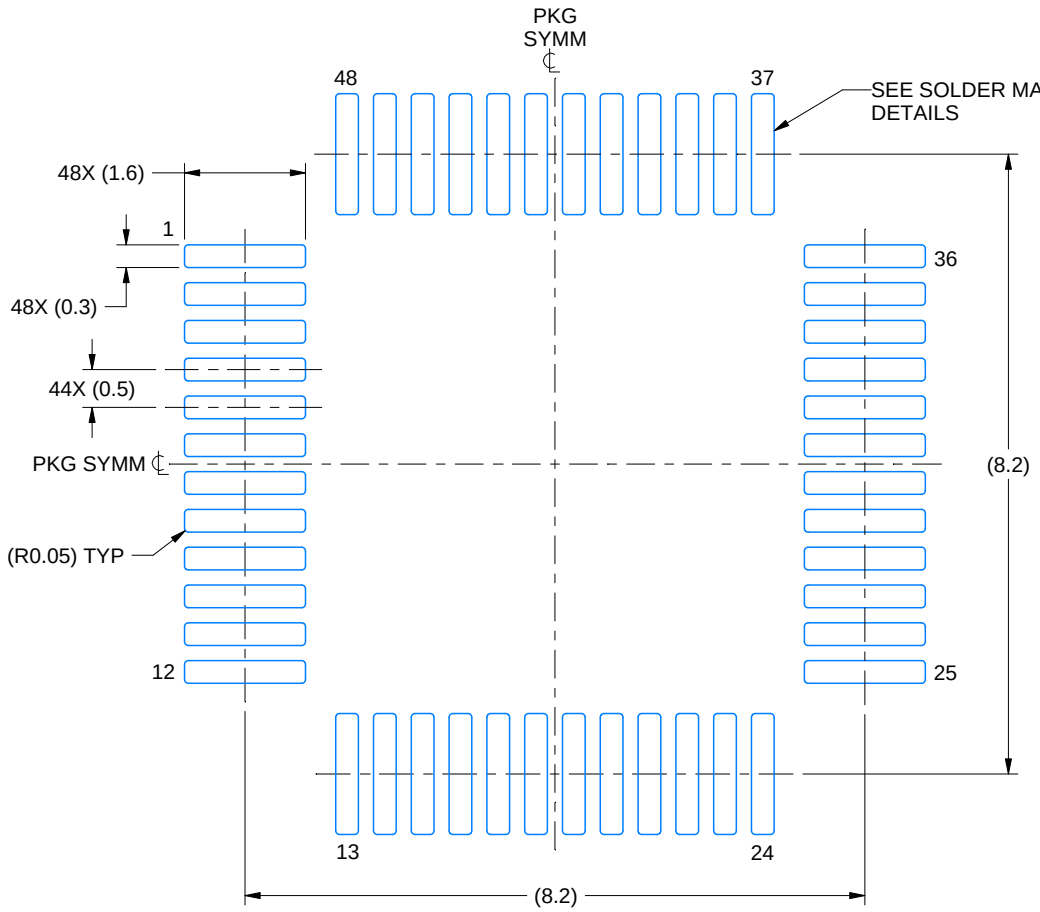
LQFP - 1.6 mm max height

LOW PROFILE QUAD FLATPACK

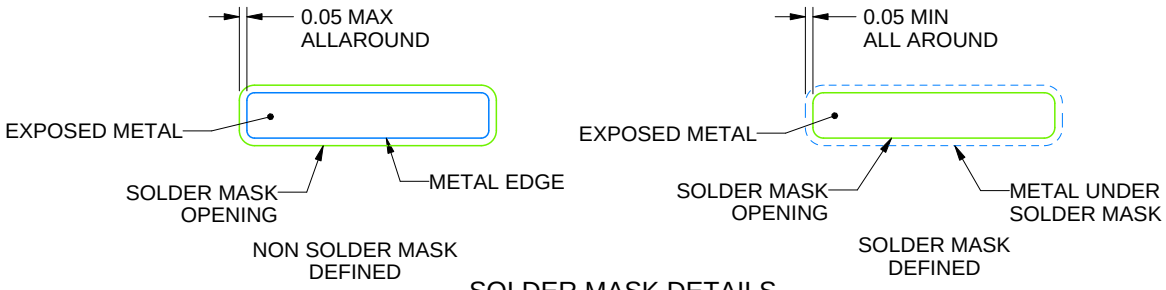


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MS-026.
4. This may also be a thermally enhanced plastic package with leads conected to the die pads.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE 10.000

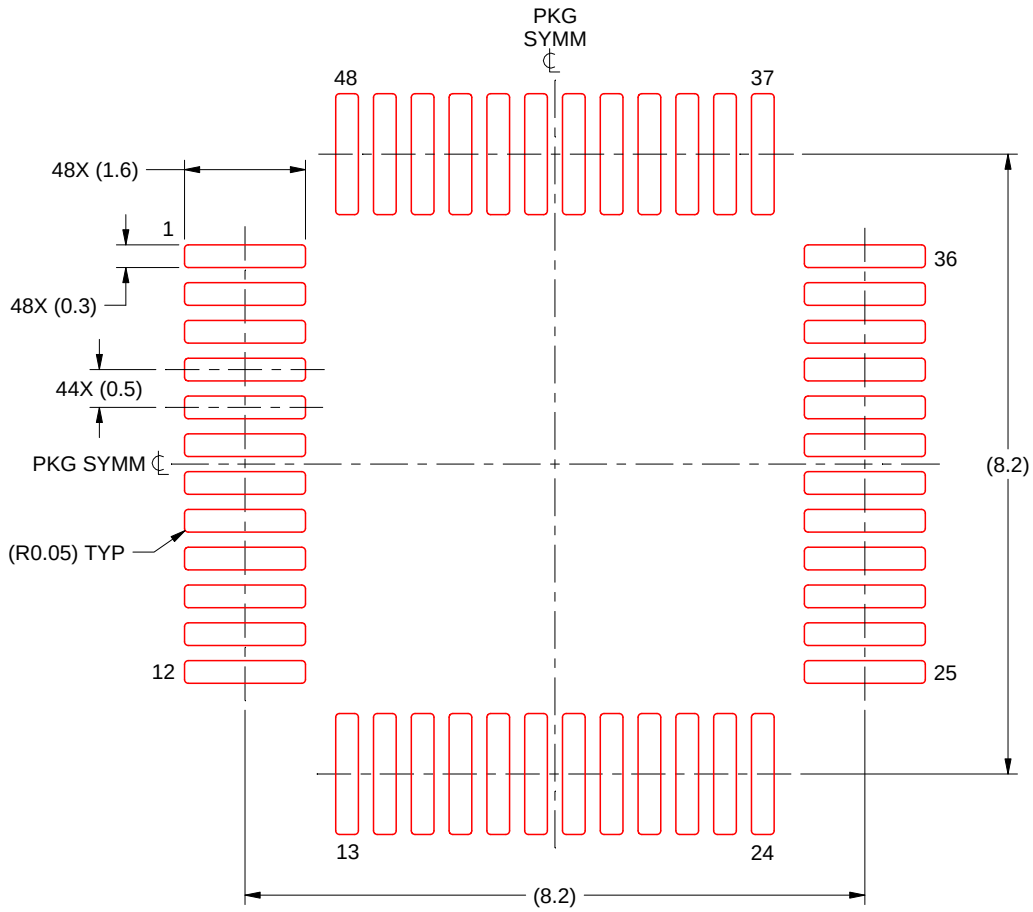


SOLDER MASK DETAILS

4215159/B 11/2023

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE: 10X

4215159/B 11/2023

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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